Intel® Server Board S5500WB

Technical Product Specification

Intel order number E53971-008

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Enterprise Platforms and Services Division

Revision History

Date	Revision Number	Modifications
03/30/2009	1.0	Initial Release.
04/29/2009	1.1	Formatting corrections.
05/20/2009	1.2	Updated heatsink installation steps. Corrected processor fault table. Added jumper location figure.
08/03/2009	1.3	Updated memory support. Corrected PCIe slot speed. Removed S4 support.
01/12/2010	1.4	Corrected USB header pin-out.
03/09/2010	1.5	Updated Power Supply communication bus requirements. Increased maximum supported memory to 128GB. Added support for 5600 series processors.
04/21/2010	1.6	Updated12V SKU board picture (Figure 1).
07/18/2010	1.7	Removed Rapid Boot Toolkit section. Updated NIC LEDs. Updated video resolution.
03/21/2010	1.8	Updated typo in board feature set.
02/16/2012	1.9	Updated typo in board feature set.

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1. Introduction

The Intel® Server Board S5500WB is a dual socket server using the Intel® Xeon® Processor 5500 series and 5600 series processors, in combination with the IOH and ICH10R to provide a balanced feature set between technology leadership and cost.

1.1 Section Outline

This document is divided into the following chapters:

- Section 1 – Introduction
- Section 2 – Server Board Overview
- Section 3 – Functional Architecture
- Section 4 – I/O Expansion Modules
- Section 5 – Platform Management Features
- Section 6 – Configuration Jumpers
- Section 7 – Connector and Header Location and Pin-out
- Section 8 – Intel® Light-Guided Diagnostics
- Section 9 – Design and Environmental Specifications
- Section 10 – Power Subsystem
- Section 11 - Regulatory and Certification Information
- Appendix A – POST Code LED Decoder
- Appendix B – Video POST Code Errors
- Glossary
- Reference Documents

1.2 Server Board Use Disclaimer

Intel Corporation server boards contain a number of high-density VLSI and power delivery components that need adequate airflow to cool. Intel ensures through its own chassis development and testing that when Intel server building blocks are used together, the fully integrated system will meet the intended thermal requirements of these components. It is the responsibility of the system integrator who chooses not to use Intel developed server building blocks to consult vendor datasheets and operating parameters to determine the amount of air flow required for their specific application and environmental conditions. Intel Corporation cannot be held responsible if components fail or the server board does not operate correctly when used outside any of their published operating or non-operating limits.

2. Server Board Overview

The Intel® Server Board S5500WB is a monolithic printed circuit board (PCB) with features designed to support the Internet Portal Data Center markets. The following table provides a high-level product feature list.

Table 1. Intel® Server Board S5500WB Feature Set

Feature	Description
Processors	Support for one or two Intel® Xeon® Processor 5500 and 5600 series processors in FC-LGA 1366 Socket B package with up to 95 W Thermal Design Power (TDP) Supports future processor compatibility guidelines ▪ 4.8 GT/s, 5.86 GT/s, and 6.4 GT/s Intel® QuickPath Interconnect (Intel® QPI) ▪ Meets EVRD11.1
Memory	Support for 800/1066/1333 MT/s ECC registered (RDIMM) or unbuffered (UDIMM) DDR3 memory. ▪ 8 DIMMs total across six memory channels (three channels per processor in a 2:1:1 configuration) ▪ VRD optimized to support QR x8 DIMMs ▪ No support for QR x4 DIMMs
Chipset	Intel® 5500 Chipset IOH Intel® 82801Jx I/O Controller Hub (ICH10R)
I/O Control	External connections: ▪ DB-15 Video connectors ▪ RJ-45 serial Port A connector ▪ RJ-45 connector for 10/100/1000 LAN ▪ One 2x USB 2.0 connectors ▪ One RJ-45 over USB for 10/100/1000 LAN Internal connections: ▪ Two USB 2x5 pin header, supporting four USB 2.0 ports ▪ One low-profile USB 2x5 pin ▪ One DH-10 Serial Port B header ▪ One 2x8 pin VGA header with presence detection to switch from rear I/O video connector ▪ Six SATA II connectors ▪ Intel® I/O Expansion Module Dual Connectors ▪ One RMM3 connector to support optional Intel® Remote Management Module 3 ▪ SATA SW RAID 5 Activation Key Connector ▪ One SSI-EEB compliant front panel header
Power Connections	**SSI SKU** ▪ One SSI-EEB compliant 24-pin main power connector (SSI only SKU) ▪ One SSI compliant 8-pin CPU power connector ▪ One SSI compliant 5-pin power control Connector (SSI only SKU) **12-V Only SKU** ▪ One 8-pin power connector ▪ One 6-pin Aux power connector for 3.3 V and 5 V ▪ One 7-pin power control connector

Feature	Description
System Fan Support	Two 8-pin fan headers for double rotor memory fans and six 4-pin fan headers supporting two processor zones and two memory zones in a redundant fashion
Add-in Adapter Support	One riser slot supporting both full-height and low-profile 1U and 2U MD2 PCI Express* x16 riser cards PCI gen2 Express* x8 w/ x16 connector. One riser slot supporting PCI Express* x8 riser cards PCI gen2 Express* x4 w/ x8 connector. Two Intel® I/O Expansion Module card connectors supporting double- and single-wide I/O modules.
Video	Onboard ServerEngines* LLC Pilot II Controller ▪ Matrox* G200 2D Video Graphics controller ▪ Uses 8 MB of the BMC 32 MB DDR2 Memory
Hard Drive	Support for six ICH10R SATA II ports Optional support for SW RAID 5 with activation key
LAN	Two 10/100/1000 ports provided by Intel® 82576 PHYs with Intel® I/O Acceleration Technology 2 support
Server Management	Onboard ServerEngines* LLC Pilot II Controller. Integrated Baseboard Management Controller (Integrated BMC), IPMI 2.0 compliant **Basic** ▪ BMC Controller: ARM 926E-S microcontroller ▪ Super IO: Serial Port logic, legacy interfaces, LPC interface, Port80 ▪ Hardware Monitoring: Fan speed control and voltage monitoring **Advanced** ▪ Video and USB compression and redirection ▪ NC-SI port, a high-speed sideband management interface ▪ Integrated Super I/O on LPC interface

2.1 Intel® Server Board S5500WB Server Board

The Intel® Server Board S5500WB has two board SKUs, such as SSI-compliant and 12-V-only-SKU. The board layouts of the SKUs are shown.

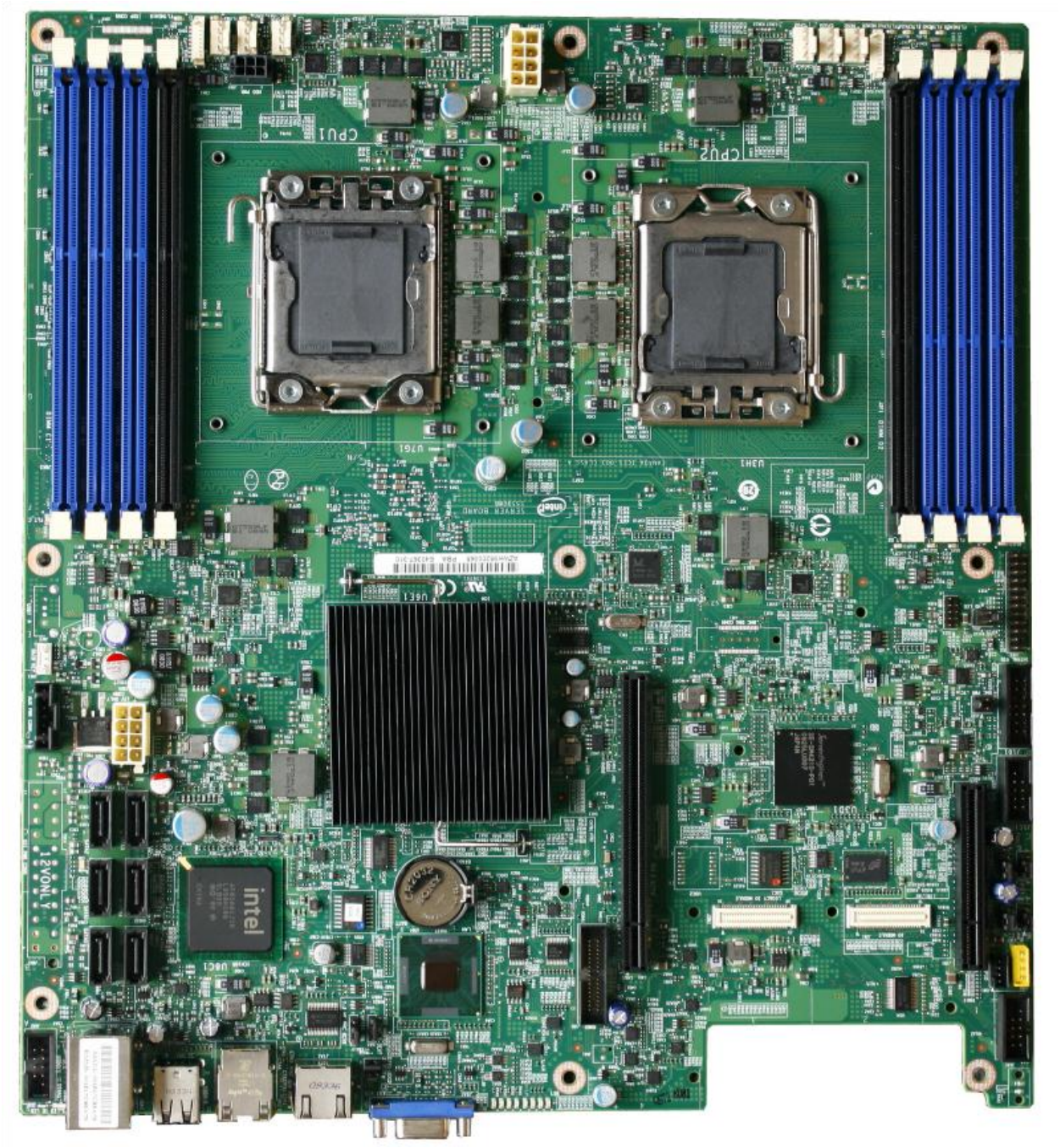


Figure 1. Intel® Server Board S5500WB 12V

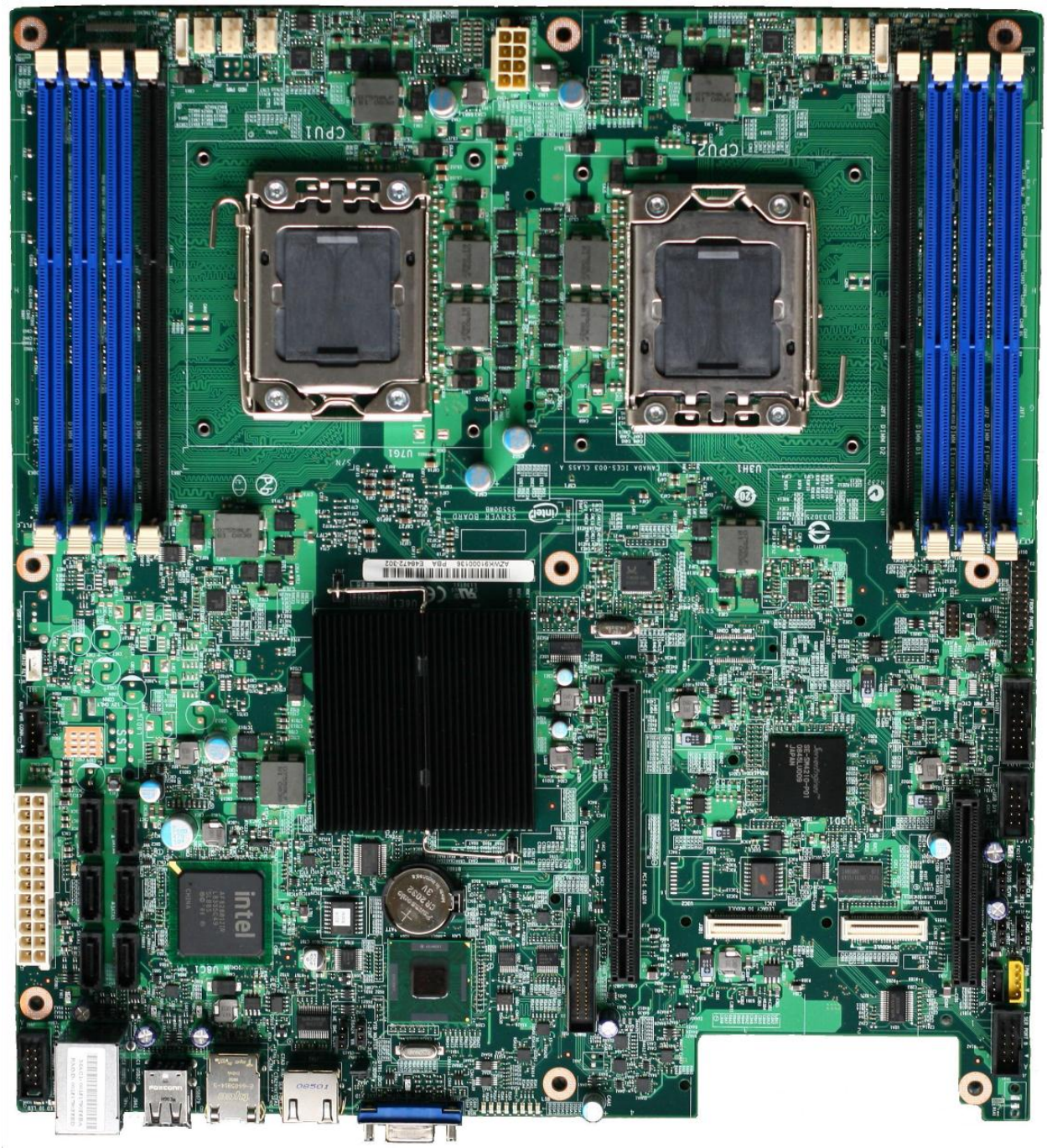


Figure 2. Intel Server Board S5500WB SSI

2.2 Server Board Connector and Component Layout

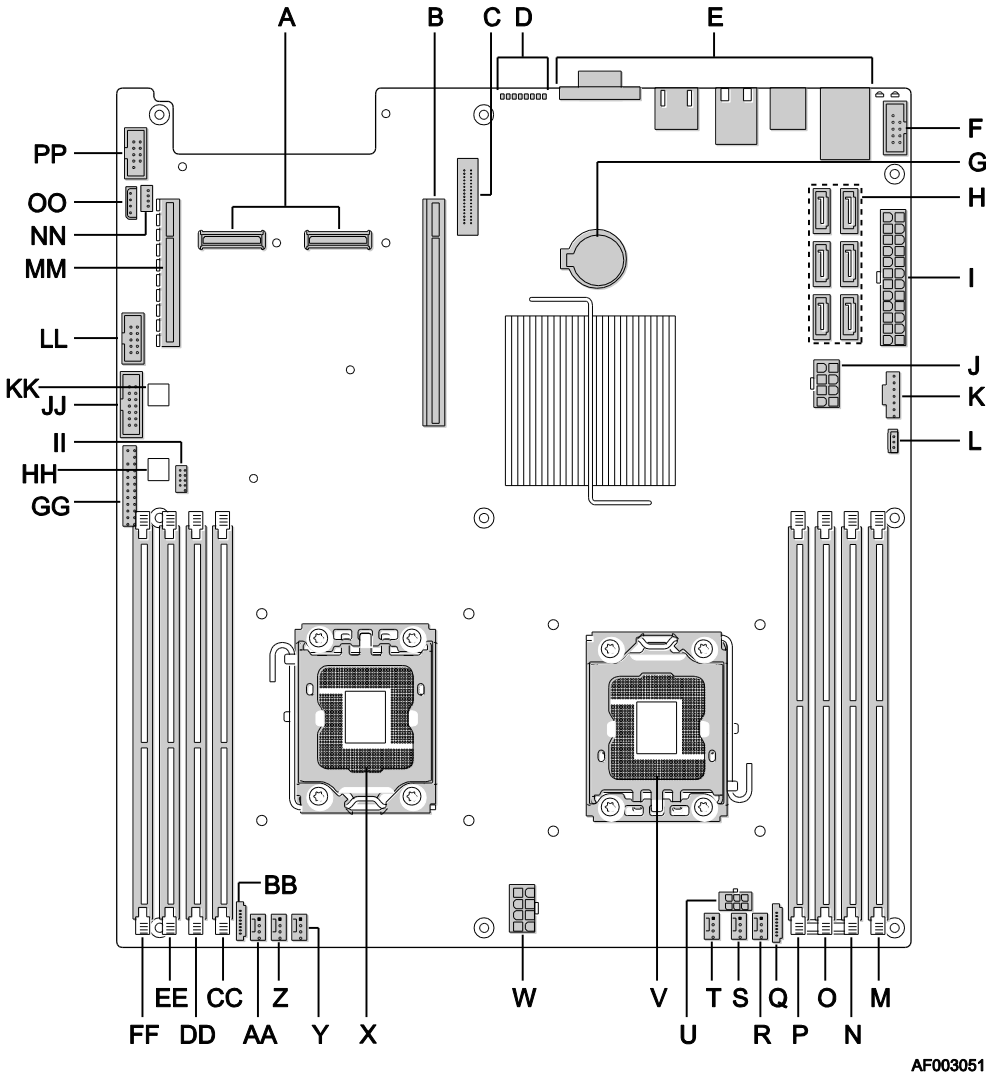


Figure 3. Intel® Server Board S5500WB Components (both SKUs are shown)

Table 2. Intel® Server Board S5500WB System Interconnects

	Description		Description
A	Dual Intel® I/O Expansion Module Connectors	V	Processor Socket 1
B	PCI Express x16 Gen2	W	8 Pin CPU Connector
C	Remote Management Module 3	X	Processor Socket 2
D	POST Code LEDs	Y	4-pin Fan Connector (CPU2)
E	External I/O	Z	4-pin Fan Connector (CPU2A)
F	USB Connector	AA	4-pin Fan Connector (MEM2)
G	Battery	BB	8-pin Fan Connector (MEM2R)
H	SATA Connectors	CC	DIMM Slot D2
I	24 Pin Connector (SSI only)	DD	DIMM Slot D1
J	8 Pin Connector (12V only)	EE	DIMM Slot E1
K	Aux Power (5-pin or 7-pin)	FF	DIMM Slot F1
L	RAID Key	GG	Front Panel Connector
M	DIMM Slot C1	HH	HDD LED Header
N	DIMM Slot B1	II	Low-Profile USB Connector
O	DIMM Slot A1	JJ	Internal VGA Connector
P	DIMM Slot A2	KK	BMC Power Cycle Header (12V Only)
Q	8-pin Fan Connector (MEM1R)	LL	USB Connector
R	4-pin Fan Connector (MEM1)	MM	Slot 1 PCI Express x8 Gen2
S	4-pin Fan Connector (CPU1A)	NN	SGPIO Connector
T	4-pin Fan Connector (CPU1)	OO	IMPB Connector
U	HDD Power Connector (12V only)	PP	Serial Port B

2.2.1 Board Rear Connector Placement

The Intel® Server Board S5500WB has the following board rear connector placement:

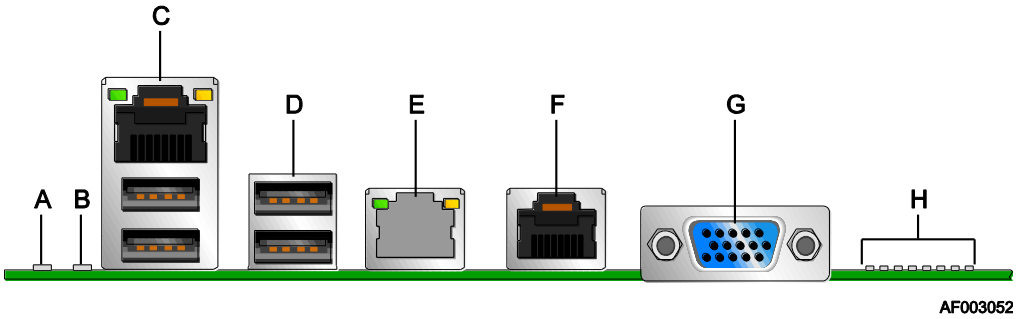


Figure 4. Rear Panel Connector Placement:

	Description		Description
A	ID LED	E	RJ-45 GbE LAN connector
B	Status LED	F	RJ-45 Serial port connector
C	RJ-45 GbE/Dual USB connector	G	DB15 Video
D	Dual USB connector	H	Diagnostic LEDs

2.2.2 Server Board Mechanical Drawings

The following figures are mechanical drawings for the Intel® Server Board S5500WB.

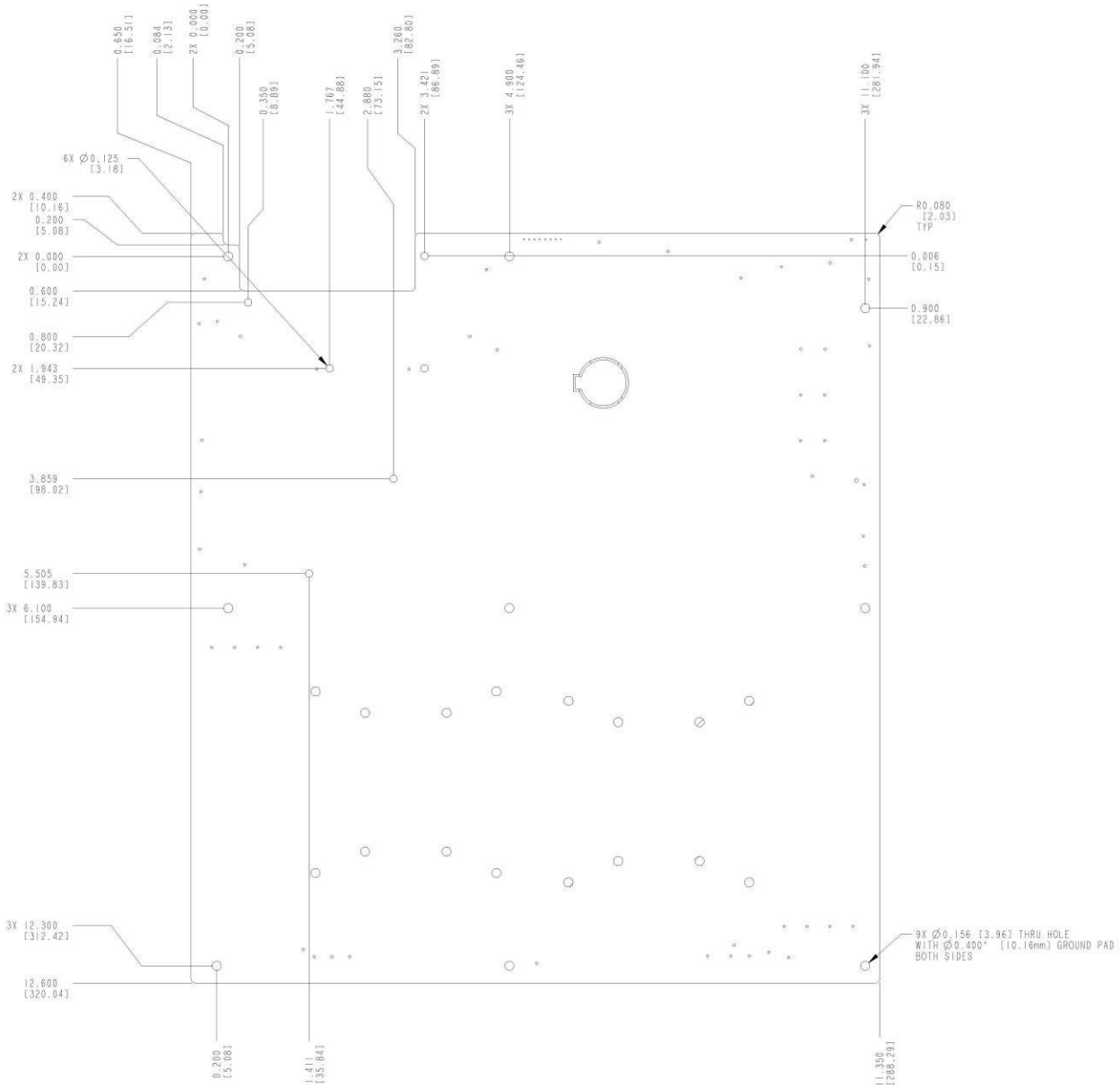


Figure 5. Baseboard and Mounting holes

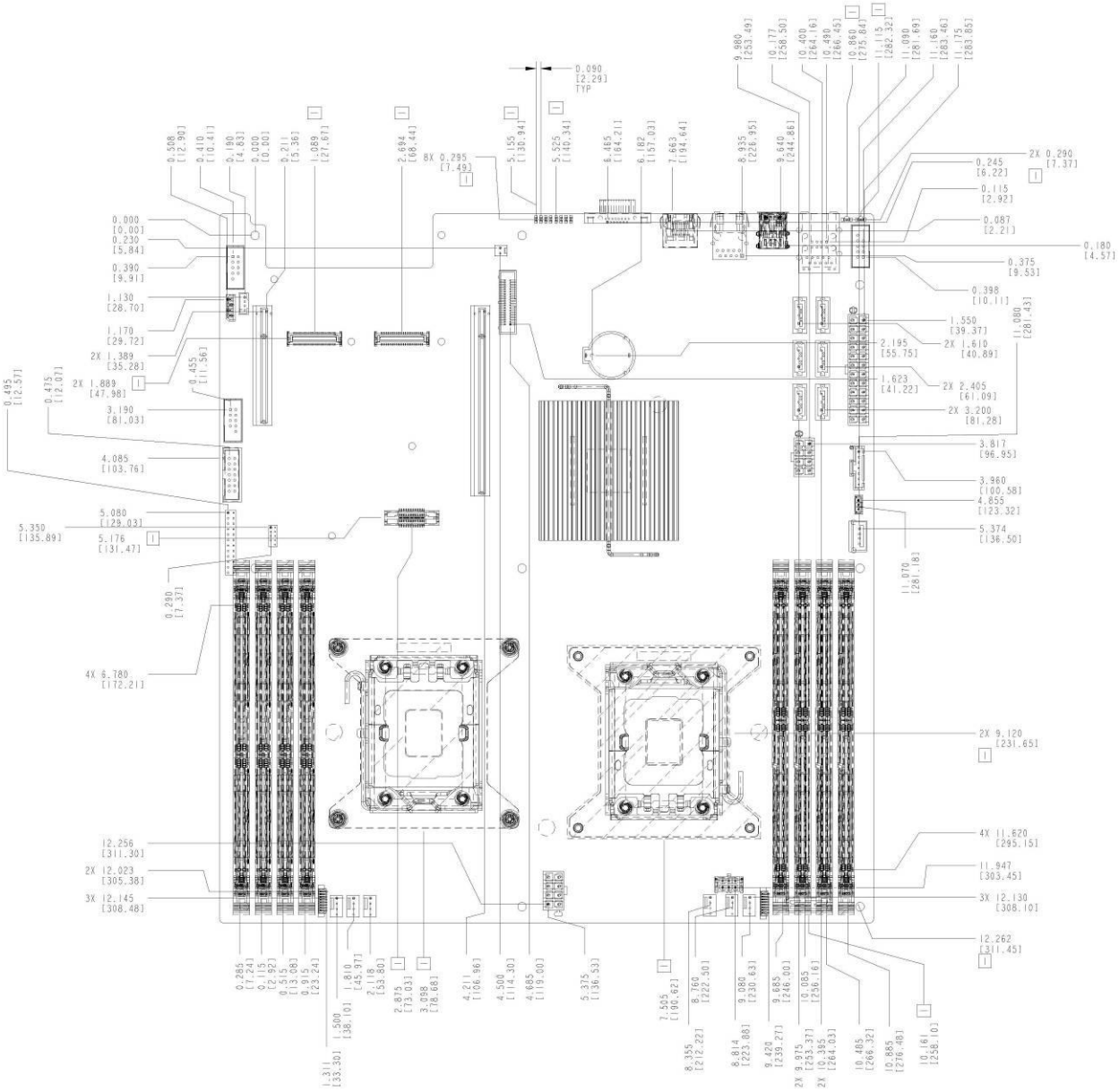


Figure 6. Connector Locations

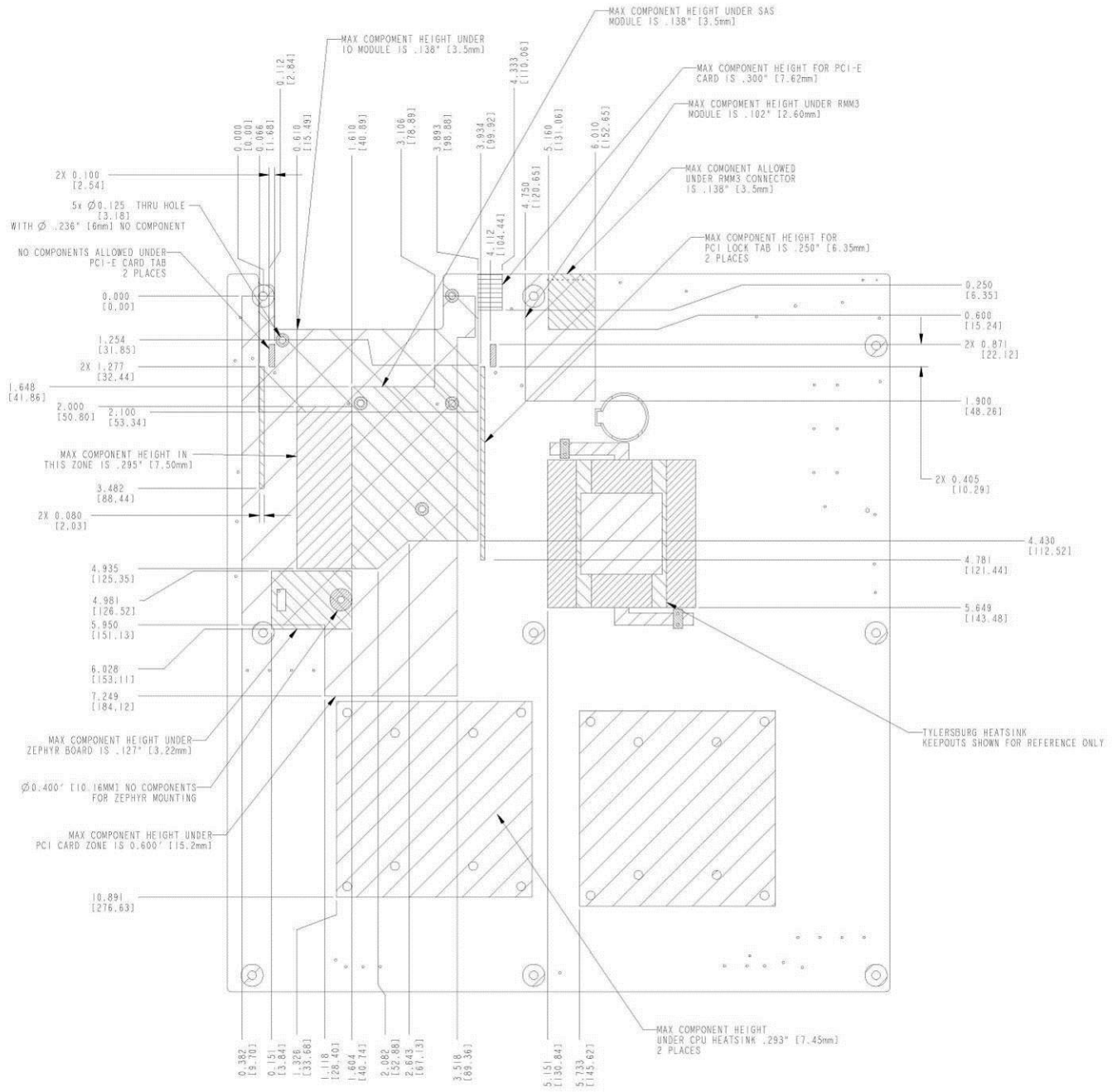


Figure 7. Primary Side Height Restrictions

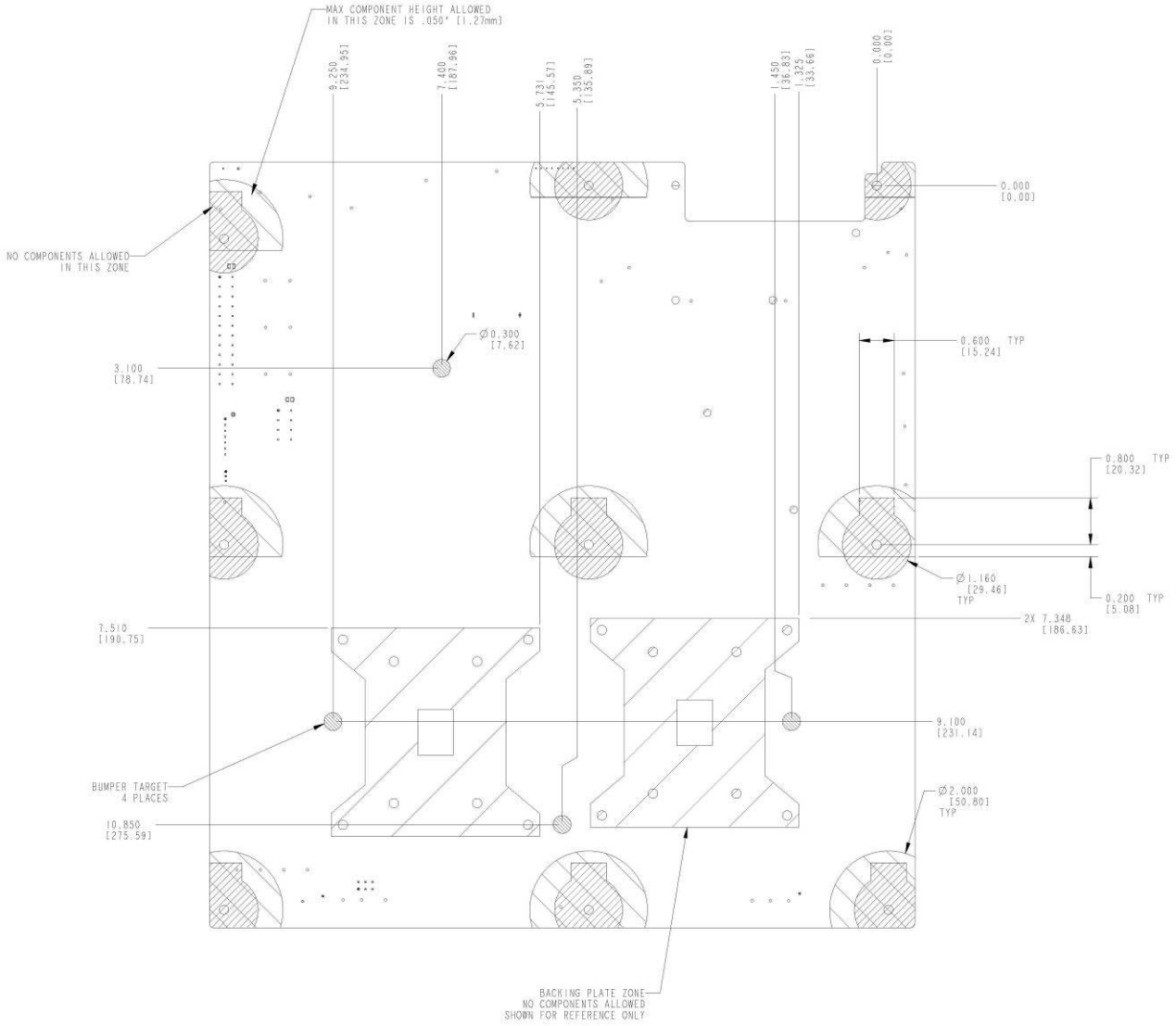


Figure 8. Secondary Side Height Restrictions

3. Functional Architecture

The Intel® Server Board S5500WB is a purpose build, power-optimized server used in a 1U rack. Memory and processor socket placement is made to minimize the amount of fan power required to cool these components. Voltage Regulators (VRDs) are optimized for a particular range of memory and CPU power that suits the target Internet Portal Datacenter (IPDC) segment of the market. The VRDs are also designed to be highly power-efficient, balancing the needs of being small in size and also cost-effective. There are two SKUs: a 12-V only SKU and an SSI-compliant SKU.

3.1 High Level Product Features

Table 3. Intel® Server Board S5500WB Features

Board	S5500WB 12V	S5500WB SSI
Form Factor	EATX 12” x 13”	EATX 12” x 13”
CPU Socket	B	B
Chipset	Intel® 5500 Chipset IOH Intel® 82801Jx I/O Controller Hub (ICH10R)	Intel® 5500 Chipset IOH Intel® 82801Jx I/O Controller Hub (ICH10R)
Memory	8 RDIMMs or 8 UDIMMs DDR3	8 RDIMMs or 8 UDIMMs DDR3
Slots	1 PCI Express* x8 w/ x16 connector 1 PCI Express* x4 w/ x8 connector	1 PCI Express* x8 w/ x16 connector 1 PCI Express* x4 w/ x8 connector
Ethernet	Dual GbE, Intel® 82576 Gigabit Ethernet	Dual GbE, Intel® 82576 Gigabit Ethernet
Storage	Six SATA II ports (3Gb/s)	Six SATA II ports (3Gb/s)
SAS	One (1) 4-port SAS module on IOM connector (optional)	One (1) 4-port SAS module on IOM connector (optional)
I/O Module	Yes, single- and double-wide	Yes, single- and double-wide
SW RAID	LSI SW RAID 0,1,5,10	LSI SW RAID 0,1,5,10
Processor Support	95 W, optimized for 80 W	95 W, optimized for 80 W
Video	Integrated in BMC	Integrated in BMC
ISM	iBMC w/ IPMI 2.0 support	iBMC w/ IPMI 2.0 support
Chassis*	Reference	Reference
Power Supply	12 V and 5 VS/B PMBus*	12 V, 5 V, 3.3 V, 5 VSB, PMBus*

Note:

*Referenced Chassis: Chenbro RM13204 Chassis and Intel® Server System SR1690WB.

3.2 Functional Block Diagram

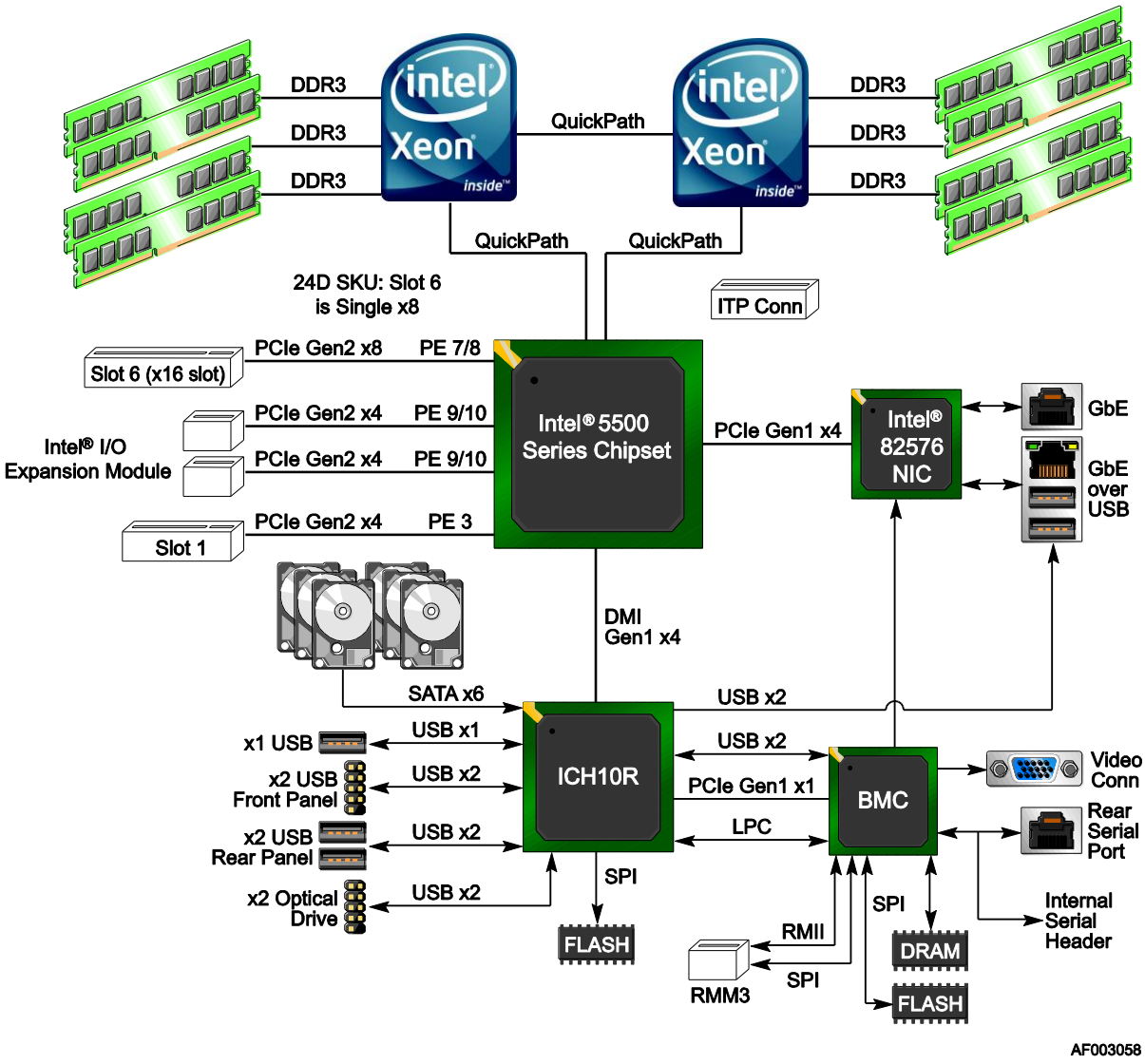


Figure 9. Intel® Server Board S5500WB Functional Block Diagram

3.3 Processor Subsystem

The Intel® 5500 series and the next generation Intel® 5600 series processors support the following key technologies:

- Intel® Integrated Memory Controller
- Point-to-point link interface based on the Intel® QuickPath Interconnect (Intel® QPI), which was formerly known as the Common System Interface (CSI).

The Intel® 5500 series processor is a multi-core processor based on the 45 nm process technology. Processor features vary by SKU and include up to two Intel® QPI point-to-point links capable of up to 6.4 GT/s, up to 8 MB of shared cache, and an integrated memory controller.

The Intel® 5600 series processor is the next generation of multi-core processors based on the 32 nm process technology. Processor features vary by SKU and include up to 6 cores and up to 12 MB of shared cache.

3.3.1 Processor Support

The Intel® Server Board S5500WB supports the following processors:

- One or two Intel® 5500 series or 5600 series processor(s) in FC-LGA 1366 socket B package with 4.8 GT/s, 5.86 GT/s, or 6.4 GT/s Intel® QPI.
- Up to 95 W Thermal Design Power (TDP).
- Supports Low Voltage (LV) processors.

3.3.2 Processor Population Rules

For optimum performance, when two processors are installed, both must be the identical revision and have the same core voltage and Intel® QPI/core speed. When only one processor is installed, it must be in the socket labeled CPU1. The other socket must be empty. You must populate processors in sequential order. Therefore, you must populate processor socket 1 (CPU1) before processor socket 2 (CPU2).

When a single processor is installed, no terminator is required in the second processor socket.

3.3.2.1 Mixed Processor Configurations

The following table describes mixed processor conditions and recommended actions for all Intel® server boards and systems that use the Intel® 5500 Chipset. The errors fall into one of the following two categories:

- **Fatal:** If the system can boot, it goes directly to the error manager, regardless of whether the Post Error Pause setup option is enabled or disabled.
- **Major:** If the Post Error Pause setup option is enabled, the system goes directly to the error manager. Otherwise, the system continues to boot and no prompt is given for the error. The error is logged to the error manager.

Table 4. Mixed Processor Configurations

Error	Severity	System Action
Processor family not identical	Fatal	The BIOS detects the error condition and responds as follows: ▪ Logs the error into the system event log (SEL). ▪ Alerts the Integrated BMC of the configuration error with an IPMI command. ▪ Does not disable the processor. ▪ Displays “0194: Processor family mismatch detected” message in the error manager. ▪ Halts the system.
Processor cache not identical	Fatal	The BIOS detects the error condition and responds as follows: ▪ Logs the error into the SEL. ▪ Alerts the Integrated BMC of the configuration error with an IPMI command. ▪ Does not disable the processor. ▪ Displays “0192: Cache size mismatch detected” message in the error manager. ▪ Halts the system.
Processor frequency (speed) not identical	Major	The BIOS detects the error condition and responds as follows: ▪ Adjusts all processor frequencies to the lowest common denominator. ▪ Continues to boot the system successfully. If the frequencies for all processors cannot be adjusted to be the same, then the BIOS: ▪ Logs the error into the SEL. ▪ Displays “0197: Processor speeds mismatched” message in the error manager. ▪ Halts the system.
Processor microcode missing	Minor	The BIOS detects the error condition and responds as follows: ▪ Logs the error into the SEL. ▪ Does not disable the processor. ▪ Displays “816x: Processor 0x unable to apply microcode update” message in the error manager. ▪ The system continues to boot in a degraded state, regardless of the setting of POST Error Pause in the Setup.
Processor Intel® QuickPath Interconnect speeds not identical	Halt	The BIOS detects the error condition and responds as follows: ▪ Adjusts all processor interconnect frequencies to lowest common denominator. ▪ Logs the error into the SEL. ▪ Alerts the Integrated BMC about the configuration error. ▪ Does not disable the processor. ▪ Displays “0195: Processor 0x Intel(R) QPI speed mismatch” message in the Error Manager. ▪ If POST Error Pause is disabled in the Setup, continues to boot in a degraded state. ▪ If POST Error Pause is enabled in the Setup, pauses the system, but can continue to boot if operator directs.

▪

3.3.3 Installing or Replacing the Processor

3.3.3.1 Installing the Processor

To install a processor, follow these instructions:

1. Turn off all peripheral devices connected to the server.
2. Turn off the server.
3. Disconnect the AC power cord from the server.
4. Remove the server's cover. See the document that came with your server chassis for instructions on removing the server's cover.
5. Locate the processor socket and raise the raise the load lever of the ILM cover completely. (see letter "A" in the figure below).

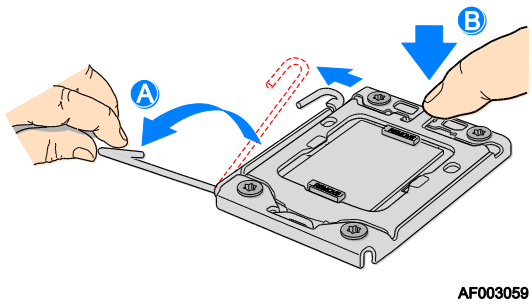


Figure 10. Lifting the load lever of ILM cover

6. Open the load plate (see letter "B" in Figure 10 and letter "C" in Figure 11).

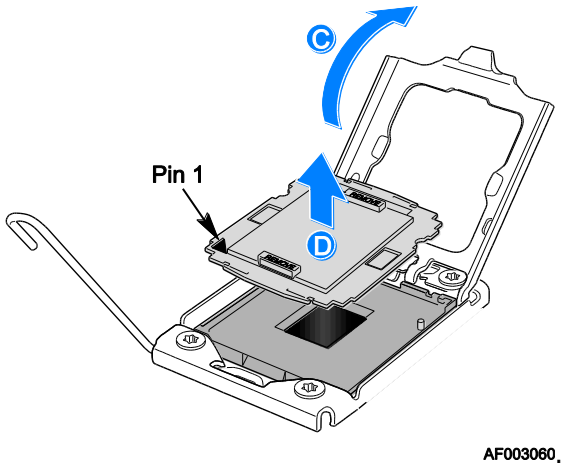


Figure 11. Removing the socket cover

7. Remove the protective socket cover. (See letter "D" in Figure 11)
8. Align the pins of the processor with the socket and insert the processor into the socket.

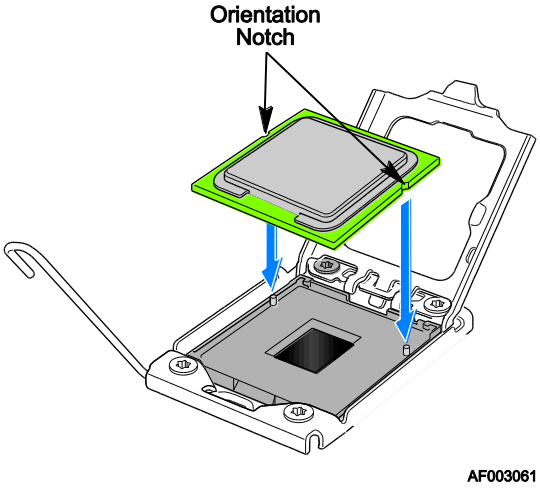


Figure 12. Installing processor

9. Lower the load plate and load lever of the ILM cover completely.

Note: Make sure the alignment triangle mark and the alignment triangle cutout align correctly.

To assist in package orientation and alignment with the socket:

A. The package Pin1 triangle and the socket Pin1 chamfer provide a visual reference for proper orientation.
B. The package substrate has orientation notches along two opposing edges of the package offset from the centerline. The socket has two corresponding orientation posts to physically prevent mis-orientation of the package. These orientation features also provide an initial rough alignment of the package to the socket.
C. The socket has alignment walls at the four corners to provide final alignment of the package.

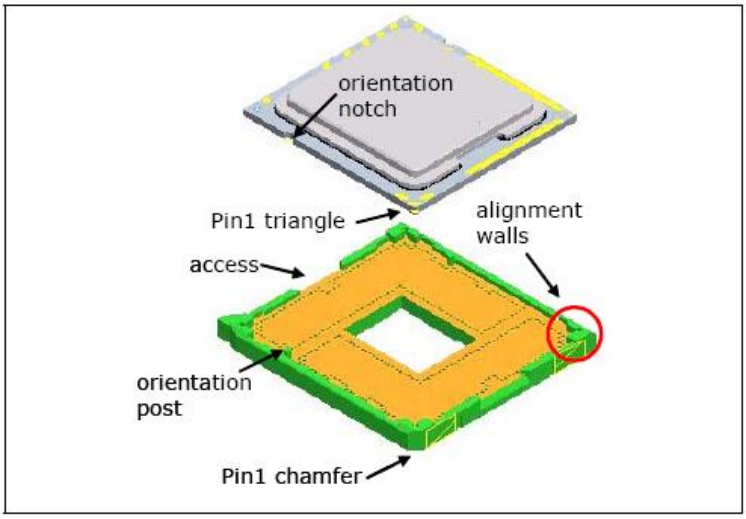


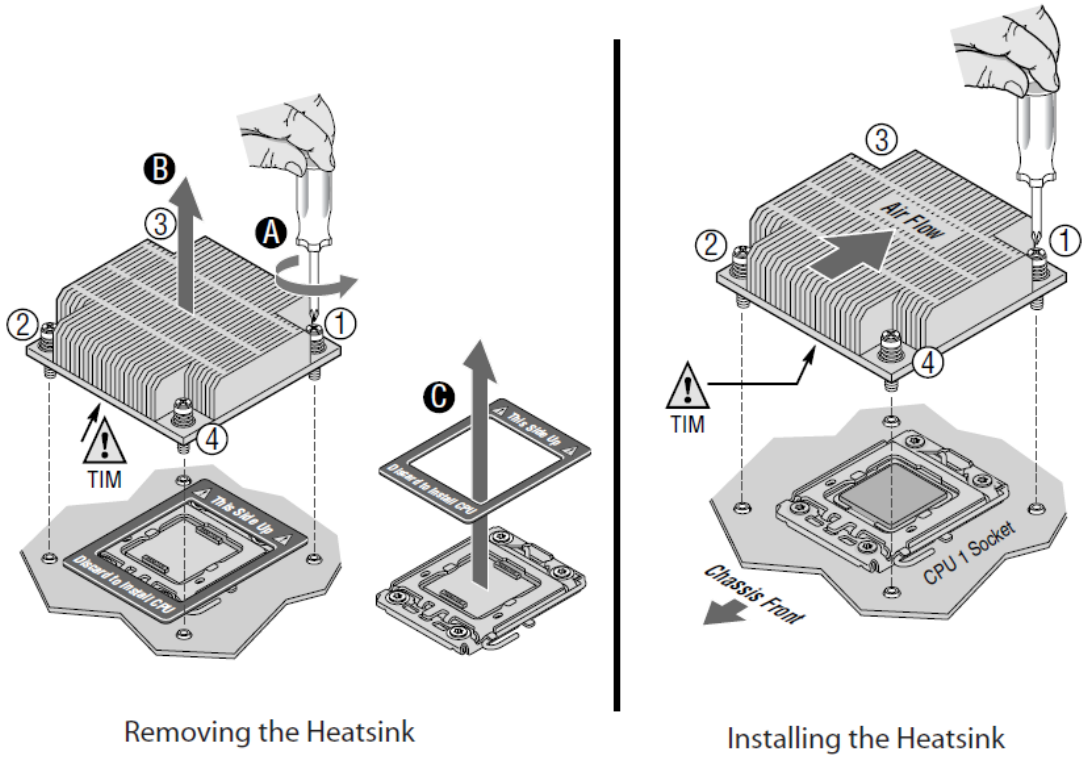
Figure 13. Package Installation/Remove Feature

3.3.3.2 Installing the Processor Heatsink(s)

CAUTION: The heatsink has Thermal Interface Material (TIM) located on the bottom of it. Use caution when you unpack the heatsink so you do not damage the TIM

To install the heatsink, follow these steps:

1. Remove the protective film on the TIM if present.
2. Orient the heatsink over the processor as shown in Figure 14. The heatsink fins must be positioned as shown to provide correct airflow through the system.
3. Set the heatsink over the processor, lining up the four captive screws with the four posts surrounding the processor.
4. Loosely screw in the captive screws on the heatsink corners in a diagonal manner according to the numbers shown in as follows:
   a) Starting with the screw at location 1, engage the screw threads by giving it **two rotations** in the clockwise direction and stop. (**IMPORTANT:** Do not fully tighten.)
   b) Proceed to the screw at location 2 and engage the screw threads by giving it two rotations and stop.
   c) Engage screws at locations 3 and 4 by giving each screw two rotations and then stop.
   d) Repeat steps 4a through 4c by giving each screw two rotations each time until all screws are lightly tightened up to a maximum of 8 inch-lbs torque.



Removing the Heatsink

Installing the Heatsink

Figure 14. Installing/Removing Heatsink

3.3.3.3 Removing the Processor Heatsink

To remove the heatsink, follow these steps:

1. Loosen the four captive screws on the heatsink corners in a diagonal manner according to the numbers shown in Figure 1 as follows:
   a) Starting with the screw at location 1, loosen it by giving it **two rotations** in the anticlockwise direction and stop. (**IMPORTANT:** Do not fully loosen.)
   b) Proceed to the screw at location 2 and loosen it by giving it two rotations and stop.
   c) Loosen screws at locations 3 and 4 by giving each screw two rotations and then stop.
   d) Repeat steps 1a through 1c by giving each screw two rotations each time until all screws are loosened.
2. Lift the heatsink from the board.

3.3.4 Intel® QuickPath Interconnect (Intel® QPI)

Intel® QPI is a cache-coherent, link-based interconnect specification for processor, chipset, and I/O bridge components. You can use it in a wide variety of desktop, mobile, and server platforms spanning IA-32 and Intel® Itanium® architectures. Intel® QPI also provides support for high-performance I/O transfer between I/O nodes. It allows connection to standard I/O buses such as PCI Express*, PCI-X*, PCI (including peer-to-peer communication support), AGP (Accelerated Graphics Port), and so forth, through the appropriate bridges.

Each Intel® QPI link consists of 20 pairs of uni-directional differential lanes for the transmitter and receiver plus a differential forwarded clock. A full-width Intel® QPI link pair consists of 84 signals (20 differential pairs in each direction) plus a forwarded differential clock in each direction. Each Intel® 5500 series and 5600 series processor supports two Intel® QPI links, one going to the second processor and one going to the Intel® 5500 chipset IOH.

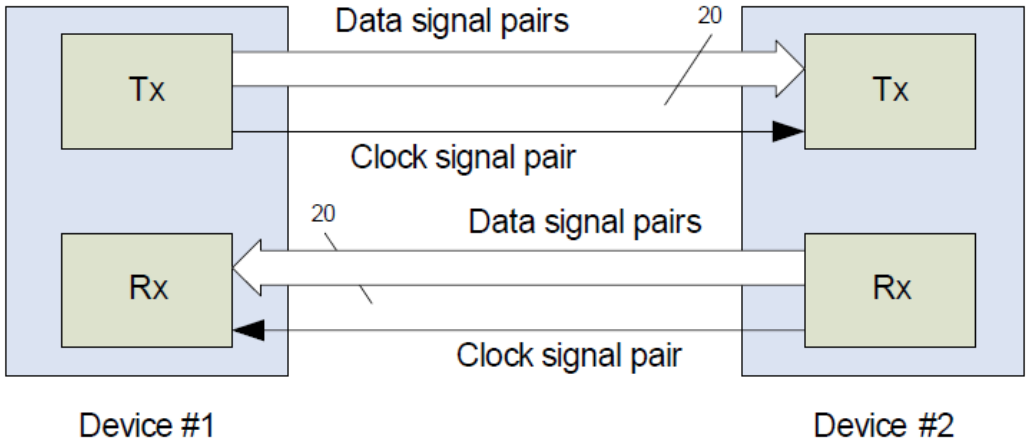


Figure 15. Intel® QPI Link

In the current implementation, Intel® QPI ports are capable of operating at transfer rates of up to 6.4 GT/s. Intel® QPI ports operate at multiple lane widths (full - 20 lanes, half - 10 lanes, and quarter - 5 lanes) independently in each direction between a pair of devices communicating via the Intel® QPI. The server boards support full-width communication only.

For more information see the *Intel® QPI Overview Rev 1.04* (Document#: 380531)

3.4 Intel® QuickPath Memory Controller

The Intel® 5500 series and 5600 series processors have an integrated memory controller on its package. Each processor produces up to three channels of DDR3 memory. The Intel® QPI Memory Controller supports DDR3 800, DDR3 1066, and DDR3 1333 memory technologies. The memory controller supports both Registered DIMMs (RDIMMs) and Unbuffered DIMMs (UDIMMs).

Mixing of RDIMMs and UDIMMs is not supported.

3.4.1 Supported Memory

The Intel® Server Board S5500WB supports six DDR3 memory channels (three per processor socket) with two DIMMs on the first channel and one DIMM on the second and third channels of each processor. Therefore, the server board supports up to 8 DIMMs with dual-processor sockets with a maximum memory capacity of 128 GB.

The server board supports DDR3 800, DDR3 1067, and DDR3 1333 memory technologies. Memory modules of mixed speed are supported by automatic selection of the highest common frequency of all memory modules.

The following configurations are not supported, validated or recommended:

- Mixing of RDIMMs and UDIMMs is not supported
- Mixing of memory type, size, speed and/or rank has not been validated and is not supported
- Mixing memory vendors has not been validated and is not recommended
- Non-ECC memory has not been validated and is not supported in a server environment

Note: Mixed memory is not tested or supported. Non-ECC memory is not tested and is not recommended for use in a server environment

The Intel® Server Board S5500WB uses a 2:1:1 memory DIMM layout. A 2:1:1 layout was chosen for its lowest power for a particular bandwidth and because it allows the maximum possible bandwidth when a 1:1:1 memory population is used.

3.4.2 Memory Subsystem Nomenclature

DIMMs are organized into physical slots on DDR3 memory channels that belong to processor sockets.

The memory channels from socket 1 are identified as Channels A, B, and C. The memory channels from socket 2 are identified as Channels D, E, and F.

The DIMM identifiers on the silkscreen on the board provide information about the channel, and, therefore the processor, to which they belong. For example, DIMM_A1 is the first slot on Channel A on processor 1; DIMM_D1 is the first DIMM socket on Channel D on processor 2.

Table 5. DIMM Nomenclature

Processor Socket 1				Processor Socket 2			
Channel A		Channel B	Channel C	Channel D		Channel E	Channel F
A1	A2	B1	C1	D1	D2	E1	F1

If the socket is not populated, the memory slots associated with a processor socket are unavailable.

You can install a processor without populating the associated memory slots provided a second processor is installed with associated memory. In this case, the memory is shared by the processors. However, the platform suffers performance degradation and latency due to the remote memory.

Sockets are self-contained and autonomous. However, all configurations in the BIOS setup such as RAS, Error Management, and so forth, are applied commonly across sockets.

3.4.3 ECC Support

If at least one non-ECC DIMM is present in the system, the system reverts to non-ECC mode. UDIMMs can be ECC or non-ECC; RDIMMs are always ECC enabled. Non-ECC DIMMs are not validated and not recommended for server use.

3.4.4 Memory Reservation for Memory-mapped Functions

A region of size 40 MB of memory below 4 GB is always reserved for mapping chipset, processor, and BIOS (flash) memory-mapped I/O regions. This region displays as a loss of memory to the operating system. In addition to this loss, the BIOS creates another reserved region for memory-mapped PCI Express* functions, including a standard 64 MB or 256 MB of standard PCI Express* Memory Mapped I/O (MMIO) configuration space. This is based on the setup selection using the MAX_BUS_NUMBER feature offered by Intel® Tylersburg IOH chipset and a variably sized MMIO region for the PCI Express* functions.

All these reserved regions are reclaimed by the operating system if Physical Address Extension (PAE) is turned on in the operating system.

3.4.5 High-Memory Reclaim

When 4 GB or more of physical memory is installed (physical memory is the memory installed as DDR3 DIMMs), the reserved memory is lost. However, the Intel® 5500 Series Chipset provides a feature called high-memory reclaim, which allows the BIOS and operating system to remap the lost physical memory into system memory above 4 GB (the system memory is the memory that can be seen by the processor).

The BIOS will always enable high-memory reclaim if it discovers installed physical memory equal to or greater than 4 GB. For the operating system, the reclaimed memory is recoverable only when it supports and enables the PAE feature in the processor. Most operating systems support this feature. For details, see the relevant operating system manuals.

3.4.6 Memory Population Rules

You should populate the memory slots of DDR3 channels furthest from the processor first. Therefore, if A1 is empty, you cannot populate/use A2.

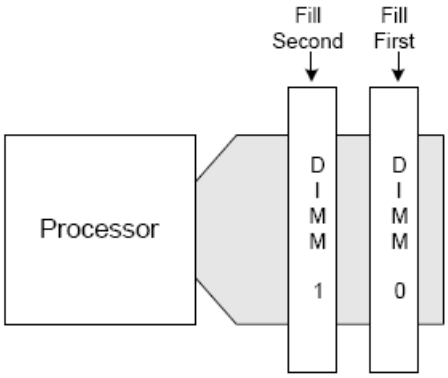


Figure 16. Memory Channel Population

3.4.7 Installing and Removing Memory

The silkscreen on the board next to CPU1 displays: DIMM_A2, DIMM_A1, DIMM_B1, DIMM_C1, and next to CPU2 display: DIMM_D2, DIMM_D1, DIMM_E1, DIMM_F1 starting from the inside of the board. DIMM_A1 is the **blue** socket closest to the CPU 1 socket. For memory channel A, the server board requires DDR3 DIMMs within a channel to be populated starting with the DIMM farthest from the processor. The DIMM farthest from the processor per channel is blue on the board.

3.4.7.1 Installing DIMMs

To install DIMMs, follow these steps:

1. Turn off the server.
2. Disconnect the AC power cord from the server.
3. Remove the server's cover and locate the DIMM sockets (see " Installing Memory").

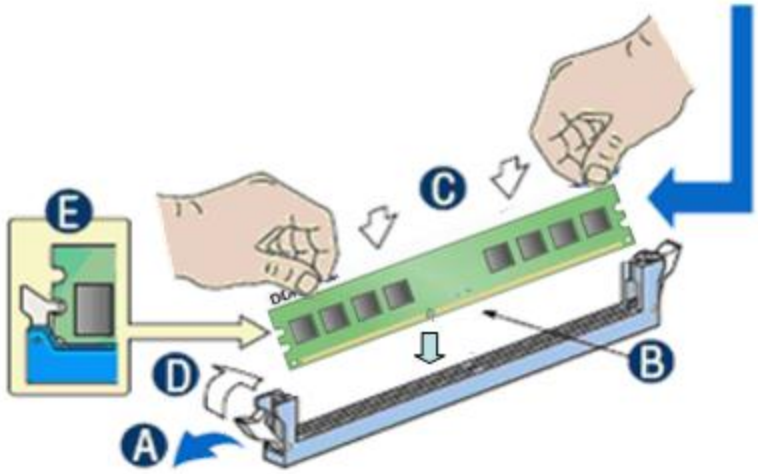


Figure 17. Installing Memory

4. Make sure the clips at either end of the DIMM socket(s) are pushed outward to the open position (see letter “A” in the figure above).
5. Holding the DIMM by the edges, remove it from its anti-static package.
6. Position the DIMM above the socket. Align the two small notches in the bottom edge of the DIMM with the keys in the socket (letter “B” in Figure 16).
7. Insert the bottom edge of the DIMM into the socket (letter “C” in Figure 16).
8. When the DIMM is inserted, push down on the top edge of the DIMM until the retaining clips snap into place (letter “D” in Figure 16). Make sure the clips are firmly in place (letter “E” in Figure 16).
9. Replace the server’s cover and reconnect the AC power cord.

3.4.7.2 Removing DIMMs

To remove a DIMM, follow these steps:

1. Turn off all peripheral devices connected to the server.
2. Turn off the server.
3. Remove the AC power cord from the server.
4. Remove the server’s cover.
5. Gently spread the retaining clips at each end of the socket. The DIMM lifts from the socket.
6. Holding the DIMM by the edges, lift it from the socket and store it in an anti-static package.
7. Reinstall and reconnect any parts you removed or disconnected to reach the DIMM sockets.
8. Replace the server’s cover and reconnect the AC power cord.

3.4.8 Channel-Independent Mode

In the Independent Channel mode, you can populate multiple channels in any order (for example, you can populate channels B and C while channel A is empty). Also, DIMMs on adjacent channels do not need to have identical parameters. Therefore, all DIMMs are enabled and used in the Independent Channel mode.

Adjacent slots on channels A and D do not need matching size and organization. However, the speed of the channel is configured to the maximum common speed of the DIMMs.

The single channel mode is established using the independent channel mode by populating DIMM slots from channel A only.

3.4.9 Memory RAS

The memory RAS offered by the Intel® 5500 series and 5600 series processors is performed at channel level (for example, during mirroring, channel B mirrors channel A). All DIMM matching requirements are on a slot-to-slot basis on adjacent channels. For example, to enable mirroring, corresponding slots on channels A and B must have DIMMS of identical parameters.

If one socket fails, the population requirements for RAS, the BIOS sets all six channels to the Independent Channel mode. One exception to this rule is when all DIMM slots from a socket are empty (for example, when only DIMM slots A1, B1, and C1 are populated, mirroring is possible on the platform).

3.4.9.1 Memory Population for Channel Mirroring Mode

The mirrored configuration is a redundant image of the memory, and can continue to operate despite the presence of sporadic uncorrectable errors.

Channel mirroring is a RAS feature in which two identical images of memory data are maintained, thus providing maximum redundancy. On the Intel® 5500 series based Intel server boards, mirroring is achieved across channels. Active channels hold the primary image and the other channels hold the secondary image of the system memory. The integrated memory controller in the processor alternates between both channels for read transactions. Under normal circumstances, write transactions are issued to both channels.

Mirroring is only supported between Channels A & B and Channels D & E. The presence of a DIMM on Channel C or F causes the BIOS to disable Mirroring and revert to the Independent Channel mode.

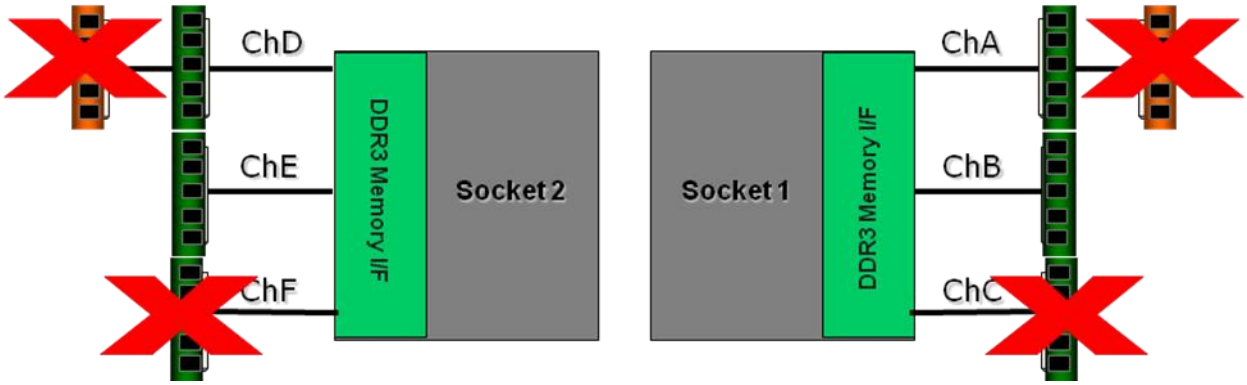


Figure 18. Mirroring Memory Configuration

3.4.10 Memory Error LED

Each DIMM is allocated an LED that, when lit, indicates a memory DIMM failure. It is the function of the BIOS to identify bad DIMMs during the boot process. The BIOS sends a message to the BMC to indicate which DIMM LED needs turn on.

3.5 Intel® 5500 Chipset IOH

The Intel® 5500 Chipset component is an I/O Hub (IOH). The Intel® 5500 Chipset provides a connection point between various I/O components and Intel processors using the Intel® QPI interface.

The Intel® 5500 Chipset IOH is capable of interfacing with up to 24 PCI Express* lanes, which can be configured in various combinations of x4, x8, x16 and limited x2 and x1 devices.

The Intel® 5500 Chipset IOH is responsible for providing a path to the legacy bridge. In addition, the Intel® 5500 Chipset supports a x4 DMI (Direct Media Interface) link interface for the legacy bridge and interfaces with other devices through SMBus, Controller Link, and RMII (Reduced Media Independent Interface) manageability interfaces. The Intel® 5500 Chipset supports the following features and technologies:

- Intel® QuickPath Interconnect (Intel® QPI)
- PCI Express* Gen2
- Intel® Virtualization Technology (Intel® VT) for Directed I/O 2 (Intel® VT-D2)
- Manageability Engine (ME) subsystem

3.5.1 IOH24D PCI Express*

PCI Express* Gen1 and Gen2 are dual-simplex, point-to point serial differential low-voltage interconnects. The signaling bit rate is 2.5 Gb/s one direction per lane for Gen1 and 5.0 Gb/s one direction per lane for Gen2. Each port consists of a transmitter and receiver pair. A link between the ports of two devices is a collection of lanes (x1, x2, x4, x8, x16, and so forth). All lanes within a port must transmit data using the same frequency. The following table lists the usage of the IOH24D PCI Express* bus segments.

Table 6. IOH24D PCI Express* Bus Segments

PCI Bus Segment	Width	Speed	Type	PCI I/O Card Slots
Port 0 ICH10R	x4	10 Gb/s	PCI Express* Gen1	x4 PCI Express* Gen1 throughput to the ICH10R southbridge
PE1, PE2 Intel® 5500 Chipset IOH PCI Express*	x4	10 Gb/s	PCI Express* Gen1	x4 PCI Express* Gen1 throughput to an onboard NIC.
PE3, Intel® 5500 Chipset IOH PCI Express*	X4	20 Gb/S	PCI Express* Gen2	X4 PCI Express* Gen2 throughput to slot 1.
PE7, PE8 Intel® 5500 Chipset IOH PCI Express*	x8	40 Gb/S	PCI Express* Gen2	x8 PCI Express* Gen2 throughput to the slot 6 riser .
PE9, PE10 Intel® 5500 Chipset IOH PCI Express*	x8	40 Gb/S	PCI Express* Gen2	x4 PCI Express* Gen2 throughput to each of the two Intel® I/O Expansion Module connectors.

3.5.1.1 Direct Cache Access (DCA)

The DCA mechanism is a system-level protocol in a multi-processor system to improve I/O network performance by providing higher system performance. It is designed to minimize cache misses when a demand read is executed. This is accomplished by placing the data from the I/O devices directly into the CPU cache through hints to the processor to perform a data pre-fetch and install it in its local caches. The Intel® 5500 series and 5600 series processor supports Direct Cache Access (DCA). You enable or disable DCA in the BIOS processor setup menu.

3.5.1.2 Intel® Virtualization Technology for Directed I/O (Intel® VT-d)

The Intel® Virtualization Technology is designed to support multiple software environments sharing the same hardware resources. Each software environment may consist of an operating system and applications. You can enable or disable the Intel® Virtualization Technology in the BIOS setup. The default behavior is disabled.

Note: If the setup options are changed to enable or disable the Virtualization Technology setting in the processor, the user must perform an AC power cycle for the changes to take effect.

The Intel® 5500 Chipset IOH supports DMA remapping from inbound PCI Express* memory Guest Physical Address (GPA) to Host Physical Address (HPA). PCI Express* devices are directly assigned to a virtual machine leading to a robust and efficient virtualization.

3.6 Management Engine

The Management Engine (ME) is an embedded ARC controller within the IOH. The IOH ME performs manageability functions called Intel® Server Platform Services (SPS) for the discrete Baseboard Management Controller (BMC).

The functionality provided by the SPS firmware is different from Intel® Active Management Technology (Intel® AMT or AT) provided by the ME on client platforms.

Server Platform Services are value-added platform management options that enhance the value of Intel platforms and their component ingredients (CPUs, chipsets, and I/O components). Each service is designed to function independently wherever possible, or grouped together with one or more features in flexible combinations to allow OEMs (Original Equipment Manufacturers) to differentiate platforms. The following is a high-level view of the Intel® Server Board S5500WB SPS functions.

- **Node Management Features:**
  - NPTM Policy Manager
  - Power Supply Monitoring Service
  - Inlet Temperature Monitoring Service
  - CPU Power Limiting Service

- **Provide Access to ICH10R Devices**: The ME has control of ICH10R platform instrumentation. SPS provides a mechanism for the BMC to access this instrumentation through IPMI OEM commands. Use of this capability on Intel servers is platform-/SKU-specific.
  - ICH10 temperature monitoring

- **PECI 2.0 Proxy:** SPS offers a means for a BMC without a PECI 2.0 interface to use the ME as a PECI proxy. The BMC on Intel servers already has a PECI 2.0 interface, so this SPS capability is not used.

3.7 Intel® 82801Jx I/O Controller Hub (ICH10R)

The Intel® 82801Jx I/O Controller Hub (ICH10R) provides extensive I/O support and supports the following features and specifications:

- *PCI Express* Base Specification*, Revision 1.1 support
- *ACPI Power Management Logic Support*, Revision 3.0a
- Enhanced DMA controller, interrupt controller, and timer functions
- Integrated Serial ATA host controllers with independent DMA operation on up to six ports and AHCI support
- USB host interface with support for up to 12 USB ports; six UHCI host controllers; and two EHCI high-speed USB 2.0 host controllers
- *System Management Bus (SMBus) Specification*, Version 2.0 with additional support for I^2C devices
- Low Pin Count (LPC) interface support
- Serial Peripheral Interface (SPI) support

3.7.1 Serial ATA Support

The ICH10R has an integrated Serial ATA (SATA) controller that supports independent DMA operation on six ports and data transfer rates of up to 3.0 Gb/s. The six SATA ports on the

server board are numbered SATA-1 through SATA-6. You can enable or disable the SATA ports and/or configure them by accessing the BIOS setup utility during POST.

3.7.1.1 Intel® Embedded Server RAID Technology II

The onboard storage capability of these server boards includes support for Intel® Embedded Server RAID Technology II (Intel® ESRTII), which provides three standard software RAID levels: data stripping (RAID Level 0), data mirroring (RAID Level 1), and data stripping with mirroring (RAID Level 10). For higher performance, you can use data stripping to alleviate disk bottlenecks by taking advantage of the dual independent DMA engines that each SATA port offers. Data mirroring is used for data security. If a disk fails, a mirrored copy of the failed disk is brought online. There is no loss of either PCI resources (request/grant pair) or add-in card slots.

With the addition of an optional Intel® RAID Activation Key, Intel® ESRTII is also capable of providing fault tolerant data stripping (software RAID Level 5), such that if a SATA hard drive fails, you can restore the lost data on a replacement drive from the other drives that make up the RAID 5 pack.

Intel® Embedded Server RAID Technology functionality requires the following items:

- ICH10R IO Controller Hub
- Software RAID option is selected on BIOS menu for SATA controller
- Intel® Embedded Server RAID Technology II Option ROM
- Intel® Embedded Server RAID Technology II drivers, most recent revision
- At least two SATA hard disk drives

3.7.1.2 Intel® Embedded Server RAID Technology II Option ROM

The Intel® Embedded Server RAID Technology II for SATA Option ROM provides a pre-operating system user interface for the Intel® Embedded Server RAID Technology II implementation and provides the ability to use an Intel® Embedded Server RAID Technology II volume as a boot disk as well as to detect any faults in the Intel® Embedded Server RAID Technology II volume(s).

3.7.2 USB 2.0 Support

The USB controller functionality integrated into ICH10R provides the server board with an interface for up to 12 USB 2.0 ports. All ports are high-speed, full-speed, and low-speed capable.

- Four external connectors are located on the back edge of the server board.
- Two internal 2x5 headers are provided, capable of supporting two optional USB 2.0 ports each, typically, one header supports Front panel USB and one supports an internal third party management card.
- One internal low-profile 2x5 header is provided
- One Internal Type A USB vertical connector is provided for attaching standard peripherals
- The BMC consumes 2 ports, for a total of 12 Ports

3.8 Network Interface Controller (NIC)

Network interface support is provided from the onboard Intel® 82576 NIC, which is a single, compact component with two fully integrated GbE Media Access Control (MAC) and Physical Layer (PHY) ports. The Intel® 82576 NIC provides the server board with support for dual LAN ports designed for 10/100/1000 Mbps operation. Refer to the *Intel® 82576 Gigabit Ethernet Controller Datasheet* (Document#: 82576) for full details of the NIC feature set.

The NIC device provides a standard IEEE 802.3 Ethernet interface for 1000BASE-T, 100BASE-TX, and 10BASE-T applications (802.3, 802.3u, and 802.3ab) and is capable of transmitting and receiving data at rates of 1000 Mbps, 100 Mbps, or 10 Mbps.

The Intel® 82576 NIC is powered off the main standby voltage rail via DC to DC Voltage regulators for efficiency purposes. It is on standby power so the BMC can send out-of-band management traffic over the RMII bus to the network during sleep state S5.

The NIC supports the normal RJ-45 LINK/Activity speed LEDs as well as the Proset ID function. These LEDs are powered from a Standby voltage rail.

The link / activity LED (at the right of the connector) indicates network connection when on, and transmit / receive activity when blinking. The speed LED (at the left of the connector) indicates 1000-Mbps operation when amber, 100-Mbps operation when green, and 10-Mbps when off. The following table provides an overview of the LEDs.

Table 7. NIC 1 Status LED

LED Color	LED State	NIC State
Green/Amber (Left)	Off	10 Mbps
	Green	100 Mbps
	Amber	1000 Mbps
Green (Right)	On	Active Connection
	Blinking	Transmit / Receive activity

Table 8. NIC 2 Status LED

LED Color	LED State	NIC State
Green/Amber (Right)	Off	10 Mbps
	Green	100 Mbps
	Amber	1000 Mbps
Green (Left)	On	Active Connection
	Blinking	Transmit / Receive activity

3.8.1 MAC Address Definition

The Intel® Server Board S5500WB has the following four MAC addresses assigned to it at the Intel factory.

- NIC 1 MAC address
- NIC 2 MAC address – Assigned the NIC 1 MAC address +1
- Integrated BMC LAN Channel MAC address – Assigned the NIC 1 MAC address +2
- Intel® Remote Management Module 3 (Intel® RMM3) MAC address – Assigned the NIC 1 MAC address +3

The Intel® Server Board S5500WB has a white MAC address sticker included with the board. The sticker displays the NIC 1 MAC address in both bar code and alphanumeric formats.

3.8.2 LAN Connector Ordering

The Intel® 82576 NIC is connected to a stacked RJ-45 over USB mag-jack for NIC 1 and a RJ-45 mag-jack for the second connection (NIC 2).

3.9 Integrated Baseboard Management Controller

The ServerEngines* LLC Pilot II Integrated BMC is provided by an embedded ARM9 controller and associated peripheral functionality that is required for IPMI-based server management. Firmware usage of these hardware features is platform-dependant.

The following is a summary of the Integrated BMC management hardware features used by the ServerEngines* LLC Pilot II Integrated BMC:

- IPMI 2.0 Compliant
- Integrated 250 MHz 32-bit ARM9 processor
- Six I^2C SMBus modules with Master-Slave support
- Two independent 10/100 Ethernet Controllers with RMII support
- Six I^2C interface
- Memory Management Unit (MMU)
- DDR2 16-bit up to 667 MHz memory interface
- Up to 16 direct and 64 Serial GPIO ports
- 12 10-bit Analog to Digital Converters
- Eight Fan Tachometers Inputs
- Four Pulse Width Modulators (PWM)
- Chassis Intrusion Logic with battery-backed general purpose register
- JTAG Master interface
- Watchdog timer

Additionally, the ServerEngines* Pilot II part integrates a super I/O module with the following features:

- Keyboard Style/BT Interface

- Two 16C550 compatible serial ports
- Serial IRQ support
- 16 GPIO ports (shared with Integrated BMC)
- LPC to SPI Bridge for system BIOS support
- SMI and PME support
- ACPI compliant
- Wake-up control

The Pilot II contains an integrated KVMS subsystem and graphics controller with the following features:

- USB 2.0 for keyboard, mouse, and storage devices
- Hardware Video Compression for text and graphics
- Hardware encryption
- 2D Graphics Acceleration
- DDR2 graphics memory interface
- Matrox 2000 Graphics core with PCI Express* x1 host interface
- Up to 1600x1200 pixel resolution

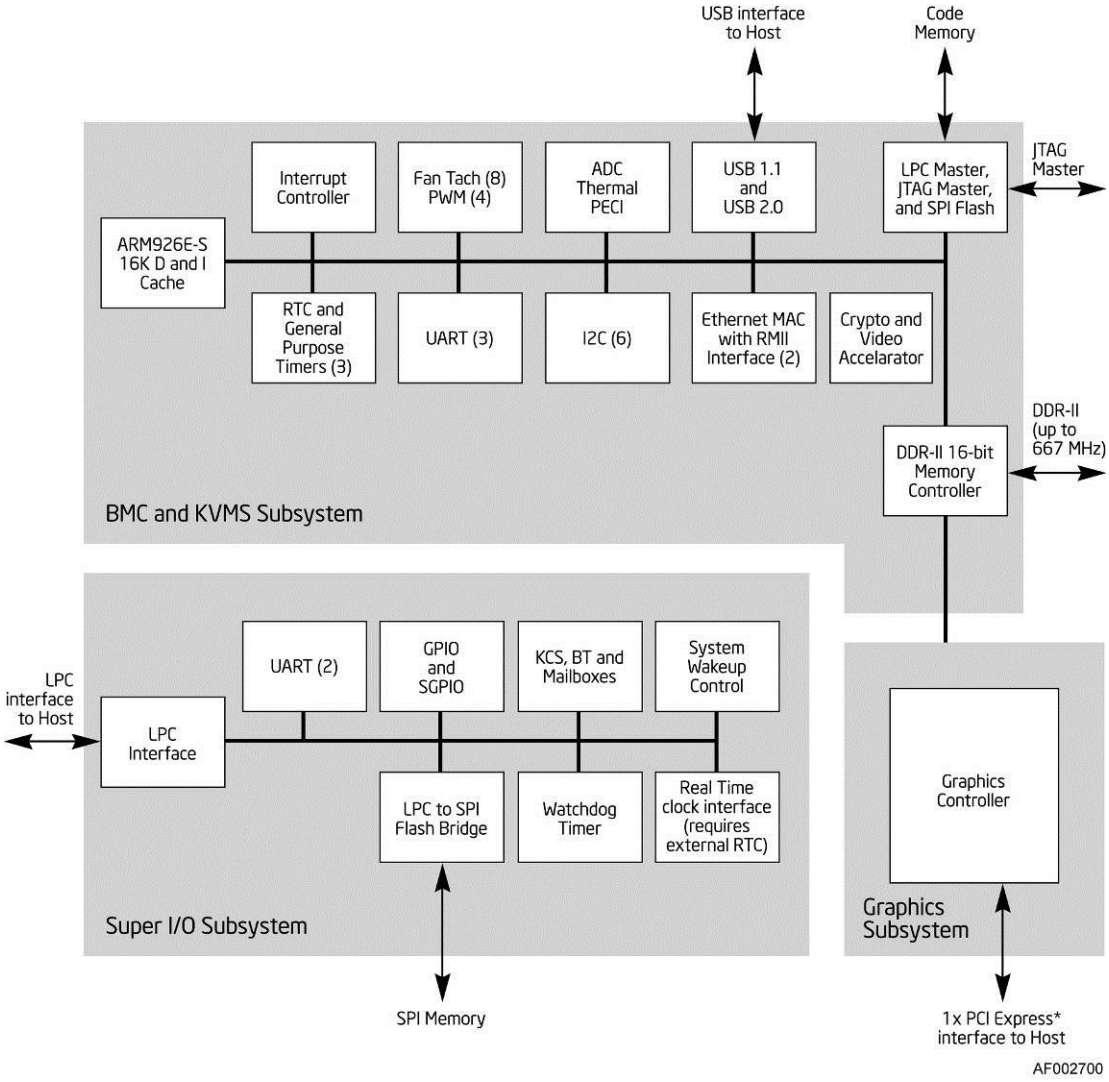


Figure 19. Integrated BMC Hardware

3.9.1 Integrated BMC Embedded LAN Channel

The Integrated BMC hardware includes two dedicated 10/100 network interfaces. These interfaces are not shared with the host system. At any time, you can enable only one dedicated interface for management traffic. The default active interface is the NIC 1 port.

For these channels, you can enable support for IPMI-over-LAN and DHCP.

For security reasons, embedded LAN channels have the following default settings:

- IP Address: Static
- All users disabled.

3.9.2 RMM3 Advanced Management Board:

The RMM3 advanced management board serves two purposes. The first is to give the customer the option to add a dedicated management 100-Mbit LAN interface to the product. The second is to give additional flash space, enabling the Advanced Management functions to support WS-MAN and CIMOM. The RMM3 comes with a third 10/100GbE NIC that connects to the board. RMM3 management traffic can use the third NIC or NIC 1.

Table 8. RMM3 Features

Manageability features	Description
Embedded Web U	Remote Power on\off, sensor status, system info, System Event log, and OEM customization
KVM Redirection	High performance and multiple concurrent sessions
USB 2.0 Media Redirection	Boot over remote media
Security	SSL, SSH support
WS- MAN	
Dedicated NIC	
Shared NIC (Onboard NICs)	
LDAP Support	

3.10 Serial Ports

The server board provides two serial ports: an external RJ-45 serial port and an internal serial header.

The rear RJ-45 serial A port is a fully-functional serial port that can support any standard serial device.

The serial B port is an optional port that is accessed through a 9-pin internal DH-10 header. You can use a standard DH-10 to DB9 cable to direct serial A port to the rear of a chassis. Appendix A defines the serial B interface.

3.11 Wake-up Control

Wake from S1 is supported on LAN, USB, Serial port, and PCI Express* slots.

3.12 Integrated Video Support

The SVGA subsystem supports a variety of modes, up to 1280x1024@24bpp modes under 2D. It also supports both CRT and LCD monitors up to a 200 Hz vertical refresh rate.

The video is accessed using a standard 15-pin VGA connector found in the I/O panel area of the server board. You can disable the onboard video controller using the BIOS Setup utility or when an add-in video card is detected. The system BIOS provides the option for dual-video operation when an add-in video card is configured in the system.

3.12.1 Video Modes

The integrated video controller supports all standard VGA modes. The following table shows the 2D modes supported for both CRT and LCD.

Table 9. Supported Video Modes

2D Mode	2D Video Mode Support				
	8 bpp	16 bpp	24 bpp	32 bpp	
640 x 480	Supported	Supported	Supported	Supported	
	60, 72, 75, 85	60, 72, 75, 85	60, 72, 75, 85	60, 72, 75, 85	Refresh Rate (Hz)
800 x 600	Supported	Supported	Supported	Supported	
	56, 60, 72, 75, 85	56, 60, 72, 75, 85	56, 60, 72, 75, 85	56, 60, 72, 75, 85	Refresh Rate (Hz)
1024 x 768	Supported	Supported	Supported	Supported	
	60, 70, 75, 85	60, 70, 75, 85	60, 70, 75, 85	60, 70, 75, 85	Refresh Rate (Hz)
1152 x 864	Supported	Supported	Supported	N/A	
	75	75	75	N/A	Refresh Rate (Hz)
1280 x 1024	Supported	Supported	Supported	N/A	
	60, 75, 85	60, 75, 85	60	NA	Refresh Rate (Hz)
1440 x 900	Supported	Supported	Supported	N/A	
	60	60	60	NA	Refresh Rate (Hz)
1600 x 1200	Supported	Supported	N/A	N/A	
	60. 65, 70, 75, 85	60. 65, 70	N/A	N/A	Refresh Rate (Hz)

3.12.2 Dual Video

The BIOS supports both single-video and dual-video modes. The dual-video mode is enabled by default in the BIOS.

In the single mode (dual monitor video = disabled), the onboard video controller is disabled when an add-in video card is detected.

In the dual mode (onboard video = enabled, dual monitor video = enabled), the onboard video controller is enabled and is the primary video device. The external video card is allocated resources and is considered the secondary video device. The BIOS Setup utility provides options to configure the feature as follows.

Table 10. Dual Video Options

Onboard Video	**Enabled** Disabled	
Dual Monitor Video	**Enabled** Disabled	Shaded if onboard video is set to "Disabled"

3.12.3 Front Panel Video

The Intel® Server Board S5500WB provides a mechanism to support video to the front panel via the use of an internal header. When a monitor is plugged into the front panel video connector, the rear panel video stream is disconnected.

There is a jumper option to change this default action. When the internal header is used by a third-party Management card to do KVM over LAN and then when a monitor is plugged into the rear panel video connector, the video stream to the internal header is cut off.

3.13 I/O Slots

3.13.1 X16 Riser Slot Definition

Slot 6 was defined to support riser cards. Slot 6 has a x16 physical connector with a PCI Express* Gen II x8 electrical interface. Two clocks are provided so the bus can be bifurcated into two x4 connectors.

Because of CPU placement, a 1U system supports only PCI Express* adapters that meet the PCI SIG half card definition. Full-length boards are supported in a 2U system by using a taller riser and extending the board over the 1U CPU heatsinks or if CPU2 is unpopulated.

Appendix A describes the pin assignments for this connector.

3.13.2 PE WIDTH Strapping

On the Intel® Server Board S5500WB, the IOH needs to be informed of the PCI Express* bus width during power on. This is accomplished using the PEWIDTH input straps. The mechanism used is the PEWIDTH bits, one bit is used to signify the width and number of PCI Express* buses used by the riser. For slot 6, the PEWIDTH bit used is 0.

Table 11. PEWIDTH Strapping Bits

Riser	Description	PEWIDTH0 pin A50
1U one x8	1 x8 PCI Express* Slot	0
2U two x4	2 X4 PCI Express* Slots	1

By using this mechanism for selecting PCI Express* port width, you can avoid a BIOS rediscover and reboot.

The PEWIDTH is pulled up to 3.3 V Aux on the baseboard and grounded, if necessary, by the riser. The baseboard provides an inverter and voltage level translator before passing this signal to the IOH.

3.13.3 Slot 1 PCI Express* x8 Connector

Slot 1 provides a PCI Express* x4 bus on an x8 connector, if provided, for use in a 2U chassis that uses LP boards without risers. Although it is feasible to use the IOM at the same time, it would require 2U chassis back panel changes.

3.13.4 I/O Module Connector

Mezanine connectors are provided to support the various I/O modules, both the older Gen 1 I/O modules supported by Intel® Server Board S5000PAL and newer, double-wide Gen 2 I/O modules supported by the Intel® Server Board S5520UR are supported on the Intel® Server Board S5500WB.

The Intel® I/O Expansion Module is also required to inform the IOH of the Intel® I/O Expansion Module Bus usage, PEWIDTH bit 1 is to be used for this.

Table 12. Intel® I/O Expansion Module Bus PEWIDTH Bits

Intel® I/O Expansion Module	Description	PEWIDTH1 - Pin 2
one x8	1 x8 PCI Express* target device	0
two x4	2 x4 target devices	1

4. Intel® I/O Expansion Modules

The Intel® Server Board S5500WB supports a variety of I/O Module options using 2x4 PCI Express* Gen2 Intel® I/O Expansion Module connectors on the rear of the server board. Each Intel® I/O Expansion Module connector is a 50-pin, surface mount, 0.8mm pitch, header. The Intel® Server Board S5500WB accommodates both the double-wide I/O expansion modules and the PCI Express* Gen 1 I/O modules (used on the S5000PAL rack server).

The Legacy modules are:

- Dual Port GbE I/O Module
- External 4 Port SAS I/O Module

The new modules consist of:

- Internal 4-port Intel 82576EB GbE*
- Dual Port Intel 10GbE I/O Module
- Internal 4-port LSI* 1064e SAS I/O Module
- Internal 4-port LSI* 1078e SAS I/O Module
- Infiniband* I/O Expansion Module Single Port QDR

The second x4 Intel® I/O Expansion Module controller does not support a single-wide module; it is only used to support a double-wide module. You must mount single-wide modules on connector (J3B1) closest to Slot 6, marked Legacy Intel® I/O Expansion Module on the silkscreen. When double-wide Intel® I/O Expansion Modules are installed, there might be interference with some adapters installed in Slot 1.

The following table shows the product codes for each module.

Table 13. Intel® I/O Expansion Module Product Codes

Product Code	Description
AXX4SASMOD	Intel® SAS Entry RAID I/O Expansion Module: Provides 4-port pass through SAS, entry-level RAID 0/1/1E, and optional host RAID (4 internal ports).
AXXGBIOMOD	Dual Gigabit Ethernet I/O Expansion Module
AXXROMBSASMR	Intel® Integrated RAID I/O Expansion Module: Provides four internal ports, full-featured SAS / SATA RAID 0,1,5,6 and striping capability for spans 10, 50, 60. You must order the optional backup battery AXXRSBBU3 separately.
AXXSASIOMOD	External 4-port SAS I/O Expansion Module.
AXX10GBIOMOD	Dual-port 10 Gigabit Ethernet I/O Expansion Module with CX4 connectors.

Product Code	Description
AXX4GBIOMOD2	Quad port Gigabit Ethernet I/O Expansion Module based on the Intel® 82576EB Gigabit Ethernet Controller.
AXXIBQDRMOD	InfiniBand* I/O Expansion Module Single Port QDR.

For more information, refer to the I/O modules in the *Intel® I/O Expansion Modules Hardware Specification*.

5. Platform Management Features

This section explains BIOS and firmware (FW) requirements that drive specific hardware implementations of the platform. To a large extent, this is background information.

5.1 BIOS Feature Overview

The Intel® Server Board S5500WB product uses the AMI Aptio v3.x code base.

5.1.1 EFI Support

The platform BIOS is compiled to support the 64-bit EFI environment, natively. This allows operating systems that are EFI-aware to take advantage of the EFI-boot process in a native 64-bit environment. It is expected this will reduce the time required to boot the platform to those operating systems. Additionally, any utilities that make use of the EFI environment provided by the platform BIOS need to support either the native 64-bit environment or make use of the EFI byte code (EBC). Of course, to maintain compatibility with legacy operating environments, a legacy boot option is provided.

5.1.2 BIOS Recovery

The platform BIOS supports a BIOS Recovery Mode Jumper. The BIOS samples this jumper during POST through a GPIO and, if set, defaults to a recovery mode of operation that allows restoration of the BIOS Flash to a full operational state.

The platform BIOS supports a Reset BIOS Configuration Jumper. The BIOS samples this jumper during POST through a GPIO and, if set, resets its configuration information stored in Flash memory.

5.2 BMC Feature Overview

The server management subsystem consists of multiple components including several interconnected microcontrollers. The subsystem monitors platform sensors (temperatures, voltages, fans, hard drives, and so forth); implements platform acoustics, power, and thermal management policies; provides an intelligent LCD front-panel; and provides facilities for remote and local management.

The server management subsystem is available when the system is connected to wall power but not fully operational (S5 state); when the system is in a S1 sleep state or when the system is fully operational (S0 state).

5.2.1 Server Engines Pilot II Controller

The center of the server management subsystem is the Server Engines Pilot II integrated Baseboard Management Controller. This device provides support for many platform functions including system video capabilities, legacy Super I/O functions, and also provides an ARM 926-EJ microcontroller to host the embedded server management firmware stack.

The Server Engines Pilot II baseboard management controller across Intel's server product line with two different management feature set configurations: Basic and Advanced. The Intel® Server Board S5500WB supports both.

Basic features include IPMI 2.0 support, remote management, hardware monitoring, event management, event alerting, system event log, asset inventory, console redirection, web interface, and SMASH CLP (basic feature set).

Advanced features include the Basic features plus KVM redirection, USB Media redirection, SMASH CLP (Advanced feature set), and WS-MAN. To enable the Advanced features, you must install the Remote Management Module 3.

Note: The BMC consumes two USB ports; one runs at USB1.1 for keyboard mouse redirection and one runs at USB2.0 for media redirection.

5.2.2 BMC Firmware

The BMC supports a Fast Firmware Update mode in addition to the standard KCS (Keyboard Controller Style) SMS interface. This is a special AMI® proprietary protocol that goes over the USB connection between the host and the BMC. Called "IPMI over USB", it is implemented in the LIBIPMI library on both host and BMC sides to transfer large blocks of data (up to 32 K) much faster than KCS can. IPMI commands are embedded in data written/read to a virtual CD-ROM device.

The embedded server management firmware stack is based on a core stack from American Megatrends Incorporated (AMI). The stack runs on an embedded version of the Linux operating system and provides support for current industry standard management interfaces (IPMI 2.0) and emerging industry standard advanced management interfaces (SMASH-CLP and WS-MAN). The stack also includes support for keyboard, video, mouse (KVM), and USB media redirection.

The server management subsystem provides remote connectivity through a single GbE NIC with NC-SI support (RMII).

NPTM support is required; you must use the ME function in the IOH to accomplish this.

5.2.3 BMC Basic Features

Table 14: BMC Basic Features

Feature	Description
IPMI 2.0	Compliance to IPMI 2.0 specification
Remote Management	Out-of-band access via either LAN or serial port for numerous features
Hardware Monitor	Monitor of fans, voltages, temperatures, chassis intrusions, memory errors, power supplies, hard drives, and so forth
Event Management	System event filtering
Event Alerting	System events delivered via SNMP traps or email
System Event Log	Dedicated persistent storage for system events
Asset Inventory	Field replaceable unit (FRU) information
Console Redirection	Text-based console redirection via serial-over-LAN

Feature	Description
SMASH CLP (Basic)	Command line SSH interface for basic server management operations
Node Manager	Power management by using P-state\C-State cycling method Requires PMBus* power supply.

5.2.4 BMC Advanced Features

The Intel® Server Board S5500WB product includes support for an upgrade module to support the advanced server management functionality. The Remote Management Module 3 supports an 8 MB SPI Flash, which connects to the integrated BMC SPI interface. This is in addition to the local integrated BMC 8 MB SPI flash connected to the PILOT II IBMC down on the board. The total 16 MB of Flash space is required to support advanced management features as defined in the following table. The RMM3 advanced management board has a PHY device that which interfaces with the secondary NC-SI port out of the Server Engines PILOT II integrated BMC to offer a dedicated management Ethernet port.

Table 15. Advanced Features

Manageability features	Description
Embedded Web UI	Remote Power on\off, sensor status, system info, System Event log, OEM customization
KVM Redirection	high performance, multiple concurrent sessions
USB 2.0 Media Redirection	boot over remote media
Security	SSL, SSH support
WS- MAN	
Dedicated NIC	
Shared NIC (Onboard NICs)	
LDAP support	

5.3 Management Engine (ME)

5.3.1 Overview

The Intel® Server Platform Services (SPS) is a set of manageability services provided by the firmware executing on an embedded ARC controller within the IOH. This management controller is also commonly referred to as the Management Engine (ME). The functionality provided by the SPS firmware is different from Intel® Active Management Technology (Intel® AMT or AT) provided by the ME on client platforms.

Server Platform Services (SPS) are value-added platform management options that enhance the value of Intel platforms and their component ingredients (CPUs, chipsets, and I/O components). Each service is designed to function independently wherever possible, or

grouped together with one or more features in flexible combinations to allow OEMs to differentiate platforms.

5.3.2 BMC - Management Engine Interaction

Management Engine-Integrated BMC interactions include the following:

- Integrated BMC stores sensor data records for ME-owned sensors.
- Integrated BMC participates in ME firmware update.
- Integrated BMC initializes ME-owned sensors based on SDRs.
- Integrated BMC receives platform event messages sent by the ME.
- Integrated BMC notifies ME of POST completion.

5.4 Data Center Manageability Interface

The DCMI specifications are derived from Intelligent Platform Management Interface (IPMI) 2.0. The DCMI specifications define a uniform set of monitoring, control features and interfaces that target the common and fundamental hardware management needs of server systems that are used in large deployments within data centers, such as Internet Portal data centers. This includes capabilities such as secure power and reset control, temperature monitoring, event logging, and others. For more information refer to www.intel.com/go/dcmi.

5.5 Other Platform Management

The platform supports the following sleep states, S1 and S5. Within S0, the platform supports additional lower power states, such as C1e and C6, for the CPU.

5.5.1 Wake On LAN (WOL)

- Wake On LAN (WOL) is supported on both LAN ports and IOM LAN modules for all supported Sleep states.
- Wake on Ring is supported on the external Serial port only for all supported Sleep states.
- Wake on USB is supported on the rear and front panel USB ports for S1 only.
- Wake on RTC is supported for all supported Sleep states.
- Wake IPMI command is supported (BMC function no additional hardware requirement) for all supported Sleep states.

5.5.2 PCI Express* Power management

L0 and L3 power management states are supported on all PCI Express* slots and embedded end points.

5.5.3 PMBus*

Power supplies that have PMBus* 1.1 are supported and required to support Intel® Dynamic Power Node Manager. Intel® Server Board S5500WB supports the features of Intel® Dynamic Power Node Manager version 1.5 except the inlet temperature sensor.

5.6 I2C\SMBUS Architecture Block

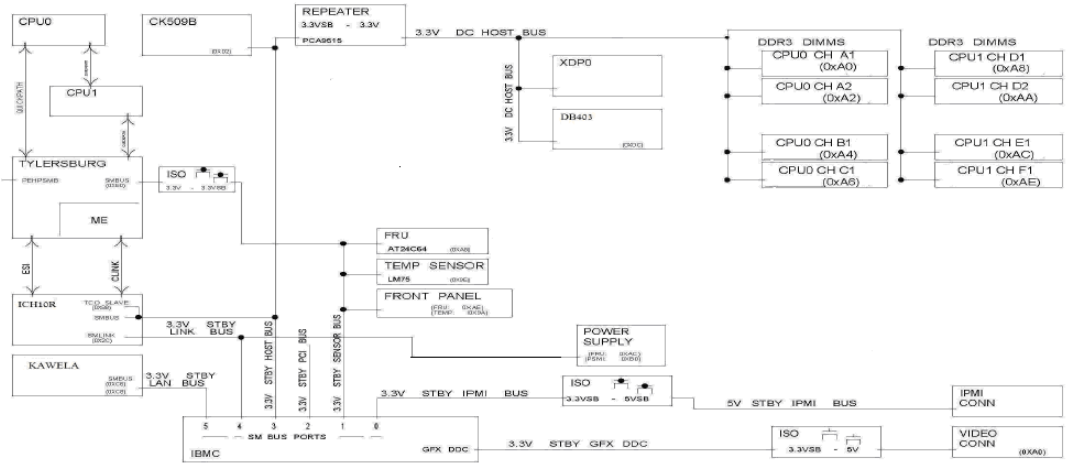


Figure 20. S5500WB I2C\SMBUS Block Diagram

5.6.1 I2C\SMBUS Device Addresses

Table 21 lists the I2C\SMBus addresses of various devices by bus.

Table 16. I2C/SMBus Device Address Assignment

Main Bus	Power Rail	Sub Bus	Power Rail	Device	I2C\SMBus Address	Note
Host	3V3SB	NA	NA	IBMC I2C\SMBus 3		No Connect
				ICH10R SMBus	0x88	
				CK509B	0xD2	
				DB403	0xDC	
		Host	3V3	XDP		
				DB803	0xDC	
				CPU0 DIMM 1A	0xA0	
				CPU0 DIMM 2A	0xA2	
				CPU0 DIMM 1B	0xA4	
				CPU0 DIMM 1C	0xA6	
				CPU0 DIMM 1D	0xA8	
				CPU0 DIMM 2D	0xAA	
				CPU0 DIMM 1E	0xAC	
				CPU0 DIMM 1F	0xAE	
Sensor	3V3SB	NA	NA	IBMC I2C\SMBus 1		
				Temp Sensor	0x9E	
				FP Temp Sensor	0x9A	
				FP FRU	0xAE	
				Baseboard FRU	0xA8	
				CPU IOH	0xE0	
IPMI	3V3SB	NA	NA	IBMC I2C\SMBus 0		
		IPMI	5VSB	IPMI Connector		
		IPMI	5V	HSBP A	0xC0	

Main Bus	Power Rail	Sub Bus	Power Rail	Device	I2C\SMBus Address	Note
LAN	3V3SB	NA	NA	IBMC I2C\SMBus 5		
				NIC LAN		
Link	3V3SB	NA	NA	IBMC I2C\SMBus 4		
				ICH10R SMLINK	0x88	
		PWR	5V	PS FRU	0xAC	
				PS I2C\PSMI	0xB0	
Spare	3V3SB	NA	NA	IBMC I2C\SMBus 2		
DDC	3V3SB	DDC	5V	IBMC GFX DDC		
				Video Monitor	0xA0	

6. Configuration Jumpers

The following table provides a summary and description of configuration, test, and debug jumpers on the Intel® Server Board S5500WB. The server board has several 3-pin jumper blocks that can be used.

Pin 1 on each jumper block can be identified by the following symbol on the silkscreen: ▼

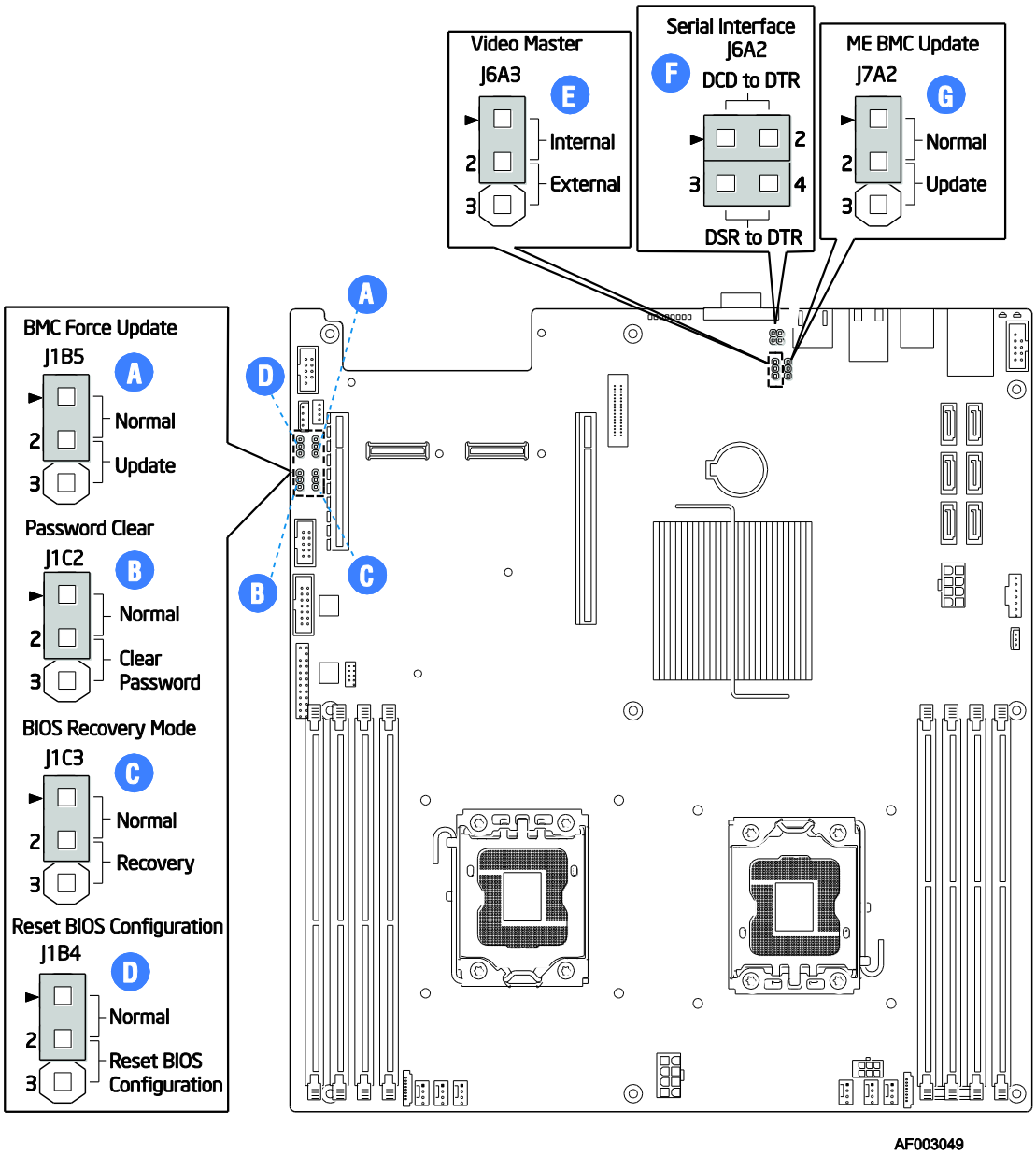


Figure 21: Jumper Blocks (J1B5, J1C2, J1C3, J1B4, J6A3, J6A2, J7A2)

Table 17: Server Board Jumpers (J1B5, J1C2, J1C3, J1B4, J6A3, J6A2)

Jumper Name	Jumper Position	Mode of Operation	Note
J1B5: BMC Force Update jumper	1-2	Normal	IBMC GPIO[1] is pulled HIGH. Default position.
	2-3	Update	IBMC GPIO[1] is pulled LOW.
J1C2: Password Clear	1-2	Normal	ICH10R INTRUDER# pin is pulled HIGH. Default position.
	2-3	Clear Password	ICH10R INTRUDER# pin is pulled LOW.
J1C3: BIOS Recovery Mode	1-2	Normal	ICH10R GPIO [55] is pulled HIGH. Default position.
	2-3	Recovery	ICH10R GPIO [55] is pulled LOW.
J1B4: CMOS Clear	1-2	Normal	ICH10R RTCRST# pin is pulled HIGH. Default position.
	2-3	Clear CMOS Settings	ICH10R RTCRST# pin is pulled LOW.
J6A3: Video Master	1-2	Internal	Internal connector will override if both connectors are used.
	2-3	External	External connector will override if both connectors are used.
J7A2: ME Firmware Force Update	1-2	Disabled	Default
	2-3	Enabled	
J6A2: Serial Interface	1 – 2	DCD to DTR	Data Carrier Detect
	3 – 4	DSR to DTR	Data Set Ready

6.1.1 Force IBMC Update (J1B5)

When performing a standard BMC firmware update procedure, the update utility places the BMC into an update mode, allowing the firmware to load safely onto the flash device. In the unlikely event the BMC firmware update process fails due to the BMC not being in the proper update state, the server board provides a BMC Force Update jumper (J1B5) which will force the BMC into the proper update state. The following procedure should be followed in the event the standard BMC firmware update process fails.

Table 18. Force IBMC Update Jumper

Jumper Position	Mode of Operation	Note
1-2	Normal	IBMC GPIO[1] is pulled HIGH. Default position.
2-3	Update	IBMC GPIO[1] is pulled LOW.

1. Power down and remove the AC power cord.
2. Open the server chassis. See your server chassis documentation for instructions.
3. Move jumper from the default operating position, covering pins1 and 2, to the enabled position, covering pins 2 and 3.
4. Close the server chassis.
5. Reconnect the AC cord and power up the server.

6. Perform the BMC firmware update procedure as documented in the README.TXT file included in the given BMC firmware update package. After successful completion of the firmware update process, the firmware update utility may generate an error stating the BMC is still in update mode.
7. Power down and remove the AC power cord.
8. Open the server chassis.
9. Move the jumper from the enabled position, covering pins 2 and 3 to the disabled position, covering pins 1 and 2.
10. Close the server chassis.
11. Reconnect the AC cord and power up the server.

Note: Normal BMC functionality is disabled with the Force BMC Update jumper is set to the enabled position. You should never run the server with the BMC Force Update jumper set in this position. You should only use this jumper setting when the standard firmware update process fails. This jumper should remain in the default / disabled position when the server is running normally.

The server board has several 3-pin jumper blocks that can be used to configure, protect, or recover specific features of the server board.

6.1.2 Password Clear (J1C2)

The user sets this 3-pin jumper to clear the password.

Table 19. Password Clear Jumper

Jumper Position	Mode of Operation	Note
1-2	Normal	ICH10R INTRUDER# pin is pulled HIGH. Default position.
2-3	Clear Password	ICH10R INTRUDER# pin is pulled LOW.

6.1.2.1 Clearing the Password

1. Power down server. Do not unplug the power cord.
2. Open the chassis. For instructions, see your server chassis documentation.
3. Move jumper (J1B6) from the default operating position, covering pins 1 and 2, to the password clear position, covering pins 2 and 3.
4. Close the server chassis.
5. Power up the server, wait 10 seconds or POST completes.
6. Power down the server.
7. Open the chassis and move the jumper back to default position, covering pins 1 and 2.
8. Close the server chassis.
9. Power up the server.

The password is now cleared and you can reset it by going into the BIOS setup.

6.1.3 BIOS Recovery Mode (J1C3)

The Intel® Server Board S5500WB uses BIOS recovery to repair the system BIOS from flash corruption in the main BIOS and Boot Block. This 3-pin jumper is used to reload the BIOS when the image is suspected to be corrupted. For directions on how to recover the BIOS, refer to the specific BIOS release notes.

Table 20. BIOS Recovery Mode Jumper

Jumper Position	Mode of Operation	Note
1-2	Normal	ICH10R GPIO [55] is pulled HIGH. Default position.
2-3	Recovery	ICH10R GPIO [55] is pulled LOW.

You can accomplish a BIOS recovery from the SATA CD and USB Mass Storage device. Please note that this platform does not support recovery from a USB floppy.

The recovery media must contain the following files under the root directory:

1. FVMAIN.FV
2. UEFI iFlash32 2.6 Build 9
3. *Rec.CAP
4. Startup.nsh (update accordingly to use proper *Rec.CAP file)

The BIOS starts the recovery process by first loading and booting to the recovery image file (FVMAIN.FV) on the root directory of the recovery media (SATA CD or USB disk).This process takes place before any video or console is available. Once the system boots to this recovery image file (FVMAIN.FV), it boots automatically into the EFI Shell to invoke the `Startup.nsh` script and start the flash update application (IFlash32.efi). IFlash32.efi requires the supporting BIOS Capsule image file (*Rec.CAP). After the update is complete, a message displays, stating the "BIOS has been updated successfully". This indicates the recovery process is finished. The user should then switch the recovery jumper back to normal operation and restart the system by performing a power cycle.

The following steps demonstrate this recovery process:

1. Power OFF the system.
2. Insert recovery media.
3. Switch the recovery jumper. Details regarding the jumper ID and location can be obtained from the Board EPS for that Platform.
4. Power ON the system.
5. The BIOS POST screen will appear displaying the progress, and the system automatically boots to the EFI SHELL.
6. The Startup.nsh file executes, and initiates the flash update (IFlash32.efi) with a new capsule file (*Rec.CAP). The regular IFlash message displays at the end of the process—once the flash update succeeds.
7. Power OFF the system, and revert the recovery jumper position to "normal operation".
8. Power ON the system.
9. Do NOT interrupt the BIOS POST during the first boot.

6.1.4 Reset BIOS Configuration (J1B4)

This jumper used to be the CMOS Clear jumper. Since the previous generation, the BIOS has moved CMOS data to the NVRAM region of the BIOS flash. The BIOS checks during boot to determine if the data in the NVRAM needs to be set to default.

Table 21. Reset BIOS Jumper

Jumper Position	Mode of Operation	Note
1-2	Normal	ICH10R RTCRST# pin is pulled HIGH. Default position.
2-3	Reset BIOS Configuration	ICH10R RTCRST# pin is pulled LOW.

6.1.4.1 Clearing the CMOS

1. Power down server. Do not unplug the power cord.
2. Open the server chassis. For instructions, see your server chassis documentation.
3. Move jumper (J1B4) from the default operating position, covering pins 1 and 2, to the reset / clear position, covering pins 2 and 3.
4. Wait five seconds.
5. Remove AC power.
6. Move the jumper back to default position, covering pins 1 and 2.
7. Close the server chassis.
8. Power up the server.

The CMOS is now cleared and you can reset it by going into the BIOS setup.

Note: Removing AC Power before performing the CMOS Clear operation causes the system to automatically power up and immediately power down, after the procedure is followed and AC power is re-applied. If this happens, remove the AC power cord again, wait 30 seconds, and re-install the AC power cord. Power-up the system and proceed to the <F2> BIOS Setup Utility to reset the desired settings.

6.1.5 Video Master (J6A3)

Table 22. Video Master Jumper

Jumper Position	Mode of Operation	Notes
1-2	Internal	Internal connector will override if both connectors are used.
2-3	External	External connector will override if both connectors are used.

This jumper determines which video is the primary.

J6A3, 1-2 jumpered: Internal video connector is primary, but video can come out of external video connector if you connect to it.

J6A3, 2-3 jumpered: External video connector is primary, but video can come out of internal video connector if you connect to it.

6.1.6 ME Firmware Force Update (J7A2)

Pins	ME Firmware Update Mode
1-2	Disabled (Default)
2-3	Enabled

The ME firmware consists of two operational images and a recovery image. During boot, the recovery loader is started first and it tries to load the active firmware image by running the loader of this image. If it fails to boot, it tries to boot the other operational image. If both fail, the recovery loader starts in recovery mode. The recovery mode can also be forced setting the MGPIOx jumper on the board. Boot image verification and boot failure

6.1.7 Serial Interface (J6A2)

Pins	Mode	Description
1 – 2	DCD to DTR	Data Carrier Detect
3 – 4	DSR to DTR	Data Set Ready

7. Connector/Header Locations and Pin-out

7.1 Power Connectors

Table 23. SSI SKU 24-pin 2x12 Connector (J9B3)

Pin	Signal Name	Pin	Signal Name
1	+3.3V	13	+3.3V
2	+3.3V	14	-12V
3	GND	15	GND
4	+5V	16	PS_ON
5	GND	17	GND
6	+5V	18	GND
7	GND	19	GND
8	PWR_GD	20	NC
9	SB5V	21	+5V
10	+12V	22	+5V
11	+12V	23	+5V
12	+3.3V	24	GND

Table 24. CPU 12V Power 2x4 Connector (J5K1)

Pin	Signal Name
1	GND
2	GND
3	GND
4	GND
5	+12V
6	+12V
7	+12V
8	+12V

Table 25. SSI Power Control (J9D1)

Pin	Signal Name
1	SMB_PWR_CLK
2	SMB_PWR_DAT
3	SMB_PWR_ALRT
4	GND
5	3.3V Remote Sense

Table 26. 12-V only 2x4 Connector (replaces EPSD12V 2x12 connector) (J9D2)

Pin	Signal Name
1	GND
2	GND
3	GND
4	GND
5	+12V
6	+12V
7	+12V
8	+12V

Table 27. 12-V Only Power Control (replaces the 1x5 power control) (J9D1)
(FOXCONN ELECTRONICS INC HF1107V-P1 or TYCO ELECTRONICS CORPORATION 5-104809-6)

Pin	Signal Name
1	SMB_PWR_CLK
2	SMB_PWR_DAT
3	SMB_PWR_ALRT
4	Remote Sense Return
5	12V Remote Sense
6	PS_ON
7	5V S/B

Table 28. Peripheral Power (Only for 12-V only SKU) (J8K2)
(iPN: C22293-003 MOLEX CONNECTOR CORPORATION 43045-0627)

Note: This connector is for output power only. The 5V is limited to 6.5A and the 3.3V is limited to 2A. Pin 4 is a 3.3V output Power Good signal if needed for a backplane

Pin	Signal Name
1	5V
2	5V
3	GND
4	Powergood
5	3.3V
6	GND

7.2 System Management Headers

7.2.1 Intel® Remote Management Module 3 (Intel® RMM3) Connector

A 34-pin Intel® RMM 3 connector (J5B1) is included on the server board to support the optional Intel® Remote Management Module 3. There is no support for third-party management cards on this server board.

Note: This connector is not compatible with the Intel® Remote Management Module (Intel® RMM) or the Intel® Remote Management Module 2 (Intel® RMM2).

Table 29. Intel® RMM3 Connector Pin-out (J5B1)

Pin	Signal Name	Pin	Signal Name
1	3V3_AUX	2	RMII_MDIO
3	3V3_AUX	4	RMII_MDC
5	GND	6	RMII_RXD1
7	GND	8	RMII_RXD0
9	GND	10	RMII_RX_DV
11	GND	12	RMII_REF_CLK
13	GND	14	RMII_RX_ER
15	GND	16	RMII_TX_EN
17	GND	18	KEY (pin removed)
19	GND	20	RMII_TXD0
21	GND	22	RMII_TXD1
23	3V3_AUX	24	SPI_CS_N
25	3V3_AUX	26	NC (spare)
27	3V3_AUX	28	SPI_DO
29	GND	30	SPI_CLK
31	GND	32	SPI_DI
33	GND	34	RMM3_Present_N (pulled high on baseboard and shorted to ground on the plug in module)

7.2.2 BMC Power Cycle Header (12V Only)

A header is provided so you can use an external switch to remove power from the BMC. In effect, it causes a BMC Power on reset to occur.

Table 30. BMC Power Cycle Header (J1D2)

Pin	Description	Note
1	RST_BMC_PWR_CYC	When power is removed from the BMC.
2	GND	

If this switch is used while the system power is still applied, then the main power rail regulators is disabled first, then the main 3.3V S/B regulator is disabled, removing power from the BMC.

The usage of this header is to recover a non-responsive board, possibly caused by a hung BMC.

7.2.3 Hard Drive Activity (Input) LED Header

Table 47. SATA HDD Activity (Input) LED Header (J1D2)

Pin	Description
1	LED_HD_ACTIVE_L
2	NC

7.2.4 IPMB Header

Table 31. IPMB Header 4-pin (J1B2)

Pin	Signal Name	Description
1	SMB_IPMB_5VSB_DAT	BMC IPMB 5V standby data line
2	GND	Ground
3	SMB_IPMB_5VSB_CLK	BMC IPMB 5V standby clock line
4	P5V_STBY	+5V standby power

7.2.5 SGPIO Header

Table 32. SGPIO Header (J1B1)

Pin	Signal Name	Description
1	SCLOCK	SGPIO Clock Signal
2	SLOAD	SGPIO Load Signal
3	SDOUT0	SGPIO Data Out
4	SDOUT1	SGPIO Data In

7.3 SSI Control Panel Connector

The server board provides a 24-pin SSI front panel connector (J1E2) for use with SSI compliant third-party chassis. The following table provides the pin-out for this connector.

Table 33. Front Panel SSI Standard 24-pin Connector Pin-out (J1E2)

Pin	Signal Name	Pin	Signal Name
1	P3V3_STBY (Power LED Anode)	2	P3V3_STBY (Front Panel Power)
3	Key	4	P5V_STBY (ID LED Anode)
5	FP_PWR_LED_N	6	FP_ID_LED_BUF_N
7	P3V3 (HDD Activity LED Anode)	8	FP_LED_STATUS_GREEN_N
9	LED_HDD_ACTIVITY_N	10	FP_LED_STATUS_A MBER_N
11	FP_PWR_BTN_N	12	NIC1_ACT_LED_N
13	GND (Power Button GND)	14	NIC1_LINK_LED_N
15	BMC_RST_BTN_N	16	SMB_SENSOR_3V3STB_DATA
17	GND (Reset GND)	18	SMB_SENSOR_3V3STB_CLK
19	FP_ID_BTN_N	20	FP_CHASSIS_INTRU
21	NC	22	NIC2_ACT_LED_N
23	FP_NMI_BTN_N	24	NIC2_LINK_LED_N

Combined system BIOS and the Integrated BMC support provide the functionality of the various supported control panel buttons and LEDs. The following sections describe the supported functionality of each control panel feature.

7.3.1 Power Button

The BIOS supports a front control panel power button. Pressing the power button initiates a request that the Integrated BMC forwards to the ACPI power state machines in the chipset. It is monitored by the Integrated BMC and does not directly control power on the power supply.

- **Power Button — Off to On**
  The Integrated BMC monitors the power button and the wake-up event signals from the chipset. A transition from either source results in the Integrated BMC starting the power-up sequence. Since the processors are not executing, the BIOS does not participate in this sequence. The hardware receives the power good and reset signals from the Integrated BMC and then transitions to an ON state.
- **Power Button — On to Off (operating system absent)**
  The System Control Interrupt (SCI) is masked. The BIOS sets up the power button event to generate an SMI and checks the power button status bit in the ACPI hardware registers when an SMI occurs. If the status bit is set, the BIOS sets the ACPI power state of the machine in the chipset to the OFF state. The Integrated BMC monitors power state signals from the chipset and de-asserts PS_PWR_ON to the power supply. As a safety mechanism, if the BIOS fails to service the request, the Integrated BMC automatically powers off the system in four to five seconds.
- **Power Button — On to Off (operating system present)**
  If an ACPI operating system is running, pressing the power button switch generates a request via SCI to the operating system to shut down the system. The operating system retains control of the system and the operating system policy determines the sleep state into which the system transitions, if any. Otherwise, the BIOS turns off the system.

7.3.2 Reset Button

The platform supports a front control panel reset button. Pressing the reset button initiates a request forwarded by the Integrated BMC to the chipset. The BIOS does not affect the behavior of the reset button.

7.3.3 NMI Button

The BIOS supports a front control panel NMI button. The NMI button may not be provided on all front panel designs. Pressing the NMI button initiates a request that causes the Integrated BMC to generate an NMI (non-maskable interrupt). The NMI is captured by the BIOS during boot services time and by the operating system during runtime. During boot services time, the BIOS halts the system upon detection of the NMI.

7.3.4 Chassis Identify Button

The front panel Chassis Identify button toggles the state of the chassis ID LED. If the LED is off, pushing the ID button lights the LED. It remains lit until the button is pushed again or until a *Chassis Identify* or a *Chassis Identify LED* command is received to change the state of the LED.

7.3.5 Power LED

The green power LED is active when the system DC power is on. The power LED is controlled by the BIOS. The power LED reflects a combination of the state of system (DC) power and the system ACPI state. The following table identifies the different states that the power LED can assume.

Table 34. Power LED Indicator States

State	ACPI	Power LED
Power off	No	Off
Power on	No	Solid on
S5	Yes	Off
S1 Sleep	Yes	~1 Hz blink
S0	Yes	Solid on

7.3.6 System Status LED

Note: The system status LED state shows the state for the current, most severe fault. For example, if there was a critical fault due to one source and a non-critical fault due to another source, the system status LED state would be solid on (the critical fault state).

The system status LED is a bicolor LED. Green (status) shows a normal operation state or a degraded operation. Amber (fault) shows the system hardware state and overrides the green status.

The Integrated BMC-detected state and the state from the other controllers, such as the SCSI / SATA hot-swap controller state, are included in the LED state. For fault states monitored by the Integrated BMC sensors, the contribution to the LED state follows the associated sensor state, with the priority going to the most critical state currently asserted.

When the server is powered down (transitions to the DC-off state or S5), the Integrated BMC is still on standby power and retains the sensor and front panel status LED state established prior to the power-down event.

The following table maps the system state to the LED state.

Table 35. System Status LED

Color	State	System Status	Description
Green	Solid on	Ok	System ready
Green	~1 Hz blink	Degraded	BIOS detected 1. Unable to use all of the installed memory (more than one DIMM installed).1 2. In a mirrored configuration, when memory mirroring takes place and system loses memory redundancy. This is not covered by (2). 1 3. PCI Express* correctable link errors. Integrated BMC detected 1. Redundancy loss such as a power supply or fan. Applies only if the associated platform subsystem has redundancy capabilities. 2. CPU disabled – if there are two CPUs and one CPU is disabled. 3. Fan alarm – Fan failure. Number of operational fans should be more than minimum number needed to cool the system. 4. Non-critical threshold crossed – Temperature, voltage, power nozzle, power gauge, and PROCHOT2 (Therm Ctrl) sensors. 5. Battery failure. 6. Predictive failure when the system has redundant power supplies.
Amber	~1 Hz blink	Non-Fatal	Non-fatal alarm – system is likely to fail: **BIOS Detected** 1. In non-mirroring mode, if the threshold of ten correctable errors is crossed within the window.1 2. PCI Express* uncorrectable link errors. **Integrated BMC Detected** 3. Critical threshold crossed – Voltage, temperature, power nozzle, power gauge, and PROCHOT (therm Ctrl) sensors. 4. VRD Hot asserted. 5. Minimum number of fans to cool the system is not present or have failed.
Amber	Solid on	Fatal	Fatal alarm – system has failed or shut down: **BIOS Detected** 1. DIMM failure when there is one DIMM present and no good memory is present.1 2. Run-time memory uncorrectable error in non-redundant mode.1 3. CPU configuration error (for instance, processor stepping mismatch). **Integrated BMC Detected** 1. CPU CATERR signal asserted. 2. CPU 1 is missing. 3. CPU THERMTRIP. 4. No power good – power fault. 5. Power Unit Redundancy sensor – Insufficient resources offset (indicates not enough power supplies are present).
Off	N/A	Not ready	Main power off

Notes:
1. The BIOS detects these conditions and sends a *Set Fault Indication* command to the Integrated BMC to provide the contribution to the system status LED.

7.3.7 Chassis ID LED

The chassis ID LED provides a visual indication of a system being serviced. The state of the chassis ID LED is affected by the following:

- Toggled by the chassis ID button
- Controlled by the *Chassis Identify* command (IPMI)
- Controlled by the *Chassis Identify LED* command (OEM)

Table 36. Chassis ID LED Indicator States

State	LED State
Identify active via button	Solid on
Identify active via command	~1 Hz blink
Off	Off

There is no precedence or lock-out mechanism for the control sources. When a new request arrives, all previous requests are terminated. For example, if the chassis ID LED is blinking and the chassis ID button is pressed, then the chassis ID LED changes to solid on. If the button is pressed again with no intervening commands, the chassis ID LED turns off.

7.4 I/O Connectors

7.4.1 PCI Express* Connectors

The Intel® Server Board S5500WB has two PCI Express slots. The pin-outs for the slots are shown in the following tables.

Table 37. Slot 6 Riser Connector (J4B1)

Pin Side B	PCI Express* Signal	PCI Express* Signal	Pin Side A
1	12V	PRSNT1#	1
2	12V	12V	2
3	RSVD	12V	3
4	GND	GND	4
5	SMCLK	JTAG2	5
6	SMDATA	JTAG3	6
7	GND	JTAG4	7
8	3.3V	JTAG5	8
9	JTAG1	3.3V	9
10	3.3VAUX	3.3V	10
11	WAKE#	PERST#	11
KEY	KEY	KEY	KEY
KEY	KEY	KEY	KEY
12	RSVD	GND	12

Pin Side B	PCI Express* Signal	PCI Express* Signal	Pin Side A
41	PETxP6	GND	41
42	PETxN6	GND	42
43	GND	PERxP6	43
44	GND	PERxN6	44
45	PETxP7	GND	45
46	PETxN7	GND	46
47	GND	PERxP7	47
48	PRSNT2#	PERxN7	48
49	GND	GND	49
50	PETxP8	RSVD	50
51	PETxN8	GND	51
52	GND	PERxP8	52
53	GND	PERxN8	53
54	PETxP9	GND	54

Pin Side B	PCI Express* Signal	PCI Express* Signal	Pin Side A
13	GND	REFCLK+	13
14	PETxP0	REFCLK-	14
15	PETxN0	GND	15
16	GND	PERxP0	16
17	PRSNT2#	PERxN0	17
18	GND	GND	18
19	PETxP1	RSVD	19
20	PETxN1	GND	20
21	GND	PERxP1	21
22	GND	PERxN1	22
23	PETxP2	GND	23
24	PETxN2	GND	24
25	GND	PERxP2	25
26	GND	PERxN2	26
27	PETxP3	GND	27
28	PETxN3	GND	28
29	GND	PERxP3	29
30	RSVD	PERxN3	30
31	PRSNT2#	GND	31
32	GND	RSVD	32
33	PETxP4	RSVD	33
34	PETxN4	GND	34
35	GND	PERxP4	35
36	GND	PERxN4	36
37	PETxP5	GND	37
38	PETxN5	GND	38
39	GND	PERxP5	39
40	GND	PERxN5	40

Pin Side B	PCI Express* Signal	PCI Express* Signal	Pin Side A
55	PETxN9	GND	55
56	GND	PERxP9	56
57	GND	PERxN9	57
58	PETxP10	GND	58
59	PETxN10	GND	59
60	GND	PERxP10	60
61	GND	PERxN10	61
62	PETxP11	GND	62
63	PETxN11	GND	63
64	GND	PERxP11	64
65	GND	PERxN11	65
66	PETxP12	GND	66
67	PETxN12	GND	67
68	GND	PERxP12	68
69	GND	PERxN12	69
70	PETxP13	GND	70
71	PETxN13	GND	71
72	GND	PERxP13	72
73	GND	PERxN13	73
74	PETxP14	GND	74
75	PETxN14	GND	75
76	GND	PERxP14	76
77	GND	PERxN14	77
78	PETxP15	GND	78
79	PETxN15	GND	79
80	GND	PERxP15	80
81	PRSNT2#	PERxN15	81
82	RSVD	GND	82

Table 38. Slot 1 PCI Express* x8 Connector (J1B3)

Pin-Side B	PCI Express* Spec Signal	Description	Pin-Side A	PCI Express* Spec Signal	Description
1	12V		1	Reserved	
2	12V		2	12V	
3	Reserved		3	12V	
4	GND		4	GND	
5	SMCLK		5	JTAG-TCK	
6	SMDATA		6	JTAG-TDI	
7	GND		7	JTAG-TDO	
8	3.3V		8	JTAG-TMS	
9	JTAG-TRST#		9	3.3V	
10	3.3VAux		10	3.3V	
11	Wake#		11	PERST#	
KEY	**KEY**		**KEY**	**KEY**	
KEY	**KEY**		**KEY**	**KEY**	
12	Reserved		12	GND	

Pin-Side B	PCI Express* Spec Signal	Description	Pin-Side A	PCI Express* Spec Signal	Description
13	GND		13	REFCLK1+	
14	PETp(0)		14	REFCLK1+	
15	PETn(0)		15	GND	
16	GND		16	PERp(0)	
17	Reserved		17	PERn(0)	
18	GND	1X end	18	GND	
19	PETp(1)		19	Reserved	
20	PETn(1)		20	GND	
21	GND		21	PERp(1)	
22	GND		22	PERn(1)	
23	PETp(2)		23	GND	
24	PETn(2)		24	GND	
25	GND		25	PERp(2)	
26	GND		26	PERn(2)	
27	PETp(3)		27	GND	
28	PETn(3)		28	GND	
29	GND		29	PERp(3)	
30	Reserved		30	PERn(3)	
31	PRSNT2#		31	GND	
32	GND	4X end	32	Reserved	
33			33	Reserved	
34			34	GND	
35	GND		35		
36	GND		36		
37			37	GND	
38			38	GND	
39	GND		39		
40	GND		40		
41			41	GND	
42			42	GND	
43	GND		43		
44	GND		44		
45			45	GND	
46			46	GND	
47	GND		47		
48	PRSNT2#		48		
49	GND	8X end	49	GND	

7.4.2 VGA Connectors

The following table details the pin-out definition of the external VGA connector (J6A1):

Table 39. VGA External Video Connector (J6A1)

Pin	Signal Name	Description
1	V_IO_R_CONN	Red (analog color signal R)
2	V_IO_G_CONN	Green (analog color signal G)
3	V_IO_B_CONN	Blue (analog color signal B)
4	TP_VID_CONN_B4	No connection
5	GND	Ground
6	GND	Ground
7	GND	Ground

Pin	Signal Name	Description
8	GND	Ground
9	TP_VID_CONN_B9	No connection
10	GND	Ground
11	TP_VID_CONN_B11	No connection
12	V_IO_DDCDAT	DDCDAT
13	V_IO_HSYNC_CONN	HSYNC (horizontal sync)
14	V_IO_VSYNC_CONN	VSYNC (vertical sync)
15	V_IO_DDCCLK	DDCCLK

The following table details the pin-out definition of the internal VGA connector (J1D1):

Table 40. VGA Internal Video Connector (J1D1)

Pin	Signal Name	Pin	Signal Name
1	Red	2	R_RTN(Red Return)
3	Green	4	G_RTN(Green Return)
5	Blue	6	B_RTN(Blue Return)
7	Vsync	8	GND
9	Hsync		GND
11	KEY	12	VIDEO_IN_USE signal
13	DDC_SDA	14	GND
15	DDC_SCL	16	+5V

7.4.3 NIC Connectors

The server board provides two stacked RJ-45 / 2xUSB connectors side-by-side on the back edge of the board (J8A2, J9A1). The pin-out for NIC connectors are identical and are defined in the following table.

Table 41. RJ-45 10/100/1000 NIC Connector Pin-out (J8A2, J9A1)

Pin	Signal Name
1	GND
2	P1V8_NIC
3	NIC_A_MDI3P
4	NIC_A_MDI3N
5	NIC_A_MDI2P
6	NIC_A_MDI2N
7	NIC_A_MDI1P
8	NIC_A_MDI1N
9	NIC_A_MDI0P
10	NIC_A_MDI0N
11 (D1)	NIC_LINKA_1000_N (LED
12 (D2)	NIC_LINKA_100_N (LED)
13 (D3)	NIC_ACT_LED_N
14	NIC_LINK_LED_N
15	GND
16	GND

7.4.4 SATA Connectors

The server board provides up to six SATA / SAS connectors:

- SATA-0 (J9B2)
- SATA-1 (J9B3)
- SATA-2 (J9C1)
- SATA-3 (J9C2)
- SATA-4 (J9B5)
- SATA-5 (J9B4)

The pin configuration for each connector is identical and defined in the following table.

Table 42. SATA Connectors

Pin	Signal Name	Description
1	GND	Ground
2	SATA_TX_P	Positive side of transmit differential pair
3	SATA_TX_N	Negative side of transmit differential pair
4	GND	Ground
5	SATA_RX_N	Negative side of receive differential pair
6	SATA_RX_P	Positive side of receive differential pair
7	GND	Ground

7.4.5 Intel® I/O Expansion Module Connector

The server board provides 2x internal 50-pin Intel® I/O Expansion Module style connector (J2B1, J3B1) to accommodate proprietary form factor Intel® I/O Expansion Modules, which expand the I/O capabilities of the server board without sacrificing an add-in slot from the riser cards. There are multiple Intel® I/O Expansion Modules for use on this server board. For more information on the supported Intel® I/O Expansion Modules, refer to the *Intel® Server Board IO Module Hardware Specification*. The following table details the pin-out of the Intel® I/O Expansion Module connectors.

Table 43. 50-pin Intel® I/O Expansion Module Connector Pin-out (J2B1, J3B1)

Pin	Signal Name	Pin	Signal Name
1	P3V3_AUX	2	P3V3_AUX
3	PE_RST_IO_MODULE_N	4	GND
5	GND	6	PE2_ESB_RXP_C<0>
7	GND	8	PE2_ESB_RXN_C<0>
9	PE2_ESB_TXP_C<0>	10	GND
11	PE2_ESB_TXN_C<0>	12	GND
13	GND	14	PE2_ESB_RXP_C<1>
15	GND	16	PE2_ESB_RXN_C<1>
17	PE2_ESB_TXP_C<1>	18	GND
19	PE2_ESB_TXN_C<1>	20	GND
21	GND	22	PE2_ESB_RXP_C<2>
22	GND	24	PE2_ESB_RXN_C<2>
25	PE2_ESB_TXP_C<2>	26	GND
27	PE2_ESB_TXN_C<2>	28	GND
29	GND	30	PE2_ESB_RXP_C<3>
31	GND	32	PE2_ESB_RXN_C<3>
33	PE2_ESB_TXP_C<3>	34	GND
35	PE2_ESB_TXN_C<3>	36	GND
37	GND	38	CLK_100M_LP_PCIE_SLOT3_P
39	GND	40	CLK_100M_LP_PCIE_SLOT3_N
41	PE_WAKE_N	42	GND
43	P3V3	44	P3V3
45	P3V3	46	P3V3
47	P3V3	48	P3V3
49	P3V3	50	P3V3

7.4.6 Serial Port Connectors

The server board provides one external RJ-45 Serial A port (J7A1) and one internal 9-pin serial B header (J1A2). The following tables define the pin-outs.

Table 44. External RJ-45 Serial Port A (COM1) (J7A1)

Pin	Signal Name	Pin	Signal
1	SPA_RTS	5	SPA_RI
2	SPA_DTR	6	SPA_SIN
3	SPA_SOUT_N	7	SPA_DSR
4	GND	8	SPA_CTS

Table 45. Internal 9-pin Serial B (COM2) (J1A2)

Pin	Signal Name	Pin	Signal Name
1	SPB_DCD	2	SPB_DSR
3	SPB_SIN_N	4	SPB_RTS
5	SPB_SOUT_N	6	SPB_CTS
7	SPB_DTR	8	SPB_RI
9	GND		

7.4.7 USB Connectors

The following table details the pin-out of the external USB connectors (J7A1, J7A2) found on the back edge of the server board and the internal connector (J9D3) centered on the right side of the board.

Table 46. External USB Connector (J8A1, J9A1))

Pin	Signal Name	Description
1	+5V	USB Power
2	USB_N	Differential data line paired with DATAH0
3	USB_P	Differential date line paired with DATAL0
4	GND	Ground

Two 2x5 connectors on the server board provide an option to support an additional four USB ports. The pin-out is the same for both of the connectors and is detailed in the following table.

Table 47. Internal USB Connector (J1C1 and J9A2)

Pin	Signal Name	Pin	Signal Name
1	+5V	2	+5V
3	USB_N	4	USB_N
5	USB_P	6	USB_P
7	GND	8	GND
9	Key Pin	10	NC

One low-profile 2x5 connectors (J1D4) on the server board provides an option to support low-profile USB based embedded flash devices. The pin-out of the connector is detailed in the following table.

Table 48. Low-Profile Internal USB Connector (J1E3)

Pin	Signal Name	Pin	Signal Name
1	+5V	2	NC
3	USB_N	4	NC
5	USB_P	6	NC
7	GND	8	NC
9	Key Pin	10	LED#

7.5 Fan Headers

The server board provides six SSI-compliant 4-pin fan headers and two 8-pin fan headers to be used for CPU, and IO cooling. The pin configuration for each of the 4-pin fan headers is identical and defined in the following tables.

Table 49. SSI 4-pin Fan Connector (J2K2, J2K3, J3K1, J7K1, J8K4, J8K5)

Pin	Signal Name	Description
1	GND	Ground
2	12V	Power Supply 12V
3	TACH IN	FAN_TACH signal is connected to the BMC to monitor the fan speed
4	PWM OUT	FAN_PWM signal to control fan speed

Table 50. 8-pin Fan Connector (J2K1 & J8K3)
(MOLEX CONNECTOR CORPORATION 53398-0890 or 53398-0871)

Pin	Signal Name
1	GND
2	12V
3	Tach0
4	PWM0
5	GND
6	12V
7	Tach1
8	PWM1

8. Intel® Light-Guided Diagnostics

The server boards have several onboard diagnostic LEDs to assist in troubleshooting board-level issues. This section provides a description the location and function of each LED on the server board.

8.1 5-V Standby LED

Several server management features of this server board require a 5-V stand-by voltage is supplied from the power supply. Some of the features and components that require this voltage must be present when the system is "Off" include the Integrated BMC, onboard NICs, and optional RMM3 connector with Intel® RMM3 installed.

The LED is located in the lower-left corner of the server board and is labeled "5VSB_LED" is illuminated when AC power is applied to the platform and 5-V standby voltage is supplied to the server board by the power supply.

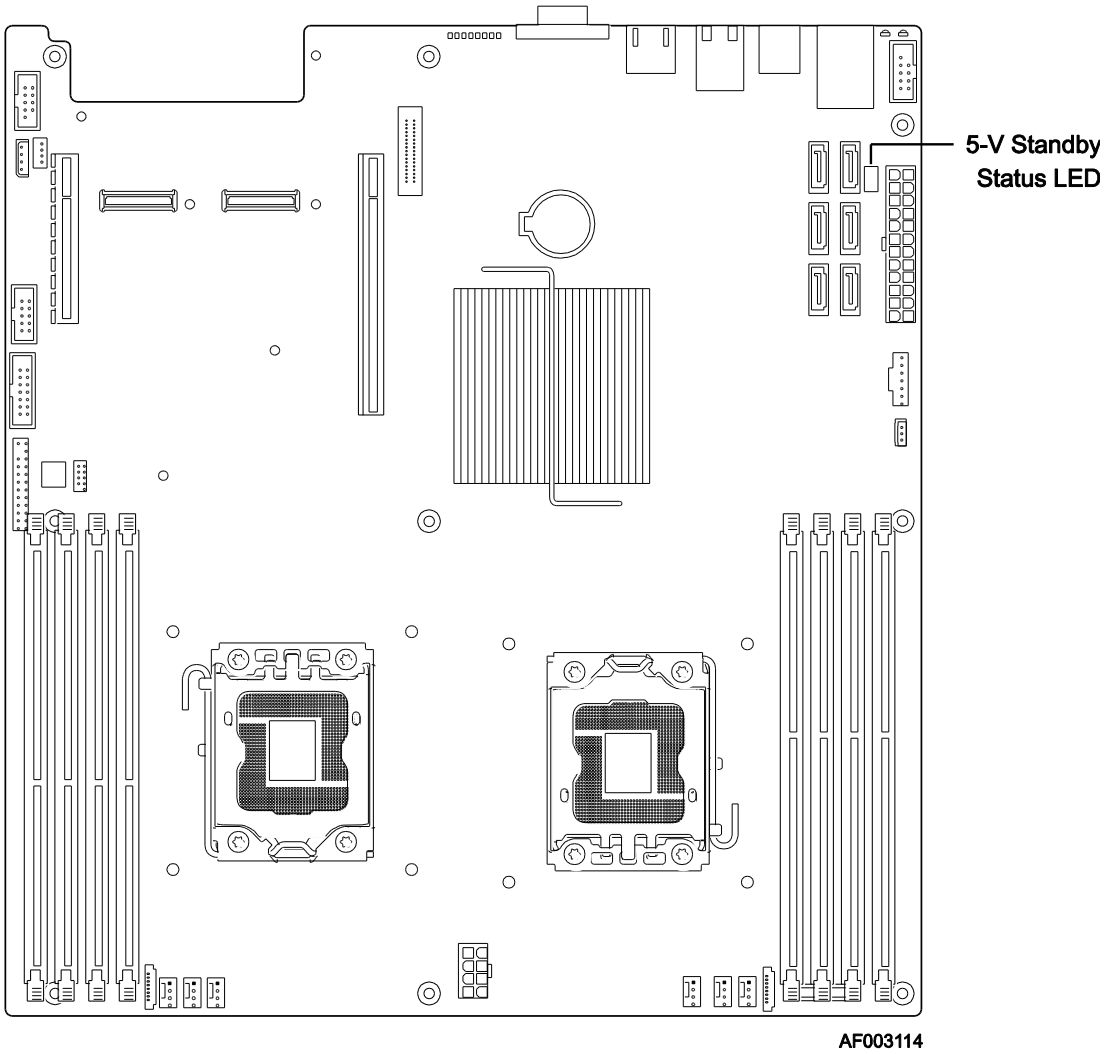
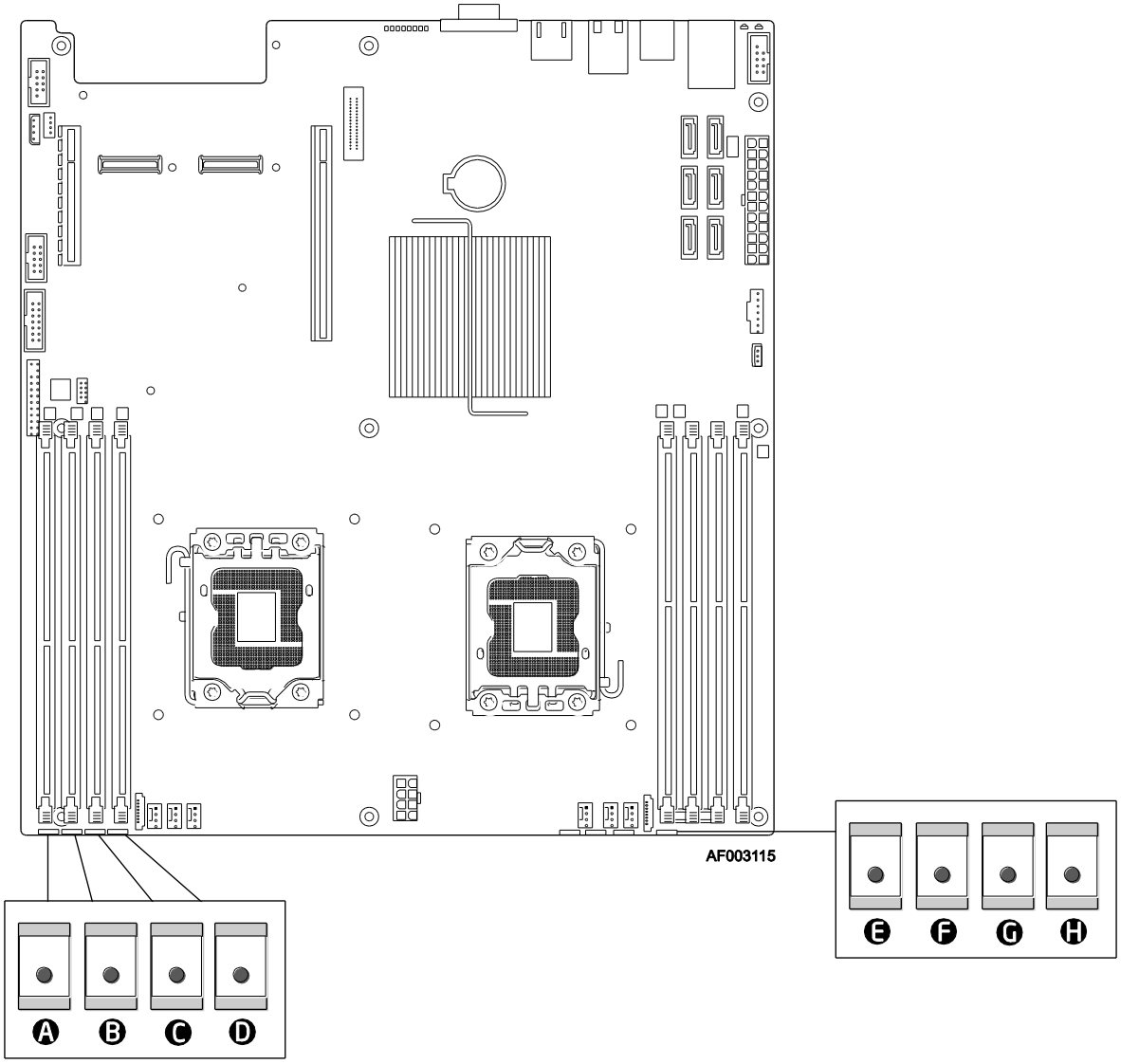


Figure 22: 5-V Standby Status LED Location

8.2 Fan Fault LEDs

Fan fault LEDs are present for the six fans and are located near each CPU fan header.



A	FLTMEM2R	E	FLTCPU1
B	FLTMEM2	F	FLTCPU1A
C	FLTCPU2A	G	FLTMEM1
D	FLTCPU2	H	FLTMEM1R

Figure 23. Fan Fault LED Locations

8.3 System Status LED

The server board provides LED for system status. The following figure shows the LED location.

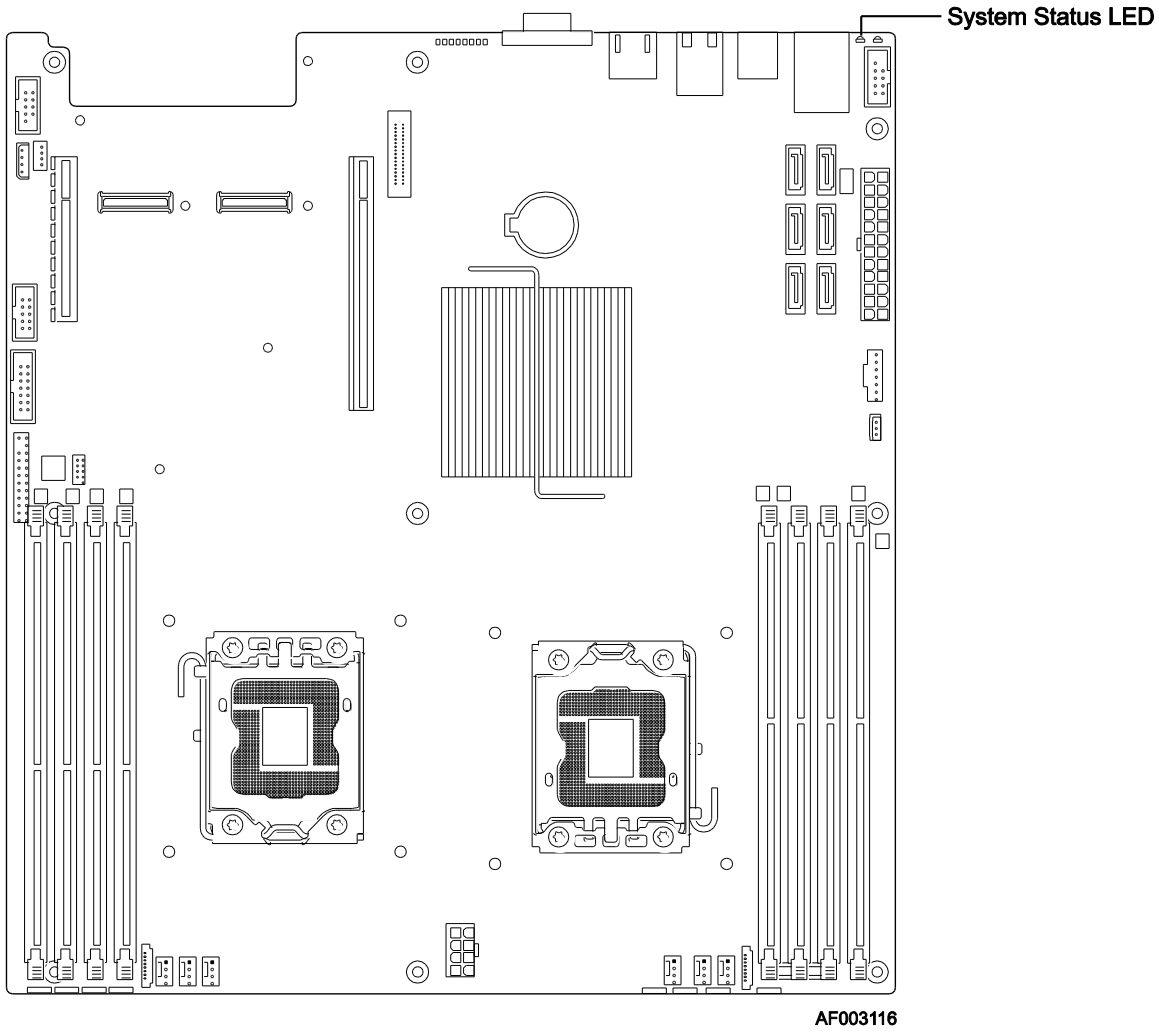


Figure 24. System Status LED Location

The bi-color System Status LED operates as follows:

Table 51. System Status LED

Color	State	System Status	Description
Green	Solid on	Ok	System ready
Green	~1 Hz blink	Degraded	System degraded: **BIOS detected** 1. Unable to use all of the installed memory (more than one DIMM installed).1 2. In a mirrored configuration, when memory mirroring takes place and system loses memory redundancy. This is not covered by (2). 1 3. PCI Express* correctable link errors. **Integrated BMC detected** 1. Redundancy loss such as a power supply or fan. Applies only if the associated platform subsystem has redundancy capabilities. 2. CPU disabled – if there are two CPUs and one CPU is disabled. 3. Fan alarm – Fan failure. Number of operational fans should be more than minimum number needed to cool the system. 4. Non-critical threshold crossed – Temperature, voltage, power nozzle, power gauge, and PROCHOT2 (Therm Ctrl) sensors. 5. Battery failure. 6. Predictive failure when the system has redundant power supplies.
Amber	~1 Hz blink	Non-Fatal	Non-fatal alarm – system is likely to fail: **BIOS Detected** 1. In non-mirroring mode, if the threshold of ten correctable errors is crossed within the window.1 2. PCI Express* uncorrectable link errors. **Integrated BMC Detected** 1. Critical threshold crossed – Voltage, temperature, power nozzle, power gauge, and PROCHOT (therm Ctrl) sensors. 2. VRD Hot asserted. 3. The minimum number of fans required to cool the system are not present or have failed.

Color	State	System Status	Description
Amber	Solid on	Fatal	Fatal alarm – system has failed or shut down: **BIOS Detected** 1. DIMM failure when there is one DIMM present and no good memory is present.1 2. Run-time memory uncorrectable error in non-redundant mode.1 3. CPU configuration error (for instance, processor stepping mismatch). **Integrated BMC Detected** 1. CPU IERR signal asserted. 2. CPU 1 is missing. 3. CPU THERMTRIP. 4. No power good – power fault. 5. Power Unit Redundancy sensor – Insufficient resources offset (indicates not enough power supplies are present).
Off	N/A	Not ready	AC power off

Notes:

1. The BIOS detects these conditions and sends a *Set Fault Indication* command to the Integrated BMC to provide the contribution to the system status LED.
2. Support for an upper, non-critical threshold limit is not provided in default SDR configuration. However if a user does enable this threshold in the SDR, then the system status LED should behave as described.

8.4 DIMM Fault LEDs

Each DIMM slot has a DIMM Fault LED near the DIMM slot.

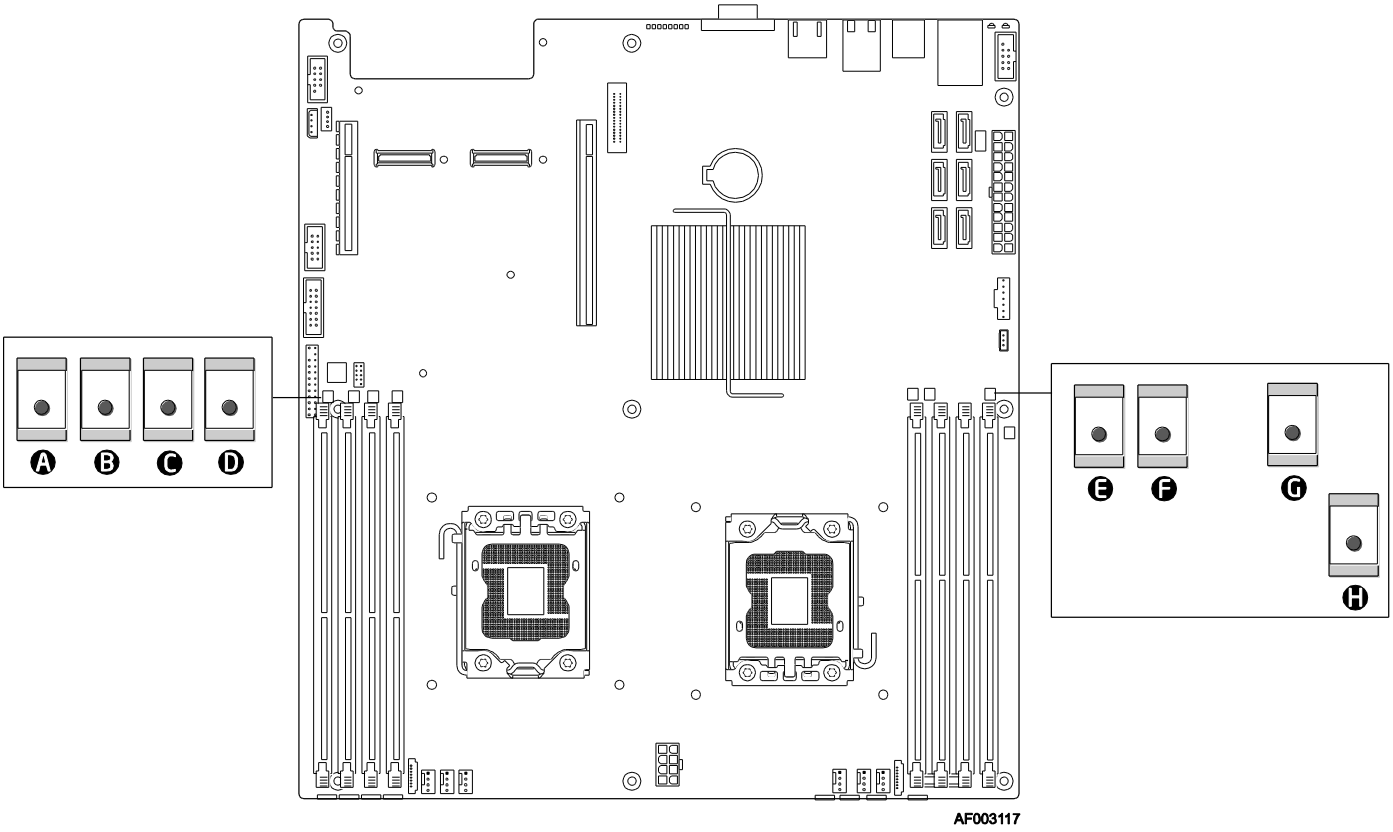


Figure 25. DIMM Fault LEDs Locations

A	FLT_F	E	FLT_A2
B	FLT_E	F	FLT_A1
C	FLT_D1	G	FLT_B
D	FLT_D2	H	FLT_C

8.5 POST Code Diagnostic LEDs

Eight amber POST code diagnostic LEDs are located on the back edge of the server board in the rear I/O area of the server board by the VGA connector.

During the system boot process, the BIOS executes a number of platform configuration processes, each of which is assigned a specific hex POST code number. As each configuration routine is started, the BIOS displays the given POST code to the POST code diagnostic LEDs on the back edge of the server board. To assist in troubleshooting a system hang during the POST process, you can use the Diagnostic LEDs to identify the last POST process executed. For a complete description of how these LEDs are read and a list of all supported POST codes, refer to Appendix A.

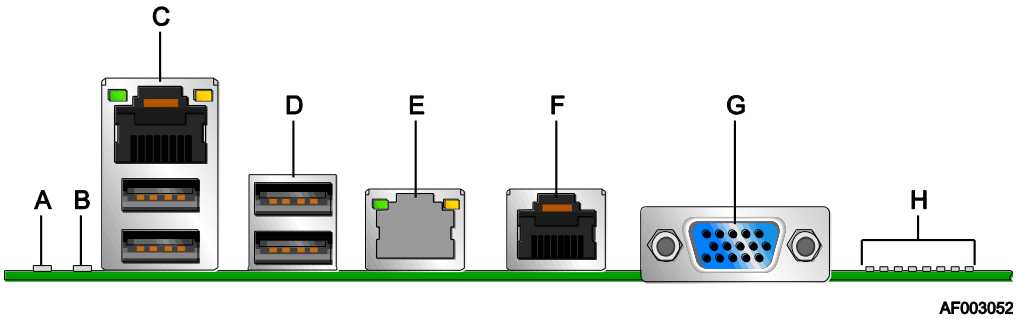


Figure 26. Rear Panel Diagnostic LEDs

	Description		Description
A	ID LED	E	RJ-45 GbE LAN connector
B	Status LED	F	RJ-45 Serial port connector
C	RJ-45 GbE/Dual USB connector	G	DB15 Video
D	Dual USB connector	H	Diagnostic LEDs

8.6 Front Panel Support

The Intel® Server Board S5500WB supports SSI standard front panel boards. The front panel support is provided by a SSI compatible 2x12-pin signal connector. The front panel connector supports the following diagnostic LEDs.

Table 52. Standard Front Panel Functionality

LED	Color	Condition	What It Means
Power/Sleep	Green	On	Power on or S0 sleep
	Green	Blink	S1 sleep
		Off	Off (also sleep S5 modes)
Status	Green	On	System ready/No alarm
	Green	Blink	System ready, but degraded: redundancy lost such as power supply or fan failure; non-critical temp/voltage threshold; battery failure; or predictive PS failure.
	Amber	On	Critical alarm: Voltage, thermal, or power fault; CPU1 missing; insufficient power unit redundancy resource offset asserted
	Amber	Blink	Non-Critical failure: Critical temp/voltage threshold; VDR hot asserted; min number fans not present or failed
		Off	AC power off: System unplugged AC power on: System powered off and in standby, no prior degraded\non-critical\critical state
HDD	Green	Blink	HDD access
	Amber	Not Supported	HDD fault
	Amber	Not Supported	Predictive failure, rebuild, identify
		Off	No access
LAN #1 - Activity	Green	On	LAN link/ no access
	Green	Blink	LAN access
		Off	Idle
LAN #2 - Activity	Green	On	LAN link/ no access
	Green	Blink	LAN access
		Off	Idle
Identification	Blue	On	Front panel chassis ID button pressed
	Blue	Blink	Unit selected for identification via software
		Off	No identification

9. Design and Environmental Specifications

9.1 Fan Speed Control Thermal Management

Fan speed control supports the following thermal sensors:

- Discrete board level digital thermal sensor TMP75
- Front panel Temp Sensor (if present)
- CPU PECI DTS
- DDR3 RDIMM TSOD

Eight front system fan headers for four individual thermal zones

- Zone 4 (mem2 fans) responds to memory2 and CPU2 temperatures.
- Zone 3 (CPU2 and MEM2 fans) responds to CPU2 and IOH temperatures.
- Zone 2 (CPU1 and MEM1 fans) responds to CPU1 and IOH temperatures.
- Zone 1 (mem1 fans) responds to memory1 and CPU1 temperatures.

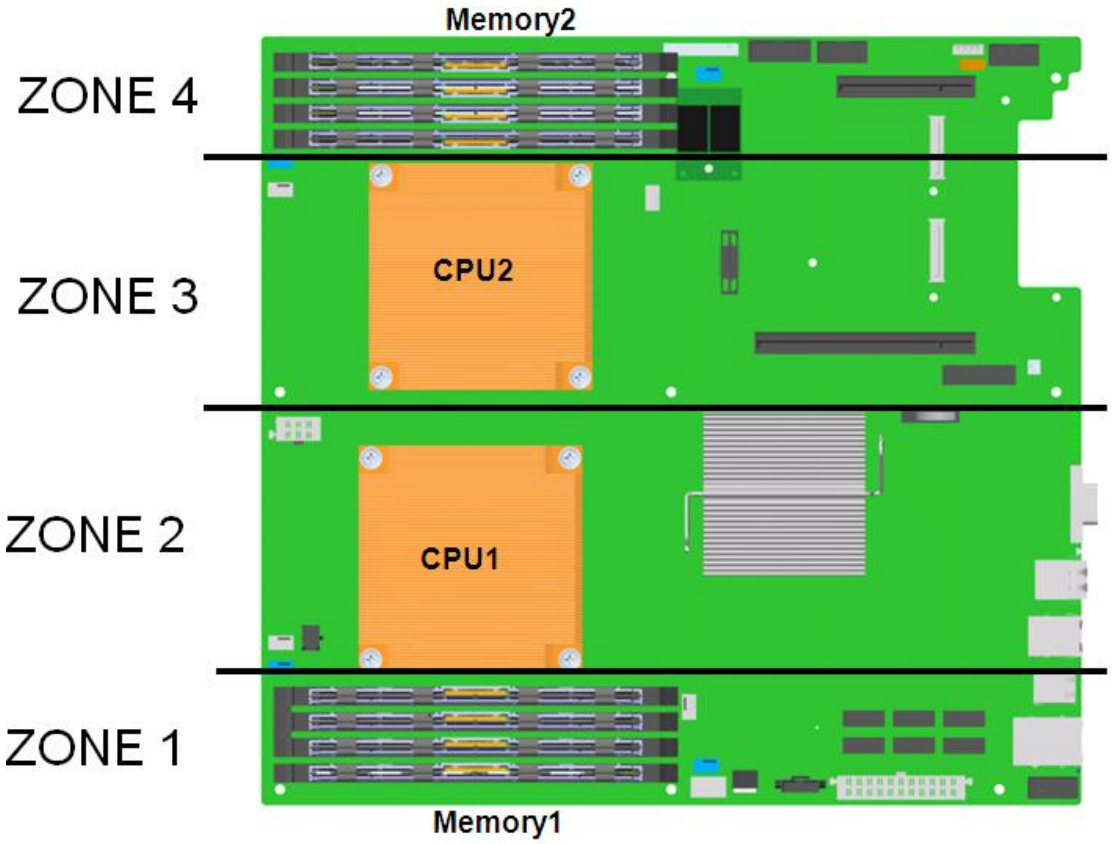


Figure 27: Thermal Zones

The following tables show a basic location of the fan connectors on the board. The first line is the silk screen name of the connector; the second is the PWM signal name; the third is the Tach #; and the forth is the reference description. The last is the signal name associated with the fault LED signal.

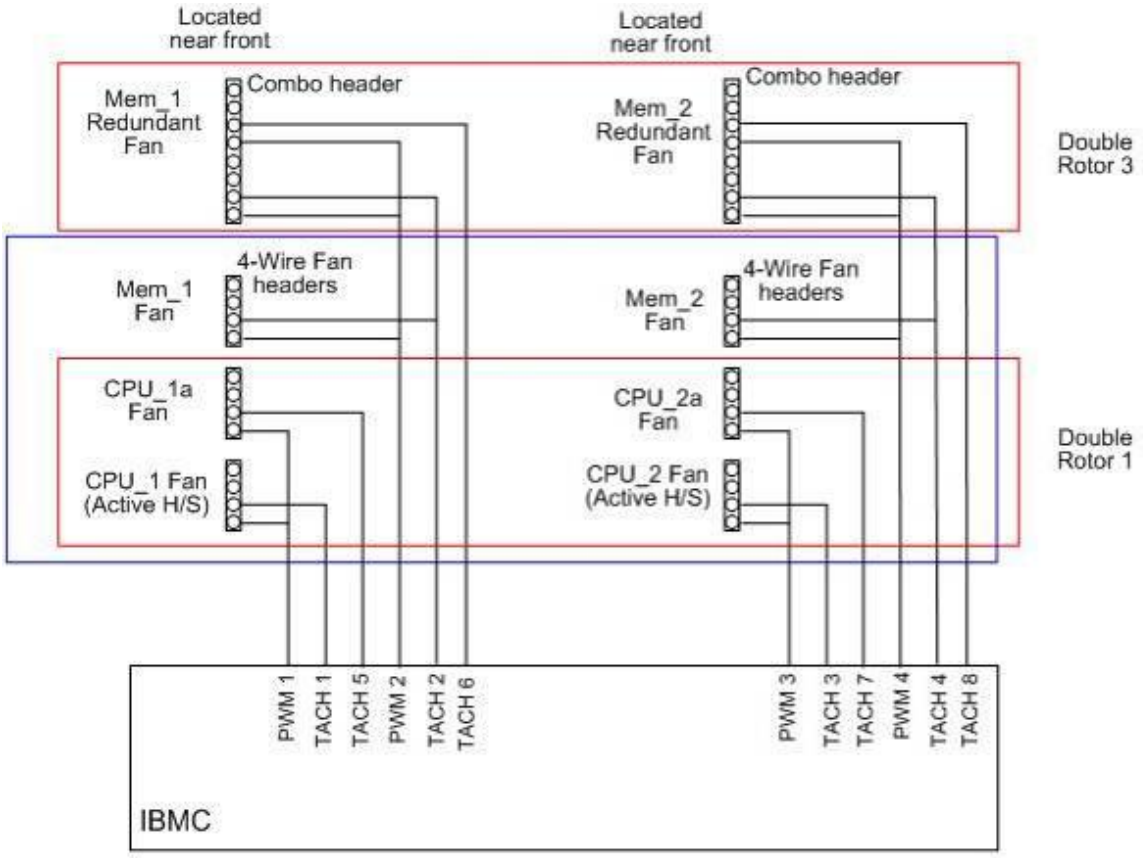


Figure 28: Location of Fan Connectors

Table 53. Fan Connector Location & Detail

CPU 1		Memory 1	
FAN_CPU1	FAN_CPU1A	FAN_MEM1	FAN_MEM1R
PWM_CPU1	PWM_CPU1	PWM_MEM1	PWM_MEM1
Tach 1	Tach 5	Tach 2	Tach 2 & 6
J8E1	J8J4	J8J3	J9E1
LED_Fan_Fault_CPU1	LED_Fan_Fault_CPU1A	LED_Fan_Fault_MEM1	LED_Fan_Fault_MEM1R

Table 54. Fan Connector Location & Detail

CPU 2		Memory 2	
FAN_CPU2	FAN_CPU2A	FAN_MEM2	FAN_MEM2R
PWM_CPU0	PWM_CPU0	PWM_MEM0	PWM_MEM0
Tach 3	Tach 7	Tach 4	Tach 4 & 8
J3E1	J2J2	J2J1	J1D5
LED_Fan_Fault_CPU0	LED_Fan_Fault_CPU0A	LED_Fan_Fault_MEM0	LED_Fan_Fault_MEM0R

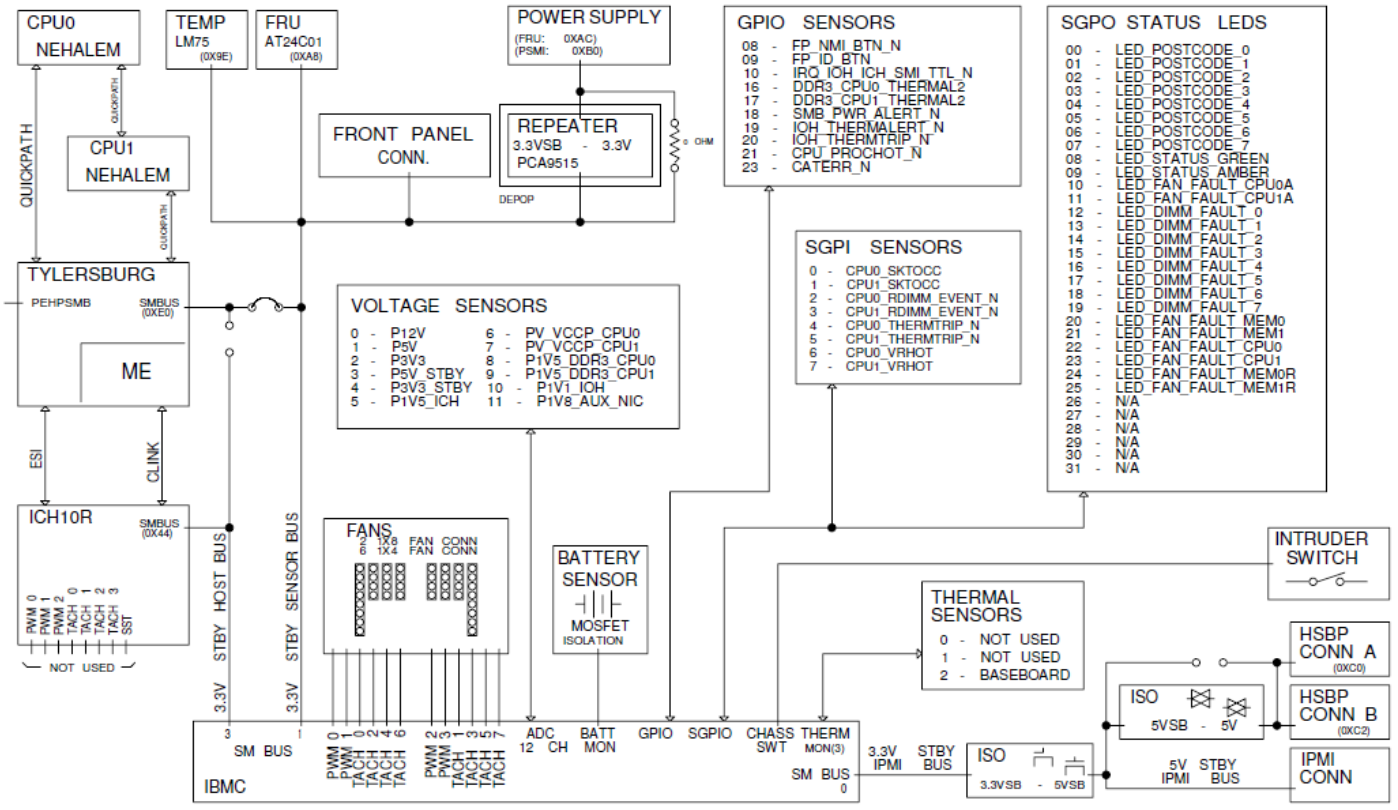


Figure 29. Fans and Sensors Block Diagram

9.2 Thermal Sensors

9.2.1 Processor PECI Temperature Sensor

The processor thermal control uses a CPU PECI thermal sensor, which is a relative temperature off PROCHOT# trip point (a -20C reading means 20C below PROCHOT# trip point temperature). The BMC can get the processor PECI Tcontrol values for each CPU installed to use/follow the clamped algorithm for component thermal sensor. The following sample SDR settings could be used:

- Use Tcontrol (byte 8, bit 0 = 1): Tcontrol value is provided by BIOS via the *Set CPU TControl* command for the indicated CPU is used.

- Tcontrol offset Temperature = -2° C
- Pos_hyst = 0° C
- Neg_hyst = 3° C

Those parameters in turn set the following:

- Upper = - CPU PECI Tcontrol + Tcontrol offset
- Lower = - CPU PECI Tcontrol + Tcontrol offset – 3C

9.2.2 Memory Temperature Sensor

DDR3 cooling requires thermal throttling to protect memory from overheating. The Intel® Server Board S5500WB supports both DDR3 UDIMM and DDR3 RDIMM. SPD temperature sensor on DIMM is anticipated to be available on all DDR3 RDIMM but not for non-ECC UDIMM, so open loop thermal throttling and closed loop thermal throttling are supported.

- **Static open loop thermal throttling**: The system does not change any of the control registers in the processor during runtime. OLTT control registers are configured by BIOS MRC and remain fixed after post.
- **Static closed loop thermal throttling**: The system does not change the control registers for a closed loop in the processor during runtime. CLTT control registers are configured by BIOS MRC.

For advanced implementation with dynamic OLTT and CLTT, refer to the VR_Hot Sensor in VR11.1.

9.2.3 Board Temperature Sensor

For rack-based systems or those systems that do not have a front panel temp sensor, the board is enabled to use a board-mounted, industry standard **TMP75** type temp sensor. This part is on the IBMC two-wire serial SENSOR bus. The use of digital parts removes calibration and placement location issues imposed by the alternate analog type sensors.

9.2.4 Thermals Sensor Placement

The I2C\SMBUS based temp sensors are placed such that the ambient air temp can be measured. Placement near hot components and or downstream of hot components (including chassis-based hot spots) is avoided. The following figure shows the sensor placement on the Intel® Server Board S5500WB.

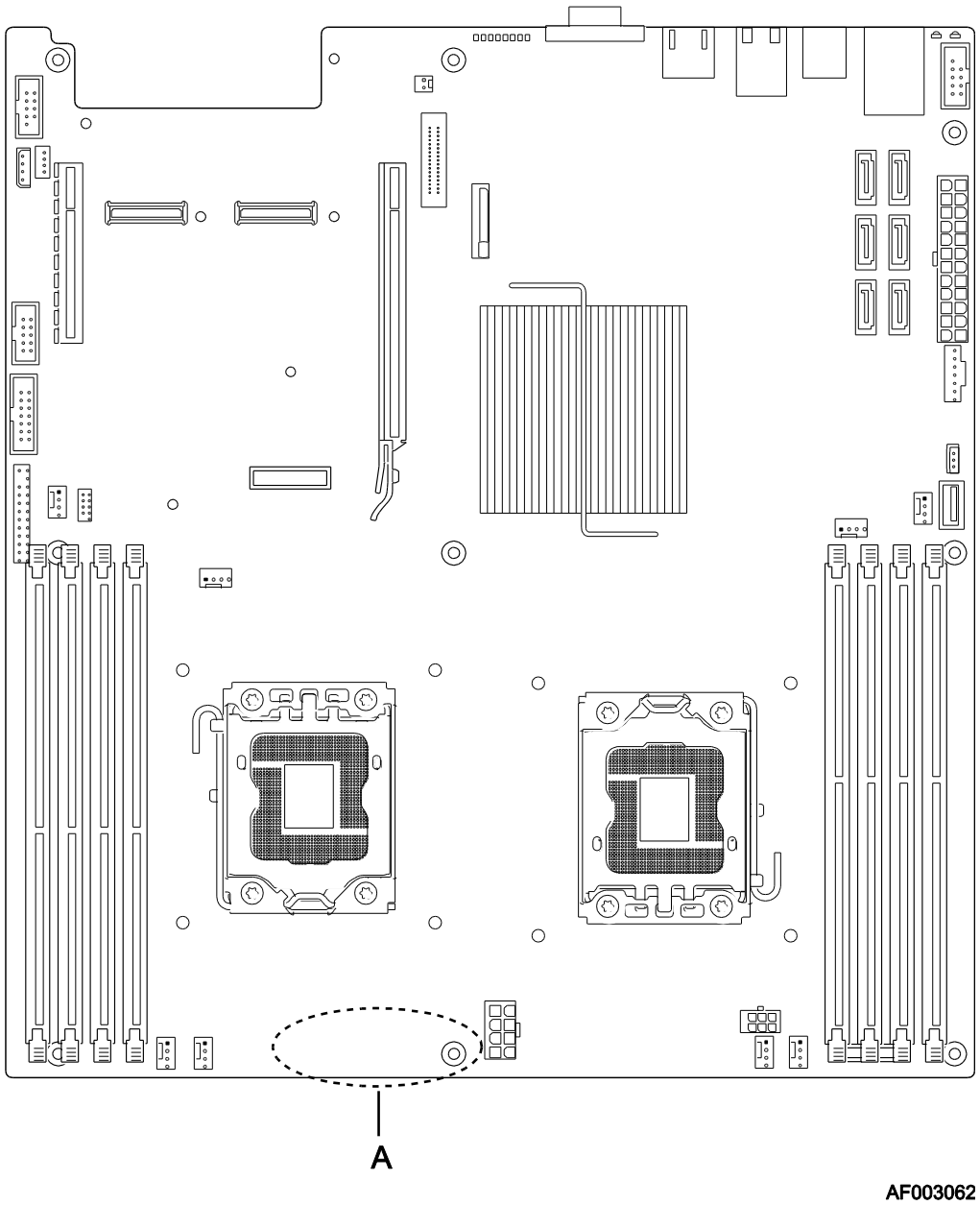


Figure 30: Temp Sensor Location

	Location	Description
A	U4K3	Temp Sensor - TMP75

9.3 Heatsinks

The Intel® Server Board S5500WB system cooling solutions rely on heatsinks for CPU cooling.

Chipset and or voltage regulator heatsinks are compatible with the 1U usage.

Note: The Intel® Thermal Solution STS100P – Passive 1U/2U heatsink was tested for processors up to and including 95-W TDP (Thermal Design Power). Product order code: BXSTS100P

9.3.1 Unified Retention System Support

The server board complies with the Intel® Unified Retention System (URS) and the Unified Backplate Assembly. The server board ships with a made-up assembly of Independent Loading Mechanism (ILM) and Unified Backplate at each processor socket.

The URS retention transfers load to the server board via the unified backplate assembly. The URS spring, captive in the heatsink, provides the necessary compressive load for the thermal interface material. All components of the URS heatsink solution are captive to the heatsink and only require a Philips* screwdriver to attach to the unified backplate assembly. See the following figure for the stacking order of the URS components.

The ILM and unified backplate are removable, allowing for the use of non-Intel heatsink retention solutions.

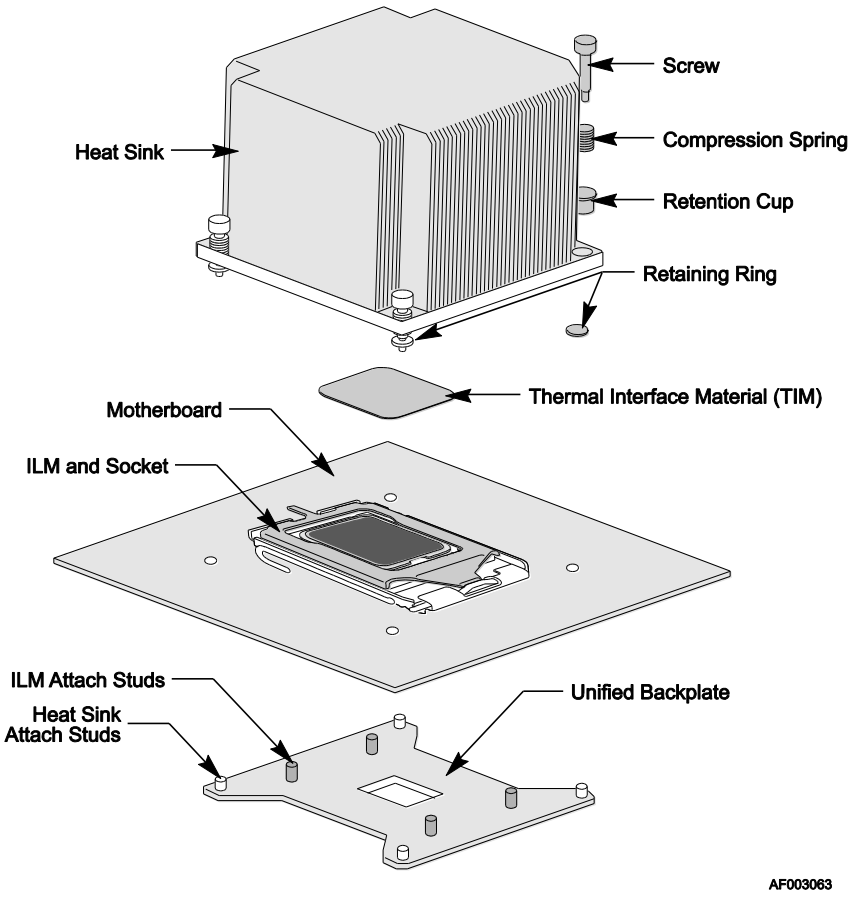


Figure 31. Unified Retention System and Unified Backplate Assembly

9.4 Errors

This section outlines how errors are routed in the hardware to ensure appropriate FW action (logging, fan control, system management, and so forth) is taken when an event occurs.

9.4.1 PROCHOT#

PROCHOT# is a bi-directional signal. The CPU toggles PROCHOT# when it goes into throttling mode. The duty cycle of PROCHOT# toggling indicates the amount of throttling initiated by the CPU. FW does not monitor PROCHOT# to determine CPU throttling percentage. Instead, it obtains outbound CPU throttling data via PECI. The path between the CPU's and IBMC (TTL_CPU_PROCHOT#) is there as a backup.

An external source can also toggle PROCHOT# to force the CPU to go into throttling mode. This usually happens when the system reaches a certain thermal threshold. VRHOT is an output of the CPU VR controller, which is capable of throttling the CPU via PROCHOT#. Some simple masking circuitry is required to prevent the VRHOT from asserting the PROCHOT# to the CPUs at the time of CPU_RST#. This keeps the VRHOT from unintentionally causing the CPU to disable. FW monitors VRHOT and creates a SEL event if VRHOT is asserted. There is no fan action as a result of the BMC seeing VRHOT.

9.4.2 THERMTRIP#

THERMTRIP# comes from the CPU. The THERMTRIP# signal is tied to a unique GPI on IBMC for FW to monitor. The combined THERMTRIP#'s from both CPUs is also tied to the ICH10R THERMTRIP input to cause an automatic Power Off condition when activated.

9.4.3 CATERR#

The CATERR# signal from the CPU signals a catastrophic error occurred. CATERR# may signal two types of issues. One type is a warning and is indicated by a pulse on the signal. The other is the static critical error, which is indicated by a continuously asserted level on the signal. The BMC only logs the static Critical Error events and ignores the warnings indicated by the pulse. An error on the CPU is immediately communicated to the ICH10R for notification.

10. Power Subsystem

10.1 Server Board Power Distribution

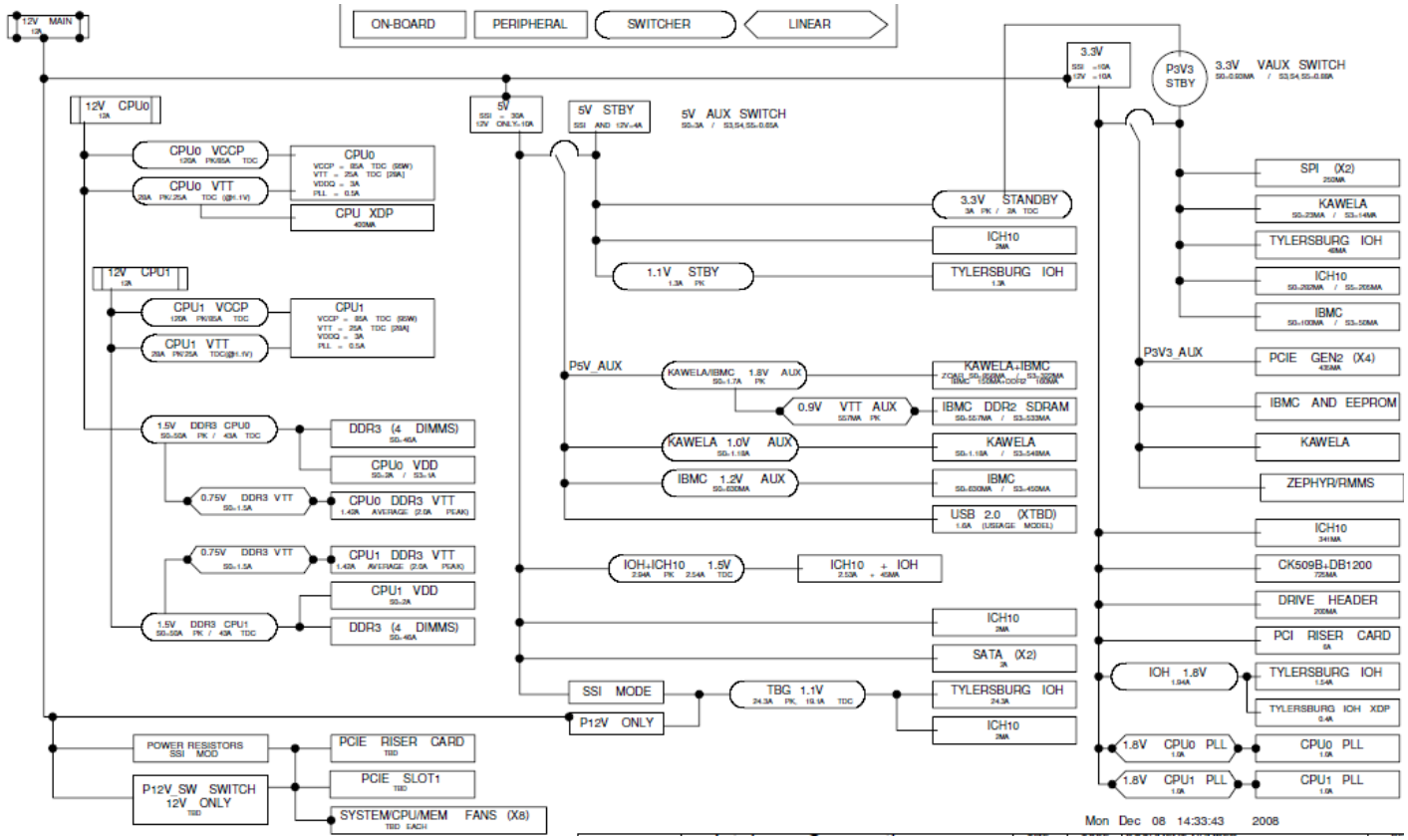


Figure 32. Power Distribution Diagram

10.2 Power Supply Compatibility

The Intel® Server Board S5500WB is offered in two models:

- SSI SKU: This version of the server board is designed to work with an “off-the-shelf” multi-rail power supply that adheres to the SSI power specification: “Power Supply Design Guideline for 2008 Dual-Socket Servers and Workstations”. You can view SSI specifications at the following website http://ssiforum.org.

- 12V SKU: This version of the server board is designed to work with specially-designed “single rail” power supplies that provide 12V and 5V standby current. The server board has integrated, high-efficiency voltage regulators that produce other voltages required (for example, 3.3 V, 5 V, and so forth) and can also supply 5 V power required by hard drives.

The SSI uses the standard 24-pin and 8-pin power headers along with the 5pin Control connector. The 12-V only uses two 8-pin power headers, a 7-pin control header and a 6 pin HDD power connector. For maximum rack server efficiency, a DC 12-V only power supply is recommended. Appendix A shows connector pin outs.

PMbus communications between the power supply and server board must comply with both SMBus and I2C Bus timing requirements.

10.3 Power Sequencing and Reset Distribution

The IBMC device is integrated into the power control and reset logic of the system. This design reduces the discrete logic requirements of previous generations and at the same time permits FW to manage certain features related to the power on/off control and the reset logic.

11. Regulatory and Certification Information

11.1 Product Regulation Requirements

Intended Application – This product was evaluated as Information Technology Equipment (ITE), which may be installed in offices, schools, computer rooms, and similar commercial type locations. The suitability of this product for other product categories and environments (such as: medical, industrial, telecommunications, NEBS, residential, alarm systems, test equipment), other than an ITE application, may require further evaluation. This is an FCC Class A device. Integration of it into a Class B chassis does not result in a Class B device.

11.1.1 Product Safety Compliance

The Intel® Server Board S5520UR complies with the following safety requirements:

- UL60950 – CSA 60950(USA / Canada)
- EN60950 (Europe)
- IEC60950 (International)
- CB Certificate & Report, IEC60950 (report to include all country national deviations)
- GOST R 50377-92 – Listed on one System Certification (Russia)
- Belarus Certification – Listed on System Certification (Belarus)
- CE - Low Voltage Directive 73/23/EEE (Europe)
- IRAM Certification (Argentina)

11.1.2 Product EMC Compliance – Class A Compliance

- FCC /ICES-003 - Emissions (USA/Canada) Verification
- CISPR 22 – Emissions (International)
- EN55022 - Emissions (Europe)
- EN55024 - Immunity (Europe)
- CE – EMC Directive 89/336/EEC (Europe)
- AS/NZS 3548 Emissions (Australia / New Zealand)
- VCCI Emissions (Japan)
- BSMI CNS13438 Emissions (Taiwan)
- GOST R 29216-91 Emissions - Listed on one System Certification (Russia)
- GOST R 50628-95 Immunity –Listed on one System Certification (Russia)
- Belarus Certification – Listed on one System Certification (Belarus)
- KCC (EMI) (Korea)

11.1.3 Certifications / Registrations / Declarations

- NRTL Certification (US/Canada)
- CE Declaration of Conformity (CENELEC Europe)
- FCC/ICES-003 Class A Attestation (USA/Canada)
- C-Tick Declaration of Conformity (Australia)
- MED Declaration of Conformity (New Zealand)

- BSMI Certification (Taiwan)
- GOST – Listed on one System Certification (Russia)
- Belarus – Listed on one System Certification (Belarus)
- KCC Certification (Korea)
- Ecology Declaration (International)

11.2 Product Regulatory Compliance Markings

This Intel Server Board bears the following regulatory marks:

Table 55: Product Regulatory Compliance Markings

Regulatory Compliance	Country	Marking
UL Mark	USA/Canada	
CE Mark	Europe	
FCC Marking (Class A)	USA	This device complies with Part 15 of the FCC Rules. Operation of this device is subject to the following two conditions: (1) This device may not cause harmful interference, and (2) This device must accept any interference received, including interference that may cause undesired operation. Manufactured by Intel Corporation
EMC Marking (Class A)	Canada	CANADA ICES-003 CLASS A CANADA NMB-003 CLASSE A
BSMI Marking (Class A)	Taiwan	 警告使用者： 這是甲類的資訊產品，在居住的環境中使用時，可能會造成射頻干擾，在這種情況下，使用者會被要求採取某些適當的對策
KCC Mark	Korea	 방송통신위원회

11.3 Electromagnetic Compatibility Notices

11.3.1 FCC Verification Statement (USA)

This device complies with Part 15 of the FCC Rules. Operation is subject to the following two conditions: (1) this device may not cause harmful interference, and (2) this device must accept any interference received, including interference that may cause undesired operation.

For questions related to the EMC performance of this product, contact:

Intel Corporation
5200 N.E. Elam Young Parkway
Hillsboro, OR 97124-6497
1-800-628-8686

This equipment has been tested and found to comply with the limits for a Class A digital device, pursuant to Part 15 of the FCC Rules. These limits are designed to provide reasonable protection against harmful interference in a residential installation. This equipment generates, uses, and can radiate radio frequency energy and, if not installed and used in accordance with the instructions, may cause harmful interference to radio communications. However, there is no guarantee that interference will not occur in a particular installation. If this equipment does cause harmful interference to radio or television reception, which can be determined by turning the equipment off and on, the user is encouraged to try to correct the interference by one or more of the following measures:

- Reorient or relocate the receiving antenna.
- Increase the separation between the equipment and the receiver.
- Connect the equipment into an outlet on a circuit different from that to which the receiver is connected.
- Consult the dealer or an experienced radio/TV technician for help.

Any changes or modifications not expressly approved by the grantee of this device could void the user's authority to operate the equipment. The customer is responsible for ensuring compliance of the modified product.

Only peripherals (computer input/output devices, terminals, printers, etc.) that comply with FCC Class A or B limits may be attached to this computer product. Operation with noncompliant peripherals is likely to result in interference to radio and TV reception.

All cables used to connect to peripherals must be shielded and grounded. Operation with cables, connected to peripherals that are not shielded and grounded may result in interference to radio and TV reception.

11.3.2 ICES-003 (Canada)

Cet appareil numérique respecte les limites bruits radioélectriques applicables aux appareils numériques de Classe Aprescrites dans la norme sur le matériel brouilleur: "Appareils Numériques", NMB-003 édictée par le Ministre Canadian des Communications.

English translation of the notice above:

This digital apparatus does not exceed the Class A limits for radio noise emissions from digital apparatus set out in the interference-causing equipment standard entitled "Digital Apparatus," ICES-003 of the Canadian Department of Communications.

11.3.3 Europe (CE Declaration of Conformity)

This product has been tested in accordance too, and complies with the Low Voltage Directive (73/23/EEC) and EMC Directive (89/336/EEC). The product has been marked with the CE Mark to illustrate its compliance.

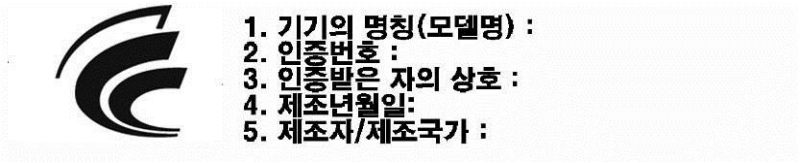
11.3.4 BSMI (Taiwan)

The BSMI Certification Marking and EMC warning is located on the outside rear area of the product.

警告使用者：
這是甲類的資訊產品，在居住的環境中使用時，可能會造成射頻干擾，在這種情況下，使用者會被要求採取某些適當的對策

11.3.5 KCC (Korea)

Following is the KCC certification information for Korea.



English translation of the notice above:

1. Type of Equipment (Model Name): On Certification and Product
2. Certification No.: On KCC certificate. Obtain certificate from local Intel representative
3. Name of Certification Recipient: Intel Corporation
4. Date of Manufacturer: Refer to date code on product
5. Manufacturer/Nation: Intel Corporation/Refer to country of origin marked on product

Appendix A: POST Code LED Decoder

During the system boot process, the BIOS executes several platform configuration processes, each of which is assigned a specific hex POST code number. As each configuration routine is started, the BIOS displays the POST code on the POST code diagnostic LEDs found on the back edge of the server board. To assist in troubleshooting a system hang during the POST process, the diagnostic LEDs can be used to identify the last POST process to be executed.

Each POST code is represented by the eight amber diagnostic LEDs. The POST codes are divided into two nibbles, an upper nibble and a lower nibble. The upper nibble bits are represented by diagnostic LEDs #4, #5, #6, and #7. The lower nibble bits are represented by diagnostics LEDs #0, #1, #2, and #3. If the bit is set in the upper and lower nibbles, then the corresponding LED is lit. If the bit is clear, then the corresponding LED is off.

The diagnostic LED #7 is labeled as “MSB” (Most Significant Bit), and the diagnostic LED #0 is labeled as “LSB” (Least Significant Bit).

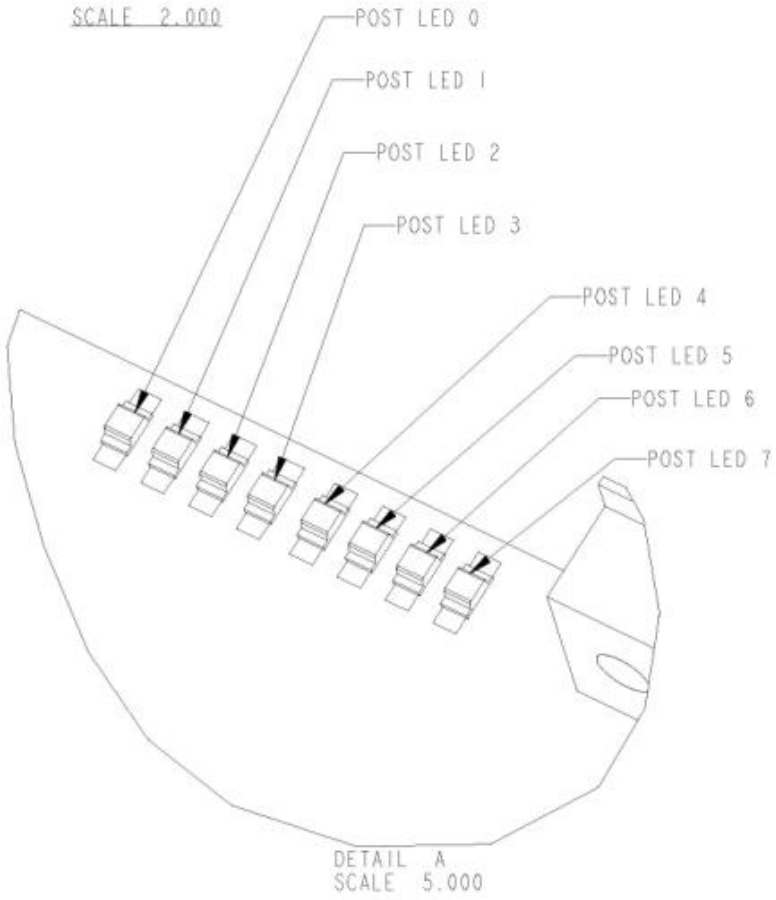


Figure 33. Diagnostic LED Placement Diagram

In the following example, the BIOS sends a value of ACh to the diagnostic LED decoder. The LEDs are decoded as follows:

Table 56. POST Progress Code LED Example

LEDs	Upper Nibble LEDs				Lower Nibble LEDs			
	MSB							LSB
	LED #7	LED #6	LED #5	LED #4	LED #3	LED #2	LED #1	LED #0
	8h	4h	2h	1h	8h	4h	2h	1h
Status	ON	OFF	ON	OFF	ON	ON	OFF	OFF
Results	1	0	1	0	1	1	0	0
	Ah				**Ch**			

Upper nibble bits = 1010b = Ah; Lower nibble bits = 1100b = Ch; the two are concatenated as ACh.

Table 57. Diagnostic LED POST Code Decoder

Checkpoint	Diagnostic LED Decoder 1 = On, 0=Off								Description
	Upper Nibble				Lower Nibble				
	MSB							LSB	
	8h	4h	2h	1h	8h	4h	2h	1h	
LED	#7	#6	#5	#4	#3	#2	#1	#0	
Host Processor									
0x10h	0	0	0	1	0	0	0	0	Power-on initialization of the host processor (bootstrap processor)
0x11h	0	0	0	1	0	0	0	1	Host processor cache initialization (including AP)
0x12h	0	0	0	1	0	0	1	0	Starting application processor initialization
0x13h	0	0	0	1	0	0	1	1	SMM initialization
0x14h	0	0	0	1	0	1	0	0	Selection of Processor with least features to be used as Boot Strap Processor
0x15h	0	0	0	1	0	1	0	1	Switch an AP processor to become the new Boot Strap Processor
Chipset									
0x21h	0	0	1	0	0	0	0	1	Initializing a chipset component
Memory									
0x22h	0	0	1	0	0	0	1	0	Reading configuration data from memory (SPD on FBDIMM)
0x23h	0	0	1	0	0	0	1	1	Detecting presence of memory
0x24h	0	0	1	0	0	1	0	0	Programming timing parameters in the memory controller
0x25h	0	0	1	0	0	1	0	1	Configuring memory parameters in the memory controller
0x26h	0	0	1	0	0	1	1	0	Optimizing memory controller settings
0x27h	0	0	1	0	0	1	1	1	Initializing memory, such as ECC init
0x28h	0	0	1	0	1	0	0	0	Testing memory
0xE4h	1	1	1	0	0	1	0	0	BIOS cannot communicate with DIMM (serial channel hardware failure)
0xE6h	1	1	1	0	0	1	1	0	DIMM(s) failed Memory iBIST or Memory Link Training failure
0xE8h	1	1	1	0	1	0	0	0	No memory available (system halted)
0xE9h	1	1	1	0	1	0	0	1	Unsupported or invalid DIMM configuration (system halted)
0xEAh	1	1	1	0	1	0	1	0	DIMM training sequence failed (system halted)
0xEBh	1	1	1	0	1	0	1	1	Memory test failed (system halted)
0xECh	1	1	1	0	1	1	0	0	Unsupported or invalid DIMM configuration (system halted)
0xEDh	1	1	1	0	1	1	0	1	Unsupported or invalid DIMM configuration (system halted)
0xEBh	1	1	1	0	1	0	1	1	DIMM with corrupted SPD data detected (system halted)

QuickPath Interconnect (QPI)									
0xA0h	1	0	1	0	0	0	0	0	QPI Initialization
0xA1h	1	0	1	0	0	0	0	1	QPI Initialization
0xA2h	1	0	1	0	0	0	1	0	QPI Initialization
0xA3h	1	0	1	0	0	0	1	1	QPI Initialization
0xA4h	1	0	1	0	0	1	0	0	QPI Initialization
0xA5h	1	0	1	0	0	1	0	1	QPI Initialization
0xA6h	1	0	1	0	0	1	1	0	QPI Initialization
0xA7h	1	0	1	0	0	1	1	1	QPI Initialization
0xA8h	1	0	1	0	1	0	0	0	QPI Initialization
0xA9h	1	0	1	0	1	0	0	1	QPI Initialization
0xAAh	1	0	1	0	1	0	1	0	QPI Initialization
0xABh	1	0	1	0	1	0	1	1	QPI Initialization
0xACh	1	0	1	0	1	1	0	0	QPI Initialization
0xADh	1	0	1	0	1	1	0	1	QPI Initialization
0xAEh	1	0	1	0	1	1	1	0	QPI Initialization
0xAFh	1	0	1	0	1	1	1	1	QPI Initialization
Integrated Memory Controller (IMC)									
0xB0h	1	0	1	1	0	0	0	0	Memory Initialization of Integrated Memory Controller
0xB1h	1	0	1	1	0	0	0	1	Memory Initialization of Integrated Memory Controller
0xB2h	1	0	1	1	0	0	1	0	Memory Initialization of Integrated Memory Controller
0xB3h	1	0	1	1	0	0	1	1	Memory Initialization of Integrated Memory Controller
0xB4h	1	0	1	1	0	1	0	0	Memory Initialization of Integrated Memory Controller
0xB5h	1	0	1	1	0	1	0	1	Memory Initialization of Integrated Memory Controller
0xB6h	1	0	1	1	0	1	1	0	Memory Initialization of Integrated Memory Controller
0xB7h	1	0	1	1	0	1	1	1	Memory Initialization of Integrated Memory Controller
0xB8h	1	0	1	1	1	0	0	0	Memory Initialization of Integrated Memory Controller
0xB9h	1	0	1	1	1	0	0	1	Memory Initialization of Integrated Memory Controller
0xBAh	1	0	1	1	1	0	1	0	Memory Initialization of Integrated Memory Controller
0xBBh	1	0	1	1	1	0	1	1	Memory Initialization of Integrated Memory Controller
0xBCh	1	0	1	1	1	1	0	0	Memory Initialization of Integrated Memory Controller
0xBDh	1	0	1	1	1	1	0	1	Memory Initialization of Integrated Memory Controller
0xBEh	1	0	1	1	1	1	1	0	Memory Initialization of Integrated Memory Controller
0xBFh	1	0	1	1	1	1	1	1	Memory Initialization of Integrated Memory Controller
PCI Bus									
0x50h	0	1	0	1	0	0	0	0	Enumerating PCI buses
0x51h	0	1	0	1	0	0	0	1	Allocating resources to PCI buses
0x52h	0	1	0	1	0	0	1	0	Hot Plug PCI controller initialization
0x53h	0	1	0	1	0	0	1	1	Reserved for PCI bus
0x54h	0	1	0	1	0	1	0	0	Reserved for PCI bus
0x55h	0	1	0	1	0	1	0	1	Reserved for PCI bus

USB									
0x56h	0	1	0	1	0	1	1	0	Initializing USB host controllers
0x57h	0	1	0	1	0	1	1	1	Detecting USB devices
0x58h	0	1	0	1	1	0	0	0	Resetting USB bus
0x59h	0	1	0	1	1	0	0	1	Reserved for USB devices
ATA/ATAPI/SATA									
0x5Ah	0	1	0	1	1	0	1	0	Resetting SATA bus and all devices
0x5Bh	0	1	0	1	1	0	1	1	Detecting the presence of ATA device
0x5Ch	0	1	0	1	1	1	0	0	Enable SMART if supported by ATA device
0x5Dh	0	1	0	1	1	1	0	1	Reserved for ATA
SMBUS									
0x5Eh	0	1	0	1	1	1	1	0	Resetting SMBUS
0x5Fh	0	1	0	1	1	1	1	1	Reserved for SMBUS
I/O Controller Hub									
0x61h	0	1	1	0	0	0	0	1	Initializing I/O Controller Hub
Super I/O									
0x63h	0	1	1	0	0	0	1	1	Initializing Super I/O
Local Console									
0x70h	0	1	1	1	0	0	0	0	Resetting the video controller (VGA)
0x71h	0	1	1	1	0	0	0	1	Disabling the video controller (VGA)
0x72h	0	1	1	1	0	0	1	0	Enabling the video controller (VGA)
0x73h	0	1	1	1	0	0	1	1	Reserved for video controller (VGA)
Remote Console									
0x78h	0	1	1	1	1	0	0	0	Resetting the console controller
0x79h	0	1	1	1	1	0	0	1	Disabling the console controller
0x7Ah	0	1	1	1	1	0	1	0	Enabling the console controller
0x7Bh	0	1	1	1	1	0	1	1	Reserved for console controller
Keyboard (only USB)									
0x90h	1	0	0	1	0	0	0	0	Resetting the keyboard
0x91h	1	0	0	1	0	0	0	1	Disabling the keyboard
0x92h	1	0	0	1	0	0	1	0	Detecting the presence of the keyboard
0x93h	1	0	0	1	0	0	1	1	Enabling the keyboard
0x94h	1	0	0	1	0	1	0	0	Clearing keyboard input buffer
0x96h	1	0	0	1	0	1	1	0	Reserved for keyboard
Mouse (only USB)									
0x98h	1	0	0	1	0	0	1	0	Resetting the mouse
0x99h	1	0	0	1	0	0	1	1	Detecting the mouse
0x9Ah	1	0	0	1	0	1	1	0	Detecting the presence of mouse
0x9Bh	1	0	0	1	0	1	1	1	Enabling the mouse
0x9Ch	1	0	0	1	0	0	1	0	Reserved for mouse
Serial Port									
0xA8h	1	0	1	0	1	0	0	0	Resetting the serial port
0xA9h	1	0	1	0	1	0	0	1	Disabling the serial port
0xAAh	1	0	1	0	1	0	1	0	Detecting the presence of the serial port
0xABh	1	0	1	0	1	0	1	1	Clearing serial port buffer
0xACh	1	0	1	0	1	1	0	0	Enabling serial port
0xADh	1	0	1	0	1	1	0	1	Reserved for serial port

Fixed Media									
0xB0h	1	0	1	1	0	0	0	0	Resetting fixed media device
0xB1h	1	0	1	1	0	0	0	1	Disabling fixed media device
0xB2h	1	0	1	1	0	0	1	0	Detecting presence of a fixed media device (SATA hard drive detection, and so forth)
0xB3h	1	0	1	1	0	0	1	1	Enabling / configuring a fixed media device
0xB4h	1	0	1	1	0	1	0	0	Reserved for fixed media
Removable Media									
0xB8h	1	0	1	1	1	0	0	0	Resetting removable media device
0xB9h	1	0	1	1	1	0	0	1	Disabling removable media device
0xBAh	1	0	1	1	1	0	1	0	Detecting presence of a removable media device (SATA CDROM detection, and so forth)
0xBCh	1	0	1	1	1	1	0	0	Enabling / configuring a removable media device
0xBDh	1	0	1	1	1	1	0	1	Reserved for removable media device
Boot Device Selection (BDS)									
0xD0	1	1	0	1	0	0	0	0	Entered the Boot Device Selection phase (BDS)
0xD1	1	1	0	1	0	0	0	1	Return to last good boot device
0xD2	1	1	0	1	0	0	1	0	Setup boot device selection policy
0xD3	1	1	0	1	0	0	1	1	Connect boot device controller
0xD4	1	1	0	1	0	1	0	0	Attempt flash update boot mode
0xD5	1	1	0	1	0	1	0	1	Transfer control to EFI boot
0xD6	1	1	0	1	0	1	1	0	Trying to boot device selection
0xDF	1	1	0	1	1	1	1	1	Reserved for boot device selection
Pre-EFI Initialization (PEI) Core									
0xE0h	1	1	1	0	0	0	0	0	Entered Pre-EFI Initialization phase (PEI)
0xE1h	1	1	1	0	0	0	0	1	Started dispatching early initialization modules (PEIM)
0xE2h	1	1	1	0	0	0	1	0	Initial memory found, configured, and installed correctly
0xE3h	1	1	1	0	0	0	1	1	Transfer control to the DXE Core
PEI Modules									
0xF0h	1	1	1	1	0	0	0	0	Install PEIM for Platform Status Codes
0xF1h	1	1	1	1	0	0	0	1	Detecting Platform Type
0xF2h	1	1	1	1	0	0	1	0	Early Platform Initialization
0xF3h	1	1	1	1	0	0	1	1	PEI Modules initialized
Driver eXecution Environment (DXE) Core									
0xE4h	1	1	1	0	0	1	0	0	Entered EFI driver execution phase (DXE)
0xE5h	1	1	1	0	0	1	0	1	Started dispatching drivers
0xE6h	1	1	1	0	0	1	1	0	Started connecting drivers
DXE Drivers									
0xE7h	1	1	1	0	1	1	0	1	Waiting for user input
0xE8h	1	1	1	0	1	0	0	0	Checking password
0xE9h	1	1	1	0	1	0	0	1	Entering BIOS setup
0xEAh	1	1	1	0	1	1	0	0	Flash Update
0xEBh	1	1	1	0	1	1	0	1	Legacy Option ROM initialization
0xECh	1	1	1	0	1	0	0	0	DXE Drivers initialized
0xEDh	1	1	1	0	1	0	0	1	Transfer control to Boot Device Selection (BDS)
0xEEh	1	1	1	0	1	1	0	0	Calling Int 19. One beep unless silent boot is enabled.
0xEFh	1	1	1	0	1	1	0	1	Unrecoverable boot failure

Pre-EFI Initialization Module (PEIM) / Recovery									
0x30h	0	0	1	1	0	0	0	0	Crisis recovery initiated because of a user request
0x31h	0	0	1	1	0	0	0	1	Crisis recovery initiated by software (corrupt flash)
0x34h	0	0	1	1	0	1	0	0	Loading crisis recovery capsule
0x35h	0	0	1	1	0	1	0	1	Handing off control to the crisis recovery capsule
0x36h	0	0	1	1	0	1	1	0	Begin crisis recovery
0x3Eh	0	0	1	1	1	1	1	0	No crisis recovery capsule detected
0x3Fh	0	0	1	1	1	1	1	1	Crisis recovery capsule failed integrity check of capsule descriptors

Appendix B: Video POST Code Errors

Whenever possible, the BIOS outputs the current boot progress codes on the video screen. Progress codes are 32-bit quantities plus optional data. The 32-bit numbers include class, subclass, and operation information. The class and subclass fields point to the type of hardware being initialized. The operation field represents the specific initialization activity. Based on the data bit availability to display progress codes, a progress code can be customized to fit the data width. The higher the data bit, the higher the granularity of information that can be sent on the progress port. The progress codes may be reported by the system BIOS or option ROMs.

The Response section in the following table is divided into three types:

- **No Pause:** The message is displayed on the local Vidoe screen during POSTor in the Error Manager. The system continues booting with a degraded state. The user may want to replace the erroneous unit. The setup POST error Pause setting does not have any effect with this error.
- **Pause:** The message is displayed on the Error Manager screen, and an error is logged to the SEL. The setup POST error Pause setting determines whether the system pauses to the Error Manager for this type of error, where the user can take immediate corrective action or choose to continue booting.
- **Halt:** The message is displayed on the Error Manager screen, an error is logged to the SEL, and the system cannot boot unless the error is resolved. The user needs to replace the faulty part and restart the system. The setup POST error Pause setting does not have any effect with this error.

Table 58. POST Error Messages and Handling

Error Code	Error Message	Response
0012	CMOS date / time not set	Major
0048	Password check failed	Major
0108	Keyboard component encountered a locked error.	Minor
0109	Keyboard component encountered a stuck key error.	Minor
0113	Fixed Media The SAS RAID firmware can not run properly. The user should attempt to reflash the firmware.	Major
0140	PCI component encountered a PERR error.	Major
0141	PCI resource conflict	Major
0146	PCI out of resources error	Major
0192	Processor 0x cache size mismatch detected.	Fatal
0193	Processor 0x stepping mismatch.	Minor
0194	Processor 0x family mismatch detected.	Fatal
0195	Processor 0x Intel(R) QPI speed mismatch.	Major
0196	Processor 0x model mismatch.	Fatal
0197	Processor 0x speeds mismatched.	Fatal
0198	Processor 0x family is not supported.	Fatal
019F	Processor and chipset stepping configuration is unsupported.	Major
5220	CMOS/NVRAM Configuration Cleared	Major
5221	Passwords cleared by jumper	Major
5224	Password clear Jumper is Set.	Major

Error Code	Error Message	Response
8160	Processor 01 unable to apply microcode update	Major
8161	Processor 02 unable to apply microcode update	Major
8180	Processor 0x microcode update not found.	Minor
8190	Watchdog timer failed on last boot	Major
8198	OS boot watchdog timer failure.	Major
8300	Baseboard management controller failed self-test	Major
84F2	Baseboard management controller failed to respond	Major
84F3	Baseboard management controller in update mode	Major
84F4	Sensor data record empty	Major
84FF	System event log full	Minor
8500	Memory component could not be configured in the selected RAS mode.	Major
8501	DIMM Population Error.	Major
8502	CLTT Configuration Failure Error.	Major
8520	DIMM_A1 failed Self Test (BIST).	Major
8521	DIMM_A2 failed Self Test (BIST).	Major
8522	DIMM_B1 failed Self Test (BIST).	Major
8523	DIMM_B2 failed Self Test (BIST).	Major
8524	DIMM_C1 failed Self Test (BIST).	Major
8525	DIMM_C2 failed Self Test (BIST).	Major
8526	DIMM_D1 failed Self Test (BIST).	Major
8527	DIMM_D2 failed Self Test (BIST).	Major
8528	DIMM_E1 failed Self Test (BIST).	Major
8529	DIMM_E2 failed Self Test (BIST).	Major
852A	DIMM_F1 failed Self Test (BIST).	Major
852B	DIMM_F2 failed Self Test (BIST).	Major
8540	DIMM_A1 Disabled.	Major
8541	DIMM_A2 Disabled.	Major
8542	DIMM_B1 Disabled.	Major
8543	DIMM_B2 Disabled.	Major
8544	DIMM_C1 Disabled.	Major
8545	DIMM_C2 Disabled.	Major
8546	DIMM_D1 Disabled.	Major
8547	DIMM_D2 Disabled.	Major
8548	DIMM_E1 Disabled.	Major
8549	DIMM_E2 Disabled.	Major
854A	DIMM_F1 Disabled.	Major
854B	DIMM_F2 Disabled.	Major
8560	DIMM_A1 Component encountered a Serial Presence Detection (SPD) fail error.	Major
8561	DIMM_A2 Component encountered a Serial Presence Detection (SPD) fail error.	Major
8562	DIMM_B1 Component encountered a Serial Presence Detection (SPD) fail error.	Major
8563	DIMM_B2 Component encountered a Serial Presence Detection (SPD) fail error.	Major
8564	DIMM_C1 Component encountered a Serial Presence Detection (SPD) fail error.	Major
8565	DIMM_C2 Component encountered a Serial Presence Detection (SPD) fail error.	Major
8566	DIMM_D1 Component encountered a Serial Presence Detection (SPD) fail error.	Major
8567	DIMM_D2 Component encountered a Serial Presence Detection (SPD) fail error.	Major

Error Code	Error Message	Response
8568	DIMM_E1 Component encountered a Serial Presence Detection (SPD) fail error.	Major
8569	DIMM_E2 Component encountered a Serial Presence Detection (SPD) fail error.	Major
856A	DIMM_F1 Component encountered a Serial Presence Detection (SPD) fail error.	Major
856B	DIMM_F2 Component encountered a Serial Presence Detection (SPD) fail error.	Major
85A0	DIMM_A1 Uncorrectable ECC error encountered.	Major
85A1	DIMM_A2 Uncorrectable ECC error encountered.	Major
85A2	DIMM_B1 Uncorrectable ECC error encountered.	Major
85A3	DIMM_B2 Uncorrectable ECC error encountered.	Major
85A4	DIMM_C1 Uncorrectable ECC error encountered.	Major
85A5	DIMM_C2 Uncorrectable ECC error encountered.	Major
85A6	DIMM_D1 Uncorrectable ECC error encountered.	Major
85A7	DIMM_D2 Uncorrectable ECC error encountered.	Major
85A8	DIMM_E1 Uncorrectable ECC error encountered.	Major
85A9	DIMM_E2 Uncorrectable ECC error encountered.	Major
85AA	DIMM_F1 Uncorrectable ECC error encountered.	Major
85AB	DIMM_F2 Uncorrectable ECC error encountered.	Major
8604	Chipset Reclaim of non critical variables complete.	Minor
9000	Unspecified processor component has encountered a non specific error.	Major
9223	Keyboard component was not detected.	Minor
9226	Keyboard component encountered a controller error.	Minor
9243	Mouse component was not detected.	Minor
9246	Mouse component encountered a controller error.	Minor
9266	Local Console component encountered a controller error.	Minor
9268	Local Console component encountered an output error.	Minor
9269	Local Console component encountered a resource conflict error.	Minor
9286	Remote Console component encountered a controller error.	Minor
9287	Remote Console component encountered an input error.	Minor
9288	Remote Console component encountered an output error.	Minor
92A3	Serial port component was not detected	Major
92A9	Serial port component encountered a resource conflict error	Major
92C6	Serial Port controller error	Minor
92C7	Serial Port component encountered an input error.	Minor
92C8	Serial Port component encountered an output error.	Minor
94C6	LPC component encountered a controller error.	Minor
94C9	LPC component encountered a resource conflict error.	Major
9506	ATA/ATPI component encountered a controller error.	Minor
95A6	PCI component encountered a controller error.	Minor
95A7	PCI component encountered a read error.	Minor
95A8	PCI component encountered a write error.	Minor
9609	Unspecified software component encountered a start error.	Minor
9641	PEI Core component encountered a load error.	Minor
9667	PEI module component encountered a illegal software state error.	Fatal
9687	DXE core component encountered a illegal software state error.	Fatal
96A7	DXE boot services driver component encountered a illegal software state error.	Fatal
96AB	DXE boot services driver component encountered invalid configuration.	Minor

Error Code	Error Message	Response
96E7	SMM driver component encountered a illegal software state error.	Fatal
0xA000	TPM device not detected.	Minor
0xA001	TPM device missing or not responding.	Minor
0xA002	TPM device failure.	Minor
0xA003	TPM device failed self test.	Minor
0xA022	Processor component encountered a mismatch error.	Major
0xA027	Processor component encountered a low voltage error.	Minor
0xA028	Processor component encountered a high voltage error.	Minor
0xA421	PCI component encountered a SERR error.	Fatal
0xA500	ATA/ATPI ATA bus SMART not supported.	Minor
0xA501	ATA/ATPI ATA SMART is disabled.	Minor
0xA5A0	PCI Express component encountered a PERR error.	Minor
0xA5A1	PCI Express component encountered a SERR error.	Fatal
0xA5A4	PCI Express IBIST error.	Major
0xA6A0	DXE boot services driver Not enough memory available to shadow a legacy option ROM.	Minor
0xB6A3	DXE boot services driver Unrecognized.	Major

Glossary

This appendix contains important terms used in the preceding chapters. For ease of use, numeric entries are listed first (for example, “82460GX”) with alpha entries following (for example, “AGP 4x”). Acronyms are then entered in their respective place, with non-acronyms following.

Table 59: Glossary

Term	Definition
ACPI	Advanced Configuration and Power Interface
AP	Application Processor
APIC	Advanced Programmable Interrupt Control
ARP	Address Resolution Protocal
ASIC	Application Specific Integrated Circuit
BIOS	Basic Input / Output System
BIST	Built-In Self Test
BMC	Baseboard Management Controller
Bridge	Circuitry connecting one computer bus to another, allowing an agent on one to access the other
BSP	Bootstrap Processor
Byte	8-bit quantity.
CATERR	On a catastrophic hardware event the core signals CATERR to the uncore. The core enters a halted state that can only be exited by a reset.
CBC	Chassis Bridge Controller (A microcontroller connected to one or more other CBCs, together they bridge the IPMB buses of multiple chassis.)
CEK	Common Enabling Kit
CHAP	Challenge Handshake Authentication Protocol
CMOS	In terms of this specification, this describes the PC-AT compatible region of battery-backed 128 bytes of memory, which normally resides on the server board.
DCMI	Data Center Management Interface
DHCP	Dynamic Host Configuration Protocal
DPC	Direct Platform Control
EEPROM	Electrically Erasable Programmable Read-Only Memory
EHCI	Enhanced Host Controller Interface
EMP	Emergency Management Port
EPS	External Product Specification
FBD	Fully Buffered DIMM
F MB	Flexible Mother Board
FRB	Fault Resilient Booting
FRU	Field Replaceable Unit
FSB	Front Side Bus
GB	1024 MB
GPIO	General Purpose I/O
GTL	Gunning Transceiver Logic
GPA	Guest Physical Address
HSC	Hot-Swap Controller

Term	Definition
HPA	Host Physical Address
Hz	Hertz (1 cycle / second)
I2C	Inter-Integrated Circuit Bus
IA	Intel® Architecture
IBF	Input Buffer
ICH	I/O Controller Hub
IC MB	Intelligent Chassis Management Bus
IFB	I/O and Firmware Bridge
ILM	Independent Loading Mechanism
IMC	Integrated Memory Controller
INTR	Interrupt
IP	Internet Protocol
IPMB	Intelligent Platform Management Bus
IPMI	Intelligent Platform Management Interface
IR	Infrared
ITP	In-Target Probe
KB	1024 bytes
KCS	Keyboard Controller Style
LAN	Local Area Network
LCD	Liquid Crystal Display
LED	Light Emitting Diode
LPC	Low Pin Count
LUN	Logical Unit Number
MAC	Media Access Control
MB	1024KB
ME	Management Engine
MD2	Message Digest 2 – Hashing Algorithm
MD5	Message Digest 5 – Hashing Algorithm – Higher Security
ms	Milliseconds
MTTR	Memory Type Range Register
Mux	Multiplexor
NIC	Network Interface Controller
NMI	Nonmaskable Interrupt
OBF	Output Buffer
OEM	Original Equipment Manufacturer
Ohm	Unit of electrical resistance
PECI	Platform Environment Control Interface
PEF	Platform Event Filtering
PEP	Platform Event Paging
PIA	Platform Information Area (This feature configures the firmware for the platform hardware)
PLD	Programmable Logic Device
PMI	Platform Management Interrupt
POST	Power-On Self Test
PSMI	Power Supply Management Interface
PWM	Pulse-Width Modulation

Term	Definition
QPI	QuickPath Interconnect
RAM	Random Access Memory
RASUM	Reliability, Availability, Serviceability, Usability, and Manageability
RISC	Reduced Instruction Set Computing
ROM	Read Only Memory
RTC	Real-Time Clock (Component of ICH peripheral chip on the server board)
RMM3	Remote Management Module 3
SDR	Sensor Data Record
SECC	Single Edge Connector Cartridge
SEEPROM	Serial Electrically Erasable Programmable Read-Only Memory
SEL	System Event Log
SIO	Server Input / Output
SMBUS	System Management BUS
SMI	Server Management Interrupt (SMI is the highest priority nonmaskable interrupt)
SMM	Server Management Mode
SMS	Server Management Software
SNMP	Simple Network Management Protocol
TBD	To Be Determined
TDP	Thermal Design Power
TIM	Thermal Interface Material
UART	Universal Asynchronous Receiver/Transmitter
UDP	User Datagram Protocol
UHCI	Universal Host Controller Interface
URS	Unified Retention System
UTC	Universal time coordinate
UUID	Universally Unique Identifier
VID	Voltage Identification
VRD	Voltage Regulator Down
VT	Virtualization Technology
Word	16-bit quantity
ZIF	Zero Insertion Force

Reference Documents

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- SATA 2.6: http://www.sata-io.org/
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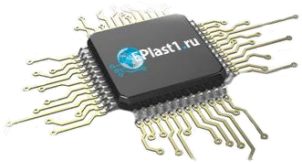
- Система менеджмента качества сертифицирована по Международному стандарту ISO 9001;
- Лицензия ФСБ на осуществление работ с использованием сведений, составляющих государственную тайну;
- Поставка специализированных компонентов (Xilinx, Altera, Analog Devices, Intersil, Interpoint, Microsemi, Aeroflex, Peregrine, Syfer, Eurofarad, Texas Instrument, Miteq, Cobham, E2V, MA-COM, Hittite, Mini-Circuits,General Dynamics и др.);

Помимо этого, одним из направлений компании «ЭлектроПласт» является направление «Источники питания». Мы предлагаем Вам помощь Конструкторского отдела:

- Подбор оптимального решения, техническое обоснование при выборе компонента;
- Подбор аналогов;
- Консультации по применению компонента;
- Поставка образцов и прототипов;
- Техническая поддержка проекта;
- Защита от снятия компонента с производства.



Как с нами связаться

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